

STN Columbus

* * * * * Welcome to STN International * * * * *

| | | | |
|------|----|--------|---|
| NEWS | 1 | | Web Page for STN Seminar Schedule - N. America |
| NEWS | 2 | DEC 01 | ChemPort single article sales feature unavailable |
| NEWS | 3 | FEB 02 | Simultaneous left and right truncation (SLART) added for CERAB, COMPUAB, ELCOM, and SOLIDSTATE |
| NEWS | 4 | FEB 02 | GENBANK enhanced with SET PLURALS and SET SPELLING |
| NEWS | 5 | FEB 06 | Patent sequence location (PSL) data added to USGENE |
| NEWS | 6 | FEB 10 | COMPENDEX reloaded and enhanced |
| NEWS | 7 | FEB 11 | WTEXTILES reloaded and enhanced |
| NEWS | 8 | FEB 19 | New patent-examiner citations in 300,000 CA/CAPLUS patent records provide insights into related prior art |
| NEWS | 9 | FEB 19 | Increase the precision of your patent queries -- use terms from the IPC Thesaurus, Version 2009.01 |
| NEWS | 10 | FEB 23 | Several formats for image display and print options discontinued in USPATFULL and USPAT2 |
| NEWS | 11 | FEB 23 | MEDLINE now offers more precise author group fields and 2009 MeSH terms |
| NEWS | 12 | FEB 23 | TOXCENTER updates mirror those of MEDLINE - more precise author group fields and 2009 MeSH terms |
| NEWS | 13 | FEB 23 | Three million new patent records blast AEROSPACE into STN patent clusters |
| NEWS | 14 | FEB 25 | USGENE enhanced with patent family and legal status display data from INPADOCDB |
| NEWS | 15 | MAR 06 | INPADOCDB and INPAFAMDB enhanced with new display formats |
| NEWS | 16 | MAR 11 | EPFULL backfile enhanced with additional full-text applications and grants |
| NEWS | 17 | MAR 11 | ESBIOBASE reloaded and enhanced |
| NEWS | 18 | MAR 20 | CAS databases on STN enhanced with new super role for nanomaterial substances |
| NEWS | 19 | MAR 23 | CA/CAPLUS enhanced with more than 250,000 patent equivalents from China |
| NEWS | 20 | MAR 30 | IMSPATENTS reloaded and enhanced |
| NEWS | 21 | APR 03 | CAS coverage of exemplified prophetic substances enhanced |
| NEWS | 22 | APR 07 | STN is raising the limits on saved answers |
| NEWS | 23 | APR 24 | CA/CAPLUS now has more comprehensive patent assignee information |
| NEWS | 24 | APR 26 | USPATFULL and USPAT2 enhanced with patent assignment/reassignment information |
| NEWS | 25 | APR 28 | CAS patent authority coverage expanded |
| NEWS | 26 | APR 28 | ENCOMPLIT/ENCOMPLIT2 search fields enhanced |
| NEWS | 27 | APR 28 | Limits doubled for structure searching in CAS REGISTRY |
| NEWS | 28 | MAY 08 | STN Express, Version 8.4, now available |
| NEWS | 29 | MAY 11 | STN on the Web enhanced |
| NEWS | 30 | MAY 11 | BEILSTEIN substance information now available on STN Easy |
| NEWS | 31 | MAY 14 | DGENE, PCTGEN and USGENE enhanced with increased limits for exact sequence match searches and introduction of free HIT display format |
| NEWS | 32 | MAY 15 | INPADOCDB and INPAFAMDB enhanced with Chinese legal status data |

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NEWS EXPRESS JUNE 27 08 CURRENT WINDOWS VERSION IS V8.3,
AND CURRENT DISCOVER FILE IS DATED 06 APRIL 2009.

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* * * * * STN Columbus * * * * *

FILE 'HOME' ENTERED AT 00:05:08 ON 23 MAY 2009

=> file caplus

| COST IN U.S. DOLLARS | SINCE FILE ENTRY | TOTAL SESSION |
|----------------------|------------------|---------------|
| FULL ESTIMATED COST | 0.22 | 0.22 |

FILE 'CAPLUS' ENTERED AT 00:05:27 ON 23 MAY 2009

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FILE COVERS 1907 - 23 May 2009 VOL 150 ISS 22

FILE LAST UPDATED: 21 May 2009 (20090521/ED)

REVISED CLASS FIELDS (/NCL) LAST RELOADED: Feb 2009

USPTO MANUAL OF CLASSIFICATIONS THESAURUS ISSUE DATE: Feb 2009

Caplus now includes complete International Patent Classification (IPC) reclassification data for the third quarter of 2008.

CAS Information Use Policies apply and are available at:

<http://www.cas.org/legal/infopolicy.html>

This file contains CAS Registry Numbers for easy and accurate

=> s 22811-02-5 or 10220-46-9 or 2917-26-2 or 2885-00-9 or thioglycolate or mercaptoacetate or hexadecanethiol or hexadecylthiol or mercaptan or octadecanethiol or octadecylthiol

REGISTRY INITIATED

Substance data SEARCH and crossover from CAS REGISTRY in progress...

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Use DISPLAY HITSTR (or FHITSTR) to directly view retrieved structures.

L2 2011 L1

REGISTRY INITIATED

Substance data SEARCH and crossover from CAS REGISTRY in progress...
Use DISPLAY HITSTR (or FHITSTR) to directly view retrieved structures.

L4 1621 L3

REGISTRY INITIATED

Substance data SEARCH and crossover from CAS REGISTRY in progress...
Use DISPLAY HITSTR (or FHITSTR) to directly view retrieved structures.

L6 50 L5

REGISTRY INITIATED

Substance data SEARCH and crossover from CAS REGISTRY in progress...
Use DISPLAY HITSTR (or FHITSTR) to directly view retrieved structures.

L8 6 L7

5570 THIOGLYCOLATE
2218 MERCAPTOACETATE
1405 HEXADECANETHIOL
41 HEXADECYLTHIOL
22248 MERCAPTAN
1668 OCTADECANETHIOL
91 OCTADECYLTHIOL

L9 32684 L8 OR L6 OR L4 OR L2 OR THIOGLYCOLATE OR MERCAPTOACETATE OR HEXA
DECANETHIOL OR HEXADECYLTHIOL OR MERCAPTAN OR OCTADECANETHIOL
OR OCTADECYLTHIOL

STN Columbus

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      1054666 NON
      307432 IONIC
      9398 NON-IONIC
          (NON(W) IONIC)
      134021 ANIONIC
      13094 ZWITTERIONIC
      275066 SURFACTANT#
L10      84695 (NONIONIC OR NON-IONIC OR ANIONIC OR ZWITTERIONIC) AND SURFACTAN
          T#
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=> d his
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L2      2011 S L1
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L4      1621 S L3
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L5      1 S 10220-46-9/RN
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L10     84695 S (NONIONIC OR NON-IONIC OR ANIONIC OR ZWITTERIONIC) AND SURFAC
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=> s 19 and 110
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L11      319 L9 AND L10
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      4009269 TREAT#####
          2447 METAL TREAT#####
              (METAL(W) TREAT#####)
      4009717 TREAT#####
      1928101 METAL
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4324 TREAT##### METAL

(TREAT#####(W)METAL)

L12 6680 METAL TREAT##### OR TREAT##### METAL

=> l11 and l12

L11 IS NOT A RECOGNIZED COMMAND

The previous command name entered was not recognized by the system.

For a list of commands available to you in the current file, enter

"HELP COMMANDS" at an arrow prompt (=>).

=> s l11 and l12

L13 1 L11 AND L12

=> d

L13 ANSWER 1 OF 1 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2003:798402 CAPLUS

DN 139:311931

TI Metal coating of hair fibers for cosmetics

IN Vic, Gabin; Livoreil, Aude; Giroud, Franck

PA L'oreal, Fr.

SO Fr. Demande, 18 pp.

CODEN: FRXXBL

DT Patent

LA French

FAN.CNT 1

| | PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
|------|--|------|----------|-----------------|----------|
| | ----- | --- | ----- | ----- | ----- |
| PI | FR 2838050 | A1 | 20031010 | FR 2002-4352 | 20020408 |
| | FR 2838050 | B1 | 20060714 | | |
| | CN 1449737 | A | 20031022 | CN 2003-108449 | 20030331 |
| | CN 1213719 | C | 20050810 | | |
| | BR 2003000873 | A | 20040817 | BR 2003-873 | 20030403 |
| | EP 1352630 | A2 | 20031015 | EP 2003-290860 | 20030407 |
| | EP 1352630 | A3 | 20040324 | | |
| | EP 1352630 | B1 | 20060301 | | |
| | R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO, MK, CY, AL, TR, BG, CZ, EE, HU, SK | | | | |
| | US 20030223944 | A1 | 20031204 | US 2003-407911 | 20030407 |
| | JP 2003300840 | A | 20031021 | JP 2003-104420 | 20030408 |
| | JP 3759120 | B2 | 20060322 | | |
| PRAI | FR 2002-4352 | A | 20020408 | | |
| | US 2002-372455P | P | 20020416 | | |

RE.CNT 10 THERE ARE 10 CITED REFERENCES AVAILABLE FOR THIS RECORD
ALL CITATIONS AVAILABLE IN THE RE FORMAT

=> d all

L13 ANSWER 1 OF 1 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2003:798402 CAPLUS

DN 139:311931

ED Entered STN: 12 Oct 2003

TI Metal coating of hair fibers for cosmetics

IN Vic, Gabin; Livoreil, Aude; Giroud, Franck

PA L'oreal, Fr.

SO Fr. Demande, 18 pp.

CODEN: FRXXBL

STN Columbus

DT Patent
 LA French
 IC ICM A61K007-075
 CC 62-3 (Essential Oils and Cosmetics)
 FAN.CNT 1

| | PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
|------|---|------|----------|-----------------|----------|
| PI | FR 2838050 | A1 | 20031010 | FR 2002-4352 | 20020408 |
| | FR 2838050 | B1 | 20060714 | | |
| | CN 1449737 | A | 20031022 | CN 2003-108449 | 20030331 |
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| | JP 3759120 | B2 | 20060322 | | |
| PRAI | FR 2002-4352 | A | 20020408 | | |
| | US 2002-372455P | P | 20020416 | | |

CLASS

| PATENT NO. | CLASS | PATENT FAMILY CLASSIFICATION CODES |
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| FR 2838050 | ICM | A61K007-075 |
| | IPCI | A61K0007-075 [ICM, 7] |
| | IPCR | A61K0008-00 [I,C*]; A61K0008-00 [I,A]; A61K0008-18 [I,C*]; A61K0008-18 [I,A]; A61K0008-19 [I,C*]; A61K0008-19 [I,A]; A61K0008-20 [I,A]; A61K0008-23 [I,A]; A61K0008-24 [I,A]; A61K0008-26 [I,A]; A61K0008-27 [I,A]; A61K0008-30 [I,C*]; A61K0008-31 [I,A]; A61K0008-34 [I,A]; A61K0008-35 [I,A]; A61K0008-37 [I,A]; A61K0008-46 [I,A]; A61K0008-64 [I,A]; A61K0008-72 [I,C*]; A61K0008-73 [I,A]; A61K0008-89 [I,A]; A61K0008-891 [I,A]; A61Q0001-02 [I,C*]; A61Q0001-02 [I,A]; A61Q0005-00 [I,C*]; A61Q0005-00 [I,A]; A61Q0005-10 [I,C*]; A61Q0005-10 [I,A]; A61Q0005-12 [I,C*]; A61Q0005-12 [I,A] |
| | ECLA | A61Q005/12; A61K008/19; A61K008/27; A61K008/46; A61Q005/00; A61Q005/10 |
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A61Q005/00; A61Q005/10
EP 1352630 IPCI A61K0008-19 [I,C]; A61K0008-30 [I,C]; A61Q0005-00
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A61Q005/00; A61Q005/10
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IPCR A61K0008-19 [I,C*]; A61K0008-19 [I,A]; A61K0008-30
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NCL 424/070.100; 510/119.000
ECLA A61K008/19; A61K008/46; A61Q005/12
JP 2003300840 IPCI A61K0008-00 [I,A]; A61Q0005-00 [I,A]; A61K0008-18
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IPCR A61K0008-00 [I,C*]; A61K0008-00 [I,A]; A61K0008-18
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ECLA A61Q005/12; A61K008/19; A61K008/27; A61K008/46;
A61Q005/00; A61Q005/10
AB The invention relates to a treatment process which confers cosmetic
properties on hair fibers. The process consists of treating the fibers
with a metal salt in the presence of a reducing agent, directly on the
fiber to form the corresponding free metal. Thus, a lock of hair after
being shampooed, was dried and an aq. soln. of AgNO3 was applied onto the
hair. After the addn. of NaBH4, the natural pigmented hair was dark, with
metallic brilliance reflected on it.
ST metal salt hair cosmetic
IT Alcohols, biological studies
RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);

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PYP (Physical process); BIOL (Biological study); PROC (Process); USES (Uses)

(C1-4; **metal treatment** of hair fibers for cosmetics)

IT Alkanes, biological studies

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process); PYP (Physical process); BIOL (Biological study); PROC (Process); USES (Uses)

(C5-10; **metal treatment** of hair fibers for cosmetics)

IT Polyelectrolytes

Surfactants

(amphoteric; **metal treatment** of hair fibers for cosmetics)

IT Fats and Glyceridic oils, biological studies

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process); PYP (Physical process); BIOL (Biological study); PROC (Process); USES (Uses)

(animal; **metal treatment** of hair fibers for cosmetics)

IT **Surfactants**

(**anionic**; **metal treatment** of hair fibers for cosmetics)

IT Polyelectrolytes

Surfactants

(cationic; **metal treatment** of hair fibers for cosmetics)

IT Cosmetics

(emollients; **metal treatment** of hair fibers for cosmetics)

IT Sulfates, reactions

RL: RCT (Reactant); RACT (Reactant or reagent)
(hydrogen; **metal treatment** of hair fibers for cosmetics)

IT Antifoaming agents

Antiperspirants

Cosmetics

Hair

Hair preparations

Perfumes

Pigments, nonbiological

Preservatives

Reducing agents

Shampoos

Sunscreens

Thickening agents

(**metal treatment** of hair fibers for cosmetics)

IT Alkaline earth salts

Bromates

Carbonates, biological studies

Disulfides

Halides

Nitrates, biological studies

Paraffin oils

Phosphates, biological studies

Polymers, biological studies

Polysiloxanes, biological studies

Proteins

Rare earth salts

Sulfates, biological studies

Thioethers

Thiosulfates

Transition metal salts

Vitamins

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);
PYP (Physical process); BIOL (Biological study); PROC (Process); USES
(Uses)

(**metal treatment** of hair fibers for cosmetics)

IT Bisulfites

Enzymes, reactions

Sulfites

Thiols, reactions

Thioredoxins

RL: RCT (Reactant); RACT (Reactant or reagent)

(**metal treatment** of hair fibers for cosmetics)

IT Cosmetics

(moisturizers; **metal treatment** of hair fibers for
cosmetics)

IT **Surfactants**

(**nonionic**; **metal treatment** of hair fibers
for cosmetics)

IT Peroxysulfates

RL: RCT (Reactant); RACT (Reactant or reagent)

(peroxymonosulfates; **metal treatment** of hair fibers
for cosmetics)

IT Alcohols, biological studies

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);
PYP (Physical process); BIOL (Biological study); PROC (Process); USES
(Uses)

(polyhydric; **metal treatment** of hair fibers for
cosmetics)

IT Sulfonic acids, biological studies

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);
PYP (Physical process); BIOL (Biological study); PROC (Process); USES
(Uses)

(salts; **metal treatment** of hair fibers for
cosmetics)

IT Sulfinic acids

Thiols, reactions

RL: RCT (Reactant); RACT (Reactant or reagent)

(salts; **metal treatment** of hair fibers for
cosmetics)

IT Salts, reactions

RL: RCT (Reactant); RACT (Reactant or reagent)

(thiol; **metal treatment** of hair fibers for
cosmetics)

IT Lactones

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);
PYP (Physical process); BIOL (Biological study); PROC (Process); USES
(Uses)

(thiolactones; **metal treatment** of hair fibers for
cosmetics)

IT Fats and Glyceridic oils, biological studies

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);
PYP (Physical process); BIOL (Biological study); PROC (Process); USES
(Uses)

(vegetable; **metal treatment** of hair fibers for
cosmetics)

IT 64-17-5, Ethanol, biological studies 67-63-0, Isopropanol, biological
studies 67-64-1, Acetone, biological studies 78-93-3, Methyl ethyl

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ketone, biological studies 79-20-9, Methyl acetate 110-71-4
 123-86-4, Butyl acetate 141-78-6, EtOAc, biological studies
 7429-90-5D, Aluminum, salts 7439-89-6D, Iron, salts 7439-98-7D,
 Molybdenum, salts 7440-02-0D, Nickel, salts 7440-05-3D, Palladium,
 salts 7440-06-4D, Platinum, salts 7440-22-4D, Silver, salts
 7440-31-5D, Tin, salts 7440-32-6D, Titanium, salts 7440-33-7D,
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 7440-57-5D, Gold, salts 7440-66-6D, Zinc, salts 7440-74-6D, Indium,
 salts 7758-89-6, Cuprous chloride 7761-88-8, Silver nitrate,
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 bromate 7783-90-6, Silver chloride, biological studies 7783-96-2,
 Silver iodide 7785-23-1, Silver bromide 7787-70-4, Cuprous bromide
 10025-98-6, Dipotassium palladium tetrachloride 10294-26-5, Silver
 sulfate 10294-28-7, Gold tribromide 16903-35-8 16923-58-3, Disodium
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 Diethoxyethane

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);
 PYP (Physical process); BIOL (Biological study); PROC (Process); USES
 (Uses)

(**metal treatment** of hair fibers for cosmetics)

IT 50-81-7, Ascorbic acid, reactions 53-57-6, NaDPH 58-68-4, NaDH
 68-11-1, Thioglycolic acid, reactions 77-92-9D, Citric acid, salts
 106-51-4, 2,5-Cyclohexadiene-1,4-dione, reactions 123-31-9,
 Hydroquinone, reactions 280-64-8, 9-BBN 1758-73-2, Formamidinesulfinic
 acid **2885-00-9**, 1-Octadecanethiol 3483-12-3,
 Dithiothreitol 6838-83-1, Diisoamylborane 7772-98-7 7775-14-6
 7803-51-2, Phosphine 13762-51-1 14451-43-5 16853-85-3 16940-66-2
 17836-88-3 25895-60-7, Sodium cyanoborohydride 37318-49-3, Protein
 disulfide isomerase 56553-60-7 131760-67-3 145626-87-5

RL: RCT (Reactant); RACT (Reactant or reagent)

(**metal treatment** of hair fibers for cosmetics)

RE.CNT 10 THERE ARE 10 CITED REFERENCES AVAILABLE FOR THIS RECORD

RE

- (1) Anon; PATENT ABSTRACTS OF JAPAN 1991, V015(243), PC-0842
- (2) Anon; PATENT ABSTRACTS OF JAPAN 1992, V016(509), PC-0997
- (3) Dong Sung Pharmaceuticals Co L; EP 1243249 A 2002 CAPLUS
- (4) Grollier, J; US 4971596 A 1990 CAPLUS
- (5) Kanebo Ltd; JP 03077806 A 1991 CAPLUS
- (6) Katsumi, M; JP 04187625 A 1992 CAPLUS
- (7) Lapidus, H; US 4195972 A 1980
- (8) Richez, H; US 1055355 A 1913 CAPLUS
- (9) Wella Ag; DE 2806603 A 1979 CAPLUS
- (10) Wella Ag; DE 29621557 U 1997

=> s silver or ag

379544 SILVER

342362 AG

L14 522045 SILVER OR AG

=> d his

(FILE 'HOME' ENTERED AT 00:05:08 ON 23 MAY 2009)

FILE 'CAPLUS' ENTERED AT 00:05:27 ON 23 MAY 2009

S 22811-02-5/REG# OR 10220-46-9/REG# OR 2917-26-2/REG# OR 28

FILE 'REGISTRY' ENTERED AT 00:12:43 ON 23 MAY 2009

L1 1 S 2885-00-9/RN

STN Columbus

L2 FILE 'CAPLUS' ENTERED AT 00:12:44 ON 23 MAY 2009
2011 S L1

L3 FILE 'REGISTRY' ENTERED AT 00:12:44 ON 23 MAY 2009
1 S 2917-26-2/RN

L4 FILE 'CAPLUS' ENTERED AT 00:12:45 ON 23 MAY 2009
1621 S L3

L5 FILE 'REGISTRY' ENTERED AT 00:12:45 ON 23 MAY 2009
1 S 10220-46-9/RN

L6 FILE 'CAPLUS' ENTERED AT 00:12:45 ON 23 MAY 2009
50 S L5

L7 FILE 'REGISTRY' ENTERED AT 00:12:46 ON 23 MAY 2009
1 S 22811-02-5/RN

L8 FILE 'CAPLUS' ENTERED AT 00:12:46 ON 23 MAY 2009
6 S L7

L9 32684 S L8 OR L6 OR L4 OR L2 OR THIOGLYCOLATE OR MERCAPTOACETATE OR H

L10 84695 S (NONIONIC OR NON-IONIC OR ANIONIC OR ZWITTERIONIC) AND SURFAC

L11 319 S L9 AND L10

L12 6680 S METAL TREAT##### OR TREAT##### METAL

L13 1 S L11 AND L12

L14 522045 S SILVER OR AG

=> l11 and l14

L11 IS NOT A RECOGNIZED COMMAND

The previous command name entered was not recognized by the system.

For a list of commands available to you in the current file, enter

"HELP COMMANDS" at an arrow prompt (=>).

=> s l11 and l14

L15 12 L11 AND L14

=> d 1-12 all

L15 ANSWER 1 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2008:1046144 CAPLUS

DN 149:312963

ED Entered STN: 29 Aug 2008

TI Preparation of conductive supported noble metal nanoparticle catalysts

IN Stucky, Galen D.; Zheng, Nanfeng

PA The Regents of the University of California, USA

SO U.S. Pat. Appl. Publ., 35pp.

CODEN: USXXCO

DT Patent

LA English

INCL 428403000; 216055000; 428402000; 264005000; 264007000; 502100000;

502300000; 502159000; 502355000; 502350000

CC 56-4 (Nonferrous Metals and Alloys)

Section cross-reference(s): 57, 67

FAN.CNT 1

| | PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
|------|-----------------|------|----------|-----------------|----------|
| | ----- | ---- | ----- | ----- | ----- |
| PI | US 20080206562 | A1 | 20080828 | US 2008-13436 | 20080112 |
| PRAI | US 2007-884668P | P | 20070112 | | |

CLASS

STN Columbus

| PATENT NO. | CLASS | PATENT FAMILY CLASSIFICATION CODES |
|----------------|--|---|
| US 20080206562 | INCL | 428403000; 216055000; 428402000; 264005000; 264007000; 502100000; 502300000; 502159000; 502355000; 502350000 |
| | IPCI | B32B0015-02 [I,A]; C23F0001-00 [I,A]; B29B0009-00 [I,A]; B29B0009-16 [I,A]; B01J0031-06 [I,A]; B01J0021-04 [I,A]; B01J0021-08 [I,A]; B01J0023-34 [I,A]; B01J0023-16 [I,C*]; B01J0029-00 [I,A]; B01J0021-18 [I,A]; B01J0021-00 [I,C*]; B01J0027-06 [I,A]; B01J0023-42 [I,A]; B01J0023-44 [I,A]; B01J0023-50 [I,A]; B01J0023-52 [I,A]; B01J0023-48 [I,C*]; B01J0027-02 [I,A]; B01J0027-24 [I,A]; B01J0031-02 [I,A]; B01J0023-755 [I,A]; B01J0031-26 [I,A] |
| | NCL | 428/403.000; 216/055.000; 216/083.000; 264/005.000; 264/007.000; 428/402.000; 502/080.000; 502/087.000; 502/100.000; 502/150.000; 502/159.000; 502/167.000; 502/168.000; 502/171.000; 502/180.000; 502/181.000; 502/200.000; 502/216.000; 502/232.000; 502/300.000; 502/325.000; 502/337.000; 502/339.000; 502/340.000; 502/344.000; 502/345.000; 502/347.000; 502/349.000; 502/350.000; 502/355.000 |
| AB | The prepn. of elec.-conductive noble metal nanoparticle catalysts on catalyst supports such as alumina, silica, titania, clays, zeolites, or carbon black, is described. | |
| ST | gold silver palladium nanocatalyst support sol gel micelle ceramic | |
| IT | Solvents (aprotic; prepn. of conductive supported noble metal nanoparticle catalysts) | |
| IT | Polyethers, uses RL: MOA (Modifier or additive use); USES (Uses) (arom., alkyl-, surfactants ; prepn. of conductive supported noble metal nanoparticle catalysts) | |
| IT | Thiols, uses RL: MOA (Modifier or additive use); USES (Uses) (caps on catalyst nanoparticles; prepn. of conductive supported noble metal nanoparticle catalysts) | |
| IT | Bentonite, processes Carbon black, processes Clays, processes Diatomite Silica gel, processes Zeolites (synthetic), processes RL: PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses) (catalyst supports; prepn. of conductive supported noble metal nanoparticle catalysts) | |
| IT | Nanoparticles (catalysts; prepn. of conductive supported noble metal nanoparticle catalysts) | |
| IT | Alcohols, uses RL: MOA (Modifier or additive use); USES (Uses) (ethoxylated, surfactants ; prepn. of conductive supported noble metal nanoparticle catalysts) | |
| IT | Hydrocarbons, processes RL: PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses) (fluoro, catalyst supports; prepn. of conductive supported noble metal nanoparticle catalysts) | |
| IT | Surfactants | |

STN Columbus

- (in coatings; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Electroluminescent devices
- Molecular electronic devices
- Optoelectronics
- Secondary batteries
- Semiconductor devices
- Sensors
- Solar cells
 - (nanocatalysts for; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Photolysis catalysts
 - (nanocatalysts; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Catalysts
- Semiconductor materials
 - (nanoparticles; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT **Surfactants**
 - (**nonionic**; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Silsesquioxanes
 - RL: RGT (Reagent); RACT (Reactant or reagent)
 - (octyl- and hexyl-; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Dyes
 - (org.-, functional mol.; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Calcination
- Catalyst supports
- Etching
- Reducing agents
 - (prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 7440-44-0, Carbon, processes
 - RL: PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)
 - (activated, catalyst supports; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 64-17-5, Ethanol, uses
 - RL: NUU (Other use, unclassified); USES (Uses)
 - (buffer soln.; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 49543-63-7, 4-(tert-Butyl)benzyl **mercaptan**
 - RL: MOA (Modifier or additive use); USES (Uses)
 - (cap on nanoparticles; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 1322-36-7, Dodecanethiol
 - RL: MOA (Modifier or additive use); USES (Uses)
 - (caps on catalyst nanoparticles; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 7440-02-0P, Nickel, preparation 7440-05-3P, Palladium, preparation
 7440-06-4P, Platinum, preparation 7440-22-4P, **Silver**,
 preparation 7440-50-8P, Copper, preparation 7440-57-5P, Gold,
 preparation 12006-51-8P, AuCu
 RL: CAT (Catalyst use); SPN (Synthetic preparation); PREP (Preparation);
 USES (Uses)
 - (catalyst nanoparticles; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 1309-48-4, Magnesium oxide (MgO), processes 1314-23-4, Zirconia,
 processes 1344-28-1, Aluminum oxide (Al₂O₃), processes 7631-86-9,

STN Columbus

Silica, processes 7782-42-5, Graphite, processes 13463-67-7, Titania, processes

RL: PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)

(catalyst supports; prepn. of conductive supported noble metal nanoparticle catalysts)

IT 1306-38-3, Cerium oxide (CeO₂), uses 1313-13-9, Manganese oxide (MnO₂), uses 1313-96-8, Niobium oxide (Nb₂O₅)

RL: MOA (Modifier or additive use); USES (Uses)

(coatings on colloidal silica; prepn. of conductive supported noble metal nanoparticle catalysts)

IT 12638-19-6P

RL: CAT (Catalyst use); SPN (Synthetic preparation); PREP (Preparation); USES (Uses)

(nanoparticles; prepn. of conductive supported noble metal nanoparticle catalysts)

IT 2966-50-9, **Silver** trifluoroacetate 14024-17-0, Iron acetyl acetate 14024-61-4 14024-64-7 16902-59-3 17927-72-9 19443-16-4 19443-17-5 23894-00-0 23894-03-3 24772-51-8 27858-32-8, Titanium diisopropoxide bis(ethyl acetoacetate) 62905-51-5 65574-21-2 65583-10-0 66197-44-2 82269-80-5 93918-06-0, Aluminum sec-butoxide bis(ethyl acetoacetate) 98719-26-7 140190-96-1 144665-26-9 204522-78-1 299957-41-8 380240-62-0 1050499-47-2 1050499-48-3 1050499-49-4 1050499-50-7 1050499-51-8 1050499-52-9 1050499-53-0 1050499-54-1

RL: RCT (Reactant); RACT (Reactant or reagent)

(precursors; prepn. of conductive supported noble metal nanoparticle catalysts)

IT 1313-99-1, Nickel oxide, uses 1345-25-1, Ferrous oxide, uses 11104-61-3, Cobalt oxide

RL: MOA (Modifier or additive use); USES (Uses)

(prepn. of conductive supported noble metal nanoparticle catalysts)

IT 78-07-9, Ethyltriethoxysilane 78-10-4, Tetraethoxysilane 681-84-5, Tetramethoxysilane 682-01-9, Tetrapropoxysilane 1185-55-3, Methyltrimethoxysilane 1336-21-6, Ammonium hydroxide ((NH₄)(OH)) 2031-67-6, Methyltriethoxysilane 4766-57-8, Tetrabutoxysilane 30232-12-3 192082-40-9, Mercaptoundecanoic acid

RL: RGT (Reagent); RACT (Reactant or reagent)

(prepn. of conductive supported noble metal nanoparticle catalysts)

IT 1722-26-5, Triethylamine-borane 4856-95-5 7337-45-3, tert-Butylamine-borane 13774-81-7, Ammonia-borane

RL: RGT (Reagent); RACT (Reactant or reagent)

(reducing agents; prepn. of conductive supported noble metal nanoparticle catalysts)

IT 67-66-3, Chloroform, uses 71-43-2, Benzene, uses 75-09-2, Dichloromethane, uses 108-88-3, Toluene, uses 110-54-3, Hexane, uses 110-82-7, Cyclohexane, uses

RL: NUU (Other use, unclassified); USES (Uses)

(solvent; prepn. of conductive supported noble metal nanoparticle catalysts)

IT 14243-64-2

RL: PEP (Physical, engineering or chemical process); PROC (Process)

(substrates; prepn. of conductive supported noble metal nanoparticle catalysts)

IT 577-11-7, Sodium bis(2-ethylhexyl) sulfosuccinate 9002-89-5, Polyvinyl alcohol 9002-92-0, Brij 30 9004-98-2, Brij 97 9036-19-5, (Octylphenoxy)polyethoxyethanol 12441-09-7D, Sorbitan, ester derivs. 27251-32-7

RL: MOA (Modifier or additive use); USES (Uses)

(**surfactants**; prepn. of conductive supported noble metal

nanoparticle catalysts)

L15 ANSWER 2 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2007:415891 CAPLUS

DN 146:463862

ED Entered STN: 16 Apr 2007

TI Discoloration prevention of metals using organic ultra-thin films and methods therefor

IN Liang, Chenghao; Yang, Changjiang; Huang, Naibao

PA Dalian Maritime University, Peop. Rep. China

SO Faming Zhuanli Shenqing Gongkai Shuomingshu, 10pp.

CODEN: CNXXEV

DT Patent

LA Chinese

CC 42-10 (Coatings, Inks, and Related Products)

Section cross-reference(s): 46, 56

FAN.CNT 1

| | PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
|------|------------------|------|----------|------------------|----------|
| | ----- | --- | ----- | ----- | ----- |
| PI | CN 1943882 | A | 20070411 | CN 2006-10134093 | 20061026 |
| PRAI | CN 2006-10134093 | | 20061026 | | |

CLASS

| PATENT NO. | CLASS | PATENT FAMILY CLASSIFICATION CODES |
|------------|-------|---|
| ----- | ----- | ----- |
| CN 1943882 | IPCI | B05D0007-14 [I,A]; B05D0007-24 [I,A]; B05D0003-10 [I,A]; C23C0022-05 [I,A]; C07C0321-04 [I,A]; C07C0321-00 [I,C*] |
| | IPCR | B05D0007-14 [I,C]; B05D0007-14 [I,A] |

OS MARPAT 146:463862

AB Film-forming solns. contain 0.001-1 mol/L alkyl thiols and 0.001-1 mol/L **surfactants**. Thus, a coating soln. on **Ag** contained stearyl thiol 15, polyethylene glycol nonylphenyl ether 7, hexadecyltrimethylammonium bromide 2, Pluronic 64 7 g/L.

ST metal discoloration prevention coating **surfactant** thiol; **silver** discoloration prevention coating **surfactant** thiol

IT **Surfactants**

(**anionic**; coating materials contg. thiols and **surfactants** for discoloration prevention of metals)

IT **Surfactants**

(**cationic**; coating materials contg. thiols and **surfactants** for discoloration prevention of metals)

IT Discoloration prevention

(coating materials contg. thiols and **surfactants** for discoloration prevention of metals)

IT Quaternary ammonium compounds, uses

Thiols, uses

RL: TEM (Technical or engineered material use); USES (Uses)

(coating materials contg. thiols and **surfactants** for discoloration prevention of metals)

IT Coating materials

(discoloration-resistant; coating materials contg. thiols and **surfactants** for discoloration prevention of metals)

IT 691397-13-4, Pluronic L 64

RL: TEM (Technical or engineered material use); USES (Uses)

(Pluronic L 64; coating materials contg. thiols and **surfactants** for discoloration prevention of metals)

IT 57-09-0, Hexadecyltrimethylammonium bromide **2885-00-9**, Stearylmercaptan 7440-22-4, **Silver**, uses 9016-45-9, Polyethylene glycol nonylphenyl ether

STN Columbus

RL: TEM (Technical or engineered material use); USES (Uses)
 (coating materials contg. thiols and **surfactants** for
 discoloration prevention of metals)

L15 ANSWER 3 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2007:150387 CAPLUS

DN 146:236227

ED Entered STN: 09 Feb 2007

TI Conductive adhesive composition comprising pressure sensitive adhesive and electrolyte

IN Menon, Vinod P.; Kumar, Kanta; Nelson, Carl T.; Rizzardi, Don A.

PA 3M Innovative Properties Company, USA

SO U.S. Pat. Appl. Publ., 20pp.

CODEN: USXXCO

DT Patent

LA English

INCL 600391000; 600392000; 252500000

CC 63-7 (Pharmaceuticals)

FAN.CNT 1

| | PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
|------|---|------|----------|------------------|----------|
| PI | US 20070032719 | A1 | 20070208 | US 2005-197216 | 20050804 |
| | AU 2006278717 | A1 | 20070215 | AU 2006-278717 | 20060801 |
| | CA 2617273 | A1 | 20070215 | CA 2006-2617273 | 20060801 |
| | WO 2007019115 | A1 | 20070215 | WO 2006-US29794 | 20060801 |
| | W: | | | | |
| | AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, | | | | |
| | CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, | | | | |
| | GE, GH, GM, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, | | | | |
| | KR, KZ, LA, LC, LK, LR, LS, LT, LU, LV, LY, MA, MD, MG, MK, MN, | | | | |
| | MW, MX, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RS, RU, | | | | |
| | SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, | | | | |
| | US, UZ, VC, VN, ZA, ZM, ZW | | | | |
| | RW: | | | | |
| | AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, | | | | |
| | IS, IT, LT, LU, LV, MC, NL, PL, PT, RO, SE, SI, SK, TR, BF, BJ, | | | | |
| | CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG, BW, GH, | | | | |
| | GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW, AM, AZ, BY, | | | | |
| | KG, KZ, MD, RU, TJ, TM | | | | |
| EP | 1917318 | A1 | 20080507 | EP 2006-789019 | 20060801 |
| | R: | | | | |
| | AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, | | | | |
| | IS, IT, LI, LT, LU, LV, MC, NL, PL, PT, RO, SE, SI, SK, TR | | | | |
| JP | 2009503235 | T | 20090129 | JP 2008-525088 | 20060801 |
| MX | 2008001425 | A | 20080416 | MX 2008-1425 | 20080129 |
| KR | 2008040689 | A | 20080508 | KR 2008-702725 | 20080201 |
| CN | 101238189 | A | 20080806 | CN 2006-80028822 | 20080204 |
| IN | 2008CN00571 | A | 20081128 | IN 2008-CN571 | 20080204 |
| PRAI | US 2005-197216 | A | 20050804 | | |
| | WO 2006-US29794 | W | 20060801 | | |

CLASS

| PATENT NO. | CLASS | PATENT FAMILY CLASSIFICATION CODES |
|----------------|-------|--|
| US 20070032719 | INCL | 600391000; 600392000; 252500000 |
| | IPCI | A61B0005-04 [I,A]; H01B0001-12 [I,A]; H01B0001-00 [I,A] |
| | IPCR | A61B0005-04 [I,C]; A61B0005-04 [I,A]; H01B0001-00 [I,C]; H01B0001-00 [I,A]; H01B0001-12 [I,C]; H01B0001-12 [I,A] |
| | NCL | 600/391.000; 252/500.000; 600/392.000 |
| | ECLA | C09J009/02; A61B005/0408F; A61N001/04; C09J133/04+B4; C09J133/06+B2; H01B001/20; K61B; M08L; M08L; M08L |
| AU 2006278717 | IPCI | C09J0009-00 [I,C]; C09J0009-02 [I,A] |

STN Columbus

| | | |
|----------------|-------|---|
| | IPCR | C09J0009-00 [I,C]; C09J0009-02 [I,A] |
| | ECLA | C09J009/02; A61B005/0408F; A61N001/04; C09J133/04+B4; C09J133/06+B2; H01B001/20; K61B; M08L; M08L; M08L |
| CA 2617273 | IPCI | A61B0005-0408 [I,A]; A61B0018-14 [I,A]; A61K0050-00 [I,A]; A61N0001-04 [I,A]; C09J0009-02 [I,A]; C09J0009-00 [I,C*]; C09J0011-06 [I,A]; C09J0011-02 [I,C*] |
| | IPCR | C09J0009-00 [I,C]; C09J0009-02 [I,A]; A61B0005-0408 [I,C]; A61B0005-0408 [I,A]; A61B0018-14 [I,C]; A61B0018-14 [I,A]; A61K0050-00 [I,C]; A61K0050-00 [I,A]; A61N0001-04 [I,C]; A61N0001-04 [I,A]; C09J0011-02 [I,C]; C09J0011-06 [I,A] |
| WO 2007019115 | IPCI | C09J0009-02 [I,A]; C09J0009-00 [I,C*] |
| | IPCR | C09J0009-00 [I,C]; C09J0009-02 [I,A] |
| | ECLA | C09J009/02; A61B005/0408F; A61N001/04; C09J133/04+B4; C09J133/06+B2; H01B001/20; K61B; M08L; M08L; M08L |
| EP 1917318 | IPCI | C09J0009-02 [I,A]; C09J0009-00 [I,C*] |
| | IPCR | C09J0009-00 [I,C]; C09J0009-02 [I,A] |
| JP 2009503235 | IPCI | C09J0201-00 [I,A]; C09J0009-02 [I,A]; C09J0009-00 [I,C*]; C09J0004-02 [I,A]; A61L0024-00 [I,A]; A61N0001-04 [I,A] |
| | FTERM | 4C053/BB04; 4C053/BB06; 4C053/BB07; 4C053/BB23; 4C053/BB35; 4C053/BB36; 4C081/AA10; 4C081/AA12; 4C081/AC04; 4C081/BB03; 4C081/BB04; 4C081/CA061; 4C081/CA071; 4C081/CA081; 4C081/CA101; 4C081/CA16; 4C081/CA181; 4C081/CA211; 4C081/CA281; 4C081/CE07; 4C081/CE09; 4C081/CE10; 4C081/DA02; 4C081/DA12; 4C081/DB07; 4C081/DC03; 4C081/DC04; 4J040/FA041; 4J040/FA081; 4J040/FA091; 4J040/FA101; 4J040/FA131; 4J040/FA141; 4J040/FA161; 4J040/FA281; 4J040/FA291; 4J040/HB04; 4J040/HB10; 4J040/HB11; 4J040/HB14; 4J040/HC01; 4J040/HD02; 4J040/HD18; 4J040/HD23; 4J040/JA03; 4J040/JB09; 4J040/KA12; 4J040/KA13; 4J040/KA32; 4J040/KA38; 4J040/KA39; 4J040/MA14; 4J040/NA02 |
| MX 2008001425 | IPCI | C09J0009-02 [I,A]; C09J0009-00 [I,C*] |
| KR 2008040689 | IPCI | C09J0009-02 [I,A]; C09J0009-00 [I,C*] |
| CN 101238189 | IPCI | C09J0009-02 [I,A]; C09J0009-00 [I,C*] |
| IN 2008CN00571 | IPCI | C09J0009-02 [ICM,7]; C09J0009-00 [ICM,7,C*] |

OS MARPAT 146:236227

AB A conductive adhesive compn. is provided and articles that include the adhesive compn. as a component thereof. The conductive adhesive compn. comprises: (a) pressure sensitive adhesive; (b) electrolyte comprising water sol. or water dispersible org. chloride; and (c) humectant. In some embodiments, the conductive adhesive compn. is a bicontinuous compn. comprising an aq. phase and an oil phase, and the bicontinuous compn. may be derived from a polymerizable microemulsion compn., the microemulsion compn. comprising: an aq. phase comprising one or more hydrophilic monomers or oligomers and/or one or more amphiphilic monomers or oligomers in water, the water-sol. or water-dispersible org. chloride, **surfactant** and humectant; and an oil phase comprising one or more hydrophobic monomers or oligomers. Biomedical articles such as biomedical electrodes, may incorporate the foregoing adhesive as a component. For example, adhesive precursor comprised of acrylic acid 15 g, 2-hydroxyethyl methacrylate 20 g, tetrakis(hydroxymethyl)phosphonium chloride 11 g, 1,3-butylene glycol 25 g, glycerol 10 g, water 19 g, Irgacure 2959 0.55 g and polyethylene glycol diacrylate 0.15 g. The precursor was coated using a knife coater onto a release liner as substrate. The knife was set so that a 25 mil (0.64 mm) thick coating was obtained. Polymn. was induced in the coated microemulsion by exposure to UV radiation. A total dose of

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1800 mJ/cm² was applied over approx. 7 min, forming a conductive, bicontinuous adhesive. This conductive adhesive had an excellent adhesion to human skin.

- ST polymer acrylate electrolyte chloride conductive adhesive
- IT Polyurethanes, biological studies
 - RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)
 - (acrylates; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Electric conductors
 - (adhesive; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Fats and Glyceridic oils, biological studies
 - RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)
 - (almond, amidopropalkonium chloride; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT **Surfactants**
 - (anionic; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Fats and Glyceridic oils, biological studies
 - RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)
 - (avocado, amidopropalkonium chloride; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT **Surfactants**
 - (cationic; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Onium compounds
 - RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)
 - (chloride; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Quaternary ammonium compounds, biological studies
 - RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)
 - (chlorides; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Fatty acids, biological studies
 - RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)
 - (coco, trimethylammonium chloride; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Chain transfer agents
- Crosslinking agents
- Electrodes
- Electrolytes
- Human
- Humectants
- Hydrogels
- Surfactants**
 - (conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Alcohols, uses
 - Thiols, uses
 - RL: NUU (Other use, unclassified); USES (Uses)
 - (conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Acrylic polymers, biological studies
 - RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)
 - (conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Sulfonium compounds
 - RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)
 - (conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)

- IT Adhesives
(conductive; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Soybean oil
RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)
(dimethylammonium chloride; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT **Surfactants**
(**nonionic**; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Chlorides, biological studies
RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)
(org.; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Adhesives
(pressure-sensitive; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Fatty acids, biological studies
RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)
(tallow, bishydroxyethyl/dime quaternary ammonium compds.; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT 558-13-4, Carbon tetrabromide 25103-09-7, Isooctyl **thioglycolate**
, uses
RL: NUU (Other use, unclassified); USES (Uses)
(conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT 1070-70-8, 1,4-Butanediol diacrylate 1321-74-0, Divinylbenzene, reactions 10526-04-2, 1,8-Octanediol diacrylate 13048-33-4, 1,6-Hexanediol diacrylate
RL: RCT (Reactant); RACT (Reactant or reagent)
(conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT 56-34-8, Tetraethylammonium chloride 56-37-1, Benzyltriethylammonium chloride 56-81-5, Glycerin, biological studies 56-93-9, Benzyltrimethylammonium chloride 57-55-6, Propylene glycol, biological studies 67-48-1 77-99-6, Trimethylolpropane 88-12-0D, polymer 107-21-1, Ethylene glycol, biological studies 107-88-0, 1,3-Butanediol 110-63-4, 1,4-Butanediol, biological studies 112-00-5, Dodecyltrimethylammonium chloride 112-02-7, Hexadecyltrimethylammonium chloride 112-03-8, Octadecyltrimethylammonium chloride 124-64-1, Tetrakis(hydroxymethyl)phosphonium chloride 139-08-2, Tetradecyldimethylbenzylammonium chloride 593-81-7D, Trimethylammonium chloride, coco fatty acid derivs. 7173-51-5 9004-98-2, Brij 98 9042-76-6 17301-53-0, Behenyltrimethylammonium chloride 24567-53-1, Phosphonium chloride 25265-71-8, Dipropylene glycol 26570-48-9, Polyethylene oxide diacrylate 26597-36-4 32862-91-2, Oxonium chloride 60182-11-8, Polyethylene glycol acrylate 93507-51-8 106797-53-9, IRGACURE 2959 123776-56-7 145687-02-1, Pemulen TR 2 463965-14-2 923929-97-9 923929-99-1 924299-17-2, Hetoxol OL 35
RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)
(conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT 7783-90-6, **Silver** chloride, biological studies
RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)
(conductive ink soln.; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)

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DN 143:351549
 ED Entered STN: 05 Oct 2005
 TI Water-based sulfur-containing composition chemical mechanical polishing of nonferrous metals
 IN Johns, Peter Gamon; Harrison, Clare Elizabeth
 PA Middlesex Silver Co. Limited, UK
 SO Brit. UK Pat. Appl., 29 pp.
 CODEN: BAXXDU
 DT Patent
 LA English
 IC ICM C23F011-16
 ICS C23F011-00
 CC 57-7 (Ceramics)
 Section cross-reference(s): 56

FAN.CNT 1

| | PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
|------|---|------|----------|------------------|----------|
| PI | GB 2412666 | A | 20051005 | GB 2004-7163 | 20040330 |
| | GB 2412666 | B | 20081008 | | |
| | AU 2005229275 | A1 | 20051013 | AU 2005-229275 | 20050324 |
| | CA 2559989 | A1 | 20051013 | CA 2005-2559989 | 20050324 |
| | WO 2005095675 | A1 | 20051013 | WO 2005-GB50043 | 20050324 |
| | W: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW | | | | |
| | RW: BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW, AM, AZ, BY, KG, KZ, MD, RU, TJ, TM, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG | | | | |
| | EP 1730325 | A1 | 20061213 | EP 2005-718135 | 20050324 |
| | R: AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LI, LT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR | | | | |
| | CN 1946878 | A | 20070411 | CN 2005-80013434 | 20050324 |
| | JP 2007537354 | T | 20071220 | JP 2007-505641 | 20050324 |
| | IN 2006DN05356 | A | 20070713 | IN 2006-DN5356 | 20060915 |
| | MX 2006010964 | A | 20061116 | MX 2006-10964 | 20060925 |
| | US 20070277906 | A1 | 20071206 | US 2007-594477 | 20070702 |
| PRAI | GB 2004-7163 | A | 20040330 | | |
| | WO 2005-GB50043 | W | 20050324 | | |

CLASS

| PATENT NO. | CLASS | PATENT FAMILY CLASSIFICATION CODES |
|---------------|-------|---|
| GB 2412666 | ICM | C23F011-16 |
| | ICS | C23F011-00 |
| | IPCI | C23F0011-10 [I,C]; C23F0011-16 [I,A]; C23F0011-00 [I,C]; C23F0011-00 [I,A] |
| | IPCR | C09G0001-00 [I,C*]; C09G0001-02 [I,A]; C11D0003-00 [I,C*]; C11D0003-00 [I,A]; C11D0003-34 [I,C*]; C11D0003-34 [I,A]; C11D0011-00 [I,C*]; C11D0011-00 [I,A] |
| | ECLA | C23F011/16; C23F011/16B |
| AU 2005229275 | IPCI | C11D0003-00 [I,C*]; C09G0001-00 [I,C*]; C11D0003-34 [I,C*]; C11D0011-00 [I,C*]; C23F0011-10 [I,C*]; C11D0003-00 [I,A]; C09G0001-02 [I,A]; C11D0003-34 [I,A]; C11D0011-00 [I,A]; C23F0011-16 [I,A] |
| | IPCR | C11D0003-00 [I,C*]; C11D0003-00 [I,A]; C09G0001-00 |

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| | | |
|---------------|-------|---|
| | | [I,C*]; C09G0001-02 [I,A]; C11D0003-34 [I,C*]; C11D0003-34 [I,A]; C11D0011-00 [I,C*]; C11D0011-00 [I,A]; C23F0011-10 [I,C*]; C23F0011-16 [I,A] |
| CA 2559989 | ECLA | C23F011/16; C23F011/16B |
| | IPCI | C09G0001-02 [I,A]; C09G0001-00 [I,C*]; C11D0003-00 [I,A]; C11D0003-34 [I,A]; C11D0011-00 [I,A]; C23F0011-16 [I,A]; C23F0011-10 [I,C*] |
| | IPCR | C23F0011-10 [I,C]; C23F0011-16 [I,A]; C09G0001-00 [I,C]; C09G0001-02 [I,A]; C11D0003-00 [I,C]; C11D0003-00 [I,A]; C11D0003-34 [I,C]; C11D0003-34 [I,A]; C11D0011-00 [I,C]; C11D0011-00 [I,A] |
| WO 2005095675 | ECLA | C23F011/16; C23F011/16B |
| | IPCI | C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C*]; C11D0003-00 [ICS,7]; C11D0003-34 [ICS,7]; C11D0011-00 [ICS,7]; C09G0001-02 [ICS,7]; C09G0001-00 [ICS,7,C*] |
| | IPCR | C09G0001-00 [I,C*]; C09G0001-02 [I,A]; C11D0003-00 [I,C*]; C11D0003-00 [I,A]; C11D0003-34 [I,C*]; C11D0003-34 [I,A]; C11D0011-00 [I,C*]; C11D0011-00 [I,A]; C23F0011-10 [I,C*]; C23F0011-16 [I,A] |
| EP 1730325 | ECLA | C23F011/16; C23F011/16B |
| | IPCI | C23F0011-16 [I,A]; C23F0011-10 [I,C*]; C11D0003-00 [I,A]; C11D0003-34 [I,A]; C11D0011-00 [I,A]; C09G0001-02 [I,A]; C09G0001-00 [I,C*] |
| | IPCR | C23F0011-10 [I,C]; C23F0011-16 [I,A]; C09G0001-00 [I,C]; C09G0001-02 [I,A]; C11D0003-00 [I,C]; C11D0003-00 [I,A]; C11D0003-34 [I,C]; C11D0003-34 [I,A]; C11D0011-00 [I,C]; C11D0011-00 [I,A] |
| CN 1946878 | ECLA | C23F011/16; C23F011/16B |
| | IPCI | C23F0011-16 [I,A]; C23F0011-10 [I,C*]; C11D0003-00 [I,A]; C11D0003-34 [I,A]; C11D0011-00 [I,A]; C09G0001-02 [I,A]; C09G0001-00 [I,C*] |
| | IPCR | C23F0011-10 [I,C]; C23F0011-16 [I,A]; C09G0001-00 [I,C*]; C09G0001-02 [I,A]; C11D0003-00 [I,C*]; C11D0003-00 [I,A]; C11D0003-34 [I,C*]; C11D0003-34 [I,A]; C11D0011-00 [I,C*]; C11D0011-00 [I,A] |
| JP 2007537354 | ECLA | C23F011/16; C23F011/16B |
| | IPCI | C23C0022-58 [I,A]; C11D0003-34 [I,A]; C23C0022-68 [I,A]; C23C0022-05 [I,C*]; C11D0003-20 [I,A]; C11D0001-52 [I,A]; C11D0001-38 [I,C*]; C11D0001-72 [I,A]; C11D0001-79 [I,A]; C11D0001-755 [I,A]; C11D0001-75 [I,A]; C11D0001-722 [I,A]; C11D0001-14 [I,A]; C11D0001-02 [I,C*]; C11D0001-90 [I,A]; C11D0001-88 [I,C*]; C11D0003-04 [I,A]; C11D0001-68 [I,A]; C09K0003-14 [I,A] |
| | IPCR | C23C0022-05 [I,C]; C23C0022-58 [I,A]; C09G0001-00 [I,C*]; C09G0001-02 [I,A]; C09K0003-14 [I,C]; C09K0003-14 [I,A]; C11D0001-02 [I,C]; C11D0001-14 [I,A]; C11D0001-38 [I,C]; C11D0001-52 [I,A]; C11D0001-68 [I,C]; C11D0001-68 [I,A]; C11D0001-72 [I,C]; C11D0001-72 [I,A]; C11D0001-722 [I,C]; C11D0001-722 [I,A]; C11D0001-75 [I,C]; C11D0001-75 [I,A]; C11D0001-755 [I,C]; C11D0001-755 [I,A]; C11D0001-79 [I,C]; C11D0001-79 [I,A]; C11D0001-88 [I,C]; C11D0001-90 [I,A]; C11D0003-00 [I,C*]; C11D0003-00 [I,A]; C11D0003-04 [I,C]; C11D0003-04 [I,A]; C11D0003-20 [I,C]; C11D0003-20 [I,A]; C11D0003-34 [I,C]; C11D0003-34 [I,A]; C11D0011-00 [I,C*]; C11D0011-00 [I,A]; C23C0022-68 [I,A]; C23F0011-10 [I,C*]; C23F0011-16 [I,A] |
| | FTERM | 4H003/AB27; 4H003/AC02; 4H003/AC10; 4H003/AC13; |

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4H003/AD04; 4H003/BA12; 4H003/DA15; 4H003/EA12;
 4H003/EA19; 4H003/EB05; 4H003/EB18; 4H003/EB21;
 4H003/ED02; 4H003/FA05; 4K026/AA01; 4K026/AA06;
 4K026/CA15; 4K026/CA37; 4K026/DA02; 4K026/DA03
 IN 2006DN05356 IPCI C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C*]
 MX 2006010964 IPCI C09G0001-02 [ICM,7]; C09G0001-00 [ICM,7,C*];
 C11D0011-00 [ICS,7]; C11D0003-00 [ICS,7]; C11D0003-34
 [ICS,7]; C23F0011-16 [ICS,7]; C23F0011-10 [ICS,7,C*]
 US 20070277906 IPCI C23F0011-16 [I,A]; C23F0011-10 [I,C*]; C09G0001-02
 [I,A]; C09G0001-00 [I,C*]; C11D0011-00 [I,A];
 C11D0003-00 [I,A]; C11D0003-34 [I,A]
 NCL 148/022.000
 OS MARPAT 143:351549
 AB A compn. and assocd. method of manuf. of a water based compn. comprising a
 treatment agent selected from an alkanethiol, alkyl thioglycollate, and
 dialkyl sulfide or dialkyl disulfide. The compn. also includes at least
 one of an amphoteric, **non-ionic** or cationic **surfactant**, where the
 treatment agent is directly dissolved or dispersed the water contg. the
 amphoteric, **non-ionic** or cationic **surfactant**. The compn. is
 particularly useful for the treatment of **Ag**-Cu-Ge alloy, copper, brass,
 and nickel. A solid polishing medium can also be included in the compn.,
 for example, silica or pptd. chalk, alumina, or silica.
 ST chalk alumina silica alkanethiol thioglycollate chem mech polishing copper
 IT Thiols, processes
 RL: CPS (Chemical process); PEP (Physical, engineering or chemical
 process); TEM (Technical or engineered material use); PROC (Process); USES
 (Uses)
 (alkanethiol; water-based sulfur-contg. compn. chem. mech. polishing of
 metals)
 IT Disulfides
 RL: CPS (Chemical process); PEP (Physical, engineering or chemical
 process); TEM (Technical or engineered material use); PROC (Process); USES
 (Uses)
 (alkyl; water-based sulfur-contg. compn. chem. mech. polishing of
 metals)
 IT Chalk
 Diatomite
 RL: TEM (Technical or engineered material use); USES (Uses)
 (as abrasive; water-based sulfur-contg. compn. chem. mech. polishing of
 metals)
 IT **Surfactants**
 (cationic; water-based sulfur-contg. compn. chem. mech. polishing of
 metals)
 IT Polishing
 (chem.-mech.; water-based sulfur-contg. compn. chem. mech. polishing of
 metals)
 IT Polishing materials
 (paste; water-based sulfur-contg. compn. chem. mech. polishing of
 metals)
 IT Thioethers
 RL: CPS (Chemical process); PEP (Physical, engineering or chemical
 process); TEM (Technical or engineered material use); PROC (Process); USES
 (Uses)
 (water-based sulfur-contg. compn. chem. mech. polishing of metals)
 IT 1344-28-1, Alumina, uses
 RL: TEM (Technical or engineered material use); USES (Uses)
 (abrasive; water-based sulfur-contg. compn. chem. mech. polishing of
 metals)
 IT 9004-82-4, Sodium laureth sulfate
 RL: MOA (Modifier or additive use); USES (Uses)

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(**anionic surfactant**; water-based sulfur-contg. compn. chem. mech. polishing of metals)

IT 7631-86-9, Silica, uses
 RL: TEM (Technical or engineered material use); USES (Uses)
 (as abrasive; water-based sulfur-contg. compn. chem. mech. polishing of metals)

IT 36574-66-0D, N-coco acyl derivs.
 RL: MOA (Modifier or additive use); USES (Uses)
 (cocamidopropyl betaine, **surfactant**; water-based sulfur-contg. compn. chem. mech. polishing of metals)

IT 7440-02-0, Nickel, processes 7440-50-8, Copper, processes 11144-43-7
 12597-71-6, Brass, processes 74969-69-0
 RL: PEP (Physical, engineering or chemical process); PYP (Physical process); PROC (Process)
 (polished substrate; water-based sulfur-contg. compn. chem. mech. polishing of metals)

IT 62-56-6, Thiourea, uses **2885-00-9**, Octadecyl **mercaptan**
 RL: TEM (Technical or engineered material use); USES (Uses)
 (polishing compn. component; water-based sulfur-contg. compn. chem. mech. polishing of metals)

IT **2917-26-2**, Hexadecyl **mercaptan**
 RL: MOA (Modifier or additive use); USES (Uses)
 (**surfactant**; water-based sulfur-contg. compn. chem. mech. polishing of metals)

IT 68-11-1D, alkyl esters
 RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)
 (water-based sulfur-contg. compn. chem. mech. polishing of metals)

RE.CNT 6 THERE ARE 6 CITED REFERENCES AVAILABLE FOR THIS RECORD

RE

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- (2) Anon; GB 0956927 A
- (3) Anon; GB 1117510 A
- (4) Anon; US 3503883 A
- (5) Anon; US 3518098 A
- (6) Anon; US 5650385 A CAPLUS

L15 ANSWER 5 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2005:622423 CAPLUS
 DN 143:295501
 ED Entered STN: 19 Jul 2005
 TI Single Etch Patterning of Stacked **Silver** and Molybdenum Alloy Layers on Glass Using Microcontact Wave Printing
 AU Burdinski, Dirk; Brans, Harold J. A.; Decre, Michel M. J.
 CS Philips Research, Eindhoven, 5656 AA, Neth.
 SO Journal of the American Chemical Society (2005), 127(31), 10786-10787
 CODEN: JACSAT; ISSN: 0002-7863
 PB American Chemical Society
 DT Journal
 LA English
 CC 74-13 (Radiation Chemistry, Photochemistry, and Photographic and Other Reprographic Processes)
 Section cross-reference(s): 56
 AB Stacked thin layers of **silver** alloy (AgPdCu) and MoCr layers on 10
 × 15 cm² glass substrates were patterned by microcontact wave printing and etching. Patterns of etch-resistant **octadecanethiol** self-assembled monolayers (SAMs) were wave printed with regular backplane

stabilized PDMS stamps. Pattern development was achieved by etching both metal layers in a single step, employing a nitric acid-based etching bath. Trifluoroacetic acid and a nitrite salt were identified as essential bath components for a homogeneous etching process. Etch defects could be eliminated by the addn. of a decanesulfonate, which stabilizes the SAM resist via a defect healing mechanism.

- ST etching **silver** molybdenum alloy electrode display
- IT Liquid crystal displays
(active matrix; single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing as electrodes for)
- IT **Surfactants**
(**anionic**; single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)
- IT Lithography
(microcontact printing; single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)
- IT Autocatalysis
Electrodes
Etching
Glass substrates
Self-assembled monolayers
(single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)
- IT 64-19-7, Acetic acid, processes 76-05-1, Trifluoroacetic acid, processes 7632-00-0, Sodium nitrite 7664-38-2, Phosphoric acid, processes 7697-37-2, Nitric acid, processes
RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); PROC (Process)
(etchant; single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)
- IT 2885-00-9, 1-Octadecanethiol
RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)
(ink, self-assembled monolayer; single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)
- IT 188820-19-1 317855-00-8
RL: CPS (Chemical process); DEV (Device component use); PEP (Physical, engineering or chemical process); PROC (Process); USES (Uses)
(single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)
- IT 13419-61-9, Sodium decane sulfonate
RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); PROC (Process)
(**surfactant** for etching soln.; single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)

RE.CNT 31 THERE ARE 31 CITED REFERENCES AVAILABLE FOR THIS RECORD
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L15 ANSWER 6 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2004:847649 CAPLUS

DN 141:353637

ED Entered STN: 15 Oct 2004

TI Pretreatment of **Ag**-alloy surface with organosulfur compounds for
tarnishing prevention

IN Johns, Peter Gammon; Harrison, Clare Elizabeth

PA Middlesex Silver Co. Limited, UK

SO PCT Int. Appl., 43 pp.

CODEN: PIXXD2

DT Patent

LA English

IC ICM C23F011-16

CC 56-6 (Nonferrous Metals and Alloys)

FAN.CNT 1

| | PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
|----|---|------|----------|------------------|----------|
| PI | WO 2004087996 | A1 | 20041014 | WO 2004-GB1373 | 20040330 |
| | W: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW | | | | |
| | RW: BW, GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW, AM, AZ, BY, KG, KZ, MD, RU, TJ, TM, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG | | | | |
| | AU 2004225693 | A1 | 20041014 | AU 2004-225693 | 20040330 |
| | CA 2520807 | A1 | 20041014 | CA 2004-2520807 | 20040330 |
| | EP 1611267 | A1 | 20060104 | EP 2004-724313 | 20040330 |
| | R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO, MK, CY, AL, TR, BG, CZ, EE, HU, PL, SK | | | | |
| | CN 1780937 | A | 20060531 | CN 2004-80011375 | 20040330 |

STN Columbus

| | | | | |
|-------------------|----|----------|----------------|----------|
| JP 2006523266 | T | 20061012 | JP 2006-506057 | 20040330 |
| IN 2005DN04346 | A | 20070831 | IN 2005-DN4346 | 20050926 |
| MX 2005010452 | A | 20060510 | MX 2005-10452 | 20050928 |
| US 20070039665 | A1 | 20070222 | US 2005-551476 | 20050929 |
| PRAI GB 2003-7290 | A | 20030331 | | |
| WO 2004-GB1373 | W | 20040330 | | |

CLASS

| PATENT NO. | CLASS | PATENT FAMILY CLASSIFICATION CODES |
|----------------|--|--|
| WO 2004087996 | ICM | C23F011-16 |
| | IPCI | C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C*] |
| | IPCR | C23F0011-10 [I,C*]; C23F0011-16 [I,A] |
| | ECLA | C23F011/16; C23F011/16B |
| AU 2004225693 | IPCI | C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C*] |
| | IPCR | C23F0011-10 [I,C*]; C23F0011-16 [I,A] |
| | ECLA | C23F011/16; C23F011/16B |
| CA 2520807 | IPCI | C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C*] |
| | IPCR | C23F0011-10 [I,C*]; C23F0011-16 [I,A] |
| | ECLA | C23F011/16; C23F011/16B |
| EP 1611267 | IPCI | C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C*] |
| | IPCR | C23F0011-10 [I,C*]; C23F0011-16 [I,A] |
| | ECLA | C23F011/16; C23F011/16B |
| CN 1780937 | IPCI | C23F0011-16 [I,A]; C23F0011-10 [I,C*] |
| | ECLA | C23F011/16; C23F011/16B |
| JP 2006523266 | IPCI | C23F0011-00 [I,A]; C22C0005-06 [I,A]; C22C0005-08 [I,A] |
| | IPCR | C23F0011-00 [I,C]; C23F0011-00 [I,A]; C22C0005-06 [I,C]; C22C0005-06 [I,A]; C22C0005-08 [I,A]; C23F0011-10 [I,C*]; C23F0011-16 [I,A] |
| | FTERM | 4K062/AA01; 4K062/BB21; 4K062/BC22; 4K062/FA16 |
| IN 2005DN04346 | IPCI | C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C*] |
| MX 2005010452 | IPCI | C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C*] |
| | ECLA | C23F011/16; C23F011/16B |
| US 20070039665 | IPCI | C23G0001-00 [I,A]; C23C0022-58 [I,A]; C23C0022-05 [I,C*] |
| | NCL | 148/271.000; 134/002.000 |
| AB | The Ag alloys contg. minor Ge (esp. Ag -Cu-Ge alloys) to decrease the fire stain discoloration are pretreated on the surface with an alkanethiol, alkyl thioglycollate, dialkyl sulfide, or dialkyl disulfide to prevent tarnishing. The treatment with organosulfur compds. is suitable for manufd. Ag -alloy articles to prevent tarnished appearance during transit and the subsequent extended display without special packaging. The Ag -alloy surface is optionally treated with aq. soln. contg. an alkanethiol, alkyl thioglycollate, dialkyl sulfide, or dialkyl disulfide, as well as a mixt. of anionic surfactant and amphoteric or nonionic surfactant to solubilize the treatment agent. The typical ternary alloy contains Ag 80-96, Cu 1-19.9, and Ge 0.1-5%. | |
| ST | silver copper germanium alloy tarnishing prevention organosulfur | |
| IT | Surfactants | |
| | (anionic, in tarnishing prevention; Ag -alloy surface treated with organosulfur compds. for tarnishing prevention) | |
| IT | Surfactants | |
| | (in tarnishing prevention; Ag -alloy surface treated with organosulfur compds. for tarnishing prevention) | |
| IT | Surfactants | |
| | (nonionic, in tarnishing prevention; Ag -alloy surface treated with organosulfur compds. for tarnishing prevention) | |
| IT | Tarnishing | |
| | (prevention of; Ag -alloy surface treated with organosulfur compds. for tarnishing prevention) | |
| IT | Thioethers | |

STN Columbus

Thiols, uses

RL: TEM (Technical or engineered material use); USES (Uses)
(tarnishing prevention by; **Ag**-alloy surface treated with
organosulfur compds. for tarnishing prevention)

IT 7440-56-4, Germanium, uses

RL: MOA (Modifier or additive use); USES (Uses)
(**Ag** alloys contg., tarnishing prevention on; **Ag**
-alloy surface treated with organosulfur compds. for tarnishing
prevention)

IT 106-94-5, n-Propyl bromide

RL: TEM (Technical or engineered material use); USES (Uses)
(solvent, in tarnishing prevention; **Ag**-alloy surface treated
with organosulfur compds. for tarnishing prevention)

IT 2885-00-9, Octadecyl mercaptan 2917-26-2,

Cetyl mercaptan

RL: CPS (Chemical process); PEP (Physical, engineering or chemical
process); PROC (Process)
(tarnishing prevention by; **Ag**-alloy surface treated with
organosulfur compds. for tarnishing prevention)

IT 39282-03-6, Sterling **silver** 103221-24-5 476614-10-5
476614-12-7 476614-13-8

RL: CPS (Chemical process); PEP (Physical, engineering or chemical
process); PROC (Process)
(tarnishing prevention on; **Ag**-alloy surface treated with
organosulfur compds. for tarnishing prevention)

IT 9080-17-5, Ammonium polysulfide

RL: CPS (Chemical process); PEP (Physical, engineering or chemical
process); PROC (Process)
(test soln. with, for tarnishing; **Ag**-alloy surface treated
with organosulfur compds. for tarnishing prevention)

RE.CNT 9 THERE ARE 9 CITED REFERENCES AVAILABLE FOR THIS RECORD

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- (2) Carpenter, J; US 3398003 A 1968 CAPLUS
- (3) Gamon, J; EP 0729398 A 1996 CAPLUS
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L15 ANSWER 7 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2003:851241 CAPLUS

DN 139:330251

ED Entered STN: 30 Oct 2003

TI **Silver** (carboxylate-n-alkyl thiolate) particles for photothermographic
of thermographic imaging

IN Ghyzel, Peter J.; Lelental, Mark; Dickinson, David A.; Pitt, Alan R.;
Wear, Trevor J.

PA Eastman Kodak Company, USA

SO U.S., 14 pp.

CODEN: USXXAM

DT Patent

LA English

IC ICM G03C001-498

INCL 430619000; 430611000; 430620000; 430631000

CC 74-2 (Radiation Chemistry, Photochemistry, and Photographic and Other
Reprographic Processes)

STN Columbus

FAN.CNT 1

| | PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
|------|---|------|----------|-----------------|----------|
| PI | US 6638708 | B1 | 20031028 | US 2002-200417 | 20020722 |
| | EP 1385047 | A1 | 20040128 | EP 2003-77179 | 20030710 |
| | R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO, MK, CY, AL, TR, BG, CZ, EE, HU, SK | | | | |
| | JP 2004054276 | A | 20040219 | JP 2003-199297 | 20030718 |
| PRAI | US 2002-200417 | A | 20020722 | | |

CLASS

| PATENT NO. | CLASS | PATENT FAMILY CLASSIFICATION CODES |
|---------------|-------|--|
| US 6638708 | ICM | G03C001-498 |
| | INCL | 430619000; 430611000; 430620000; 430631000 |
| | IPCI | G03C0001-498 [ICM, 7] |
| | IPCR | B41M0005-30 [I,C*]; B41M0005-323 [I,A]; G03C0001-498 [I,C*]; G03C0001-498 [I,A] |
| | NCL | 430/619.000; 430/611.000; 430/620.000; 430/631.000 |
| | ECLA | G03C001/498B; G03C001/498E1 |
| EP 1385047 | IPCI | G03C0001-498 [ICM, 7] |
| | IPCR | B41M0005-30 [I,C*]; B41M0005-323 [I,A]; G03C0001-498 [I,C*]; G03C0001-498 [I,A] |
| | ECLA | G03C001/498B; G03C001/498E1 |
| JP 2004054276 | IPCI | G03C0001-498 [ICM, 7]; B41M0005-30 [ICS, 7] |
| | IPCR | G03C0001-498 [I,A]; G03C0001-498 [I,C*] |
| | FTERM | 2H026/AA07; 2H026/BB46; 2H123/AB00; 2H123/AB03; 2H123/AB25; 2H123/AB28; 2H123/BC00; 2H123/BC12; 2H123/CB00; 2H123/CB03 |

AB The present disclosure relates to dispersions of **silver** (carboxylate-n-alkyl thiolate). The carboxylates are typically **silver** salts of long chain fatty acids and the n-alkyl thiolate is preferably 1-dodecanethiol. These **silver** (carboxylate-n-alkyl thiolate) particles can be used to formulate imaging forming compns. that are useful in aq. thermog. or photothermog. imaging elements.

ST photog emulsion **silver** carboxylate alkyl thiolate particle photothermog

IT Photographic emulsions
(heat-developable; **silver** (carboxylate-n-alkyl thiolate)
particles for photothermog. of thermog. imaging)

IT **Surfactants**
(**nonionic**; **silver** (carboxylate-n-alkyl thiolate)
particles for photothermog. of thermog. imaging)

IT Nanoparticles
(**silver** (carboxylate-n-alkyl thiolate) particles for
photothermog. of thermog. imaging)

IT 111-31-9, 1-Hexanethiol 112-55-0, 1-Dodecanethiol 112-85-6, Behenic acid **2885-00-9**, 1-Octadecanethiol

RL: TEM (Technical or engineered material use); USES (Uses)
(**silver** (carboxylate-n-alkyl thiolate) particles for
photothermog. of thermog. imaging)

RE.CNT 5 THERE ARE 5 CITED REFERENCES AVAILABLE FOR THIS RECORD

RE

- (1) Anon; EP 0803764 A1 2001 CAPLUS
- (2) Goffe; US 3666477 A 1972 CAPLUS
- (3) Lelental; US 6391537 B2 2002 CAPLUS
- (4) Voicu, R; Structure and Dynamics of Selectively Deuterated Self-Assembled Silver n-Octadecanethiolate Layered Materials P2266
- (5) Voicu, R; Thermal Behavior of a Self-Assembled Silver n-Dodecanethiolate Layered Material Monitored by DSC P2642

STN Columbus

Full Text

AN 2003:798402 CAPLUS
 DN 139:311931
 ED Entered STN: 12 Oct 2003
 TI Metal coating of hair fibers for cosmetics
 IN Vic, Gabin; Livoreil, Aude; Giroud, Franck
 PA L'oreal, Fr.
 SO Fr. Demande, 18 pp.
 CODEN: FRXXBL
 DT Patent
 LA French
 IC ICM A61K007-075
 CC 62-3 (Essential Oils and Cosmetics)
 FAN.CNT 1

| | PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
|------|---|------|----------|-----------------|----------|
| PI | FR 2838050 | A1 | 20031010 | FR 2002-4352 | 20020408 |
| | FR 2838050 | B1 | 20060714 | | |
| | CN 1449737 | A | 20031022 | CN 2003-108449 | 20030331 |
| | CN 1213719 | C | 20050810 | | |
| | BR 2003000873 | A | 20040817 | BR 2003-873 | 20030403 |
| | EP 1352630 | A2 | 20031015 | EP 2003-290860 | 20030407 |
| | EP 1352630 | A3 | 20040324 | | |
| | EP 1352630 | B1 | 20060301 | | |
| | R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO, MK, CY, AL, TR, BG, CZ, EE, HU, SK | | | | |
| | US 20030223944 | A1 | 20031204 | US 2003-407911 | 20030407 |
| | JP 2003300840 | A | 20031021 | JP 2003-104420 | 20030408 |
| | JP 3759120 | B2 | 20060322 | | |
| PRAI | FR 2002-4352 | A | 20020408 | | |
| | US 2002-372455P | P | 20020416 | | |

CLASS

| PATENT NO. | CLASS | PATENT FAMILY CLASSIFICATION CODES |
|------------|-------|--|
| FR 2838050 | ICM | A61K007-075 |
| | IPCI | A61K0007-075 [ICM, 7] |
| | IPCR | A61K0008-00 [I,C*]; A61K0008-00 [I,A]; A61K0008-18 [I,C*]; A61K0008-18 [I,A]; A61K0008-19 [I,C*]; A61K0008-19 [I,A]; A61K0008-20 [I,A]; A61K0008-23 [I,A]; A61K0008-24 [I,A]; A61K0008-26 [I,A]; A61K0008-27 [I,A]; A61K0008-30 [I,C*]; A61K0008-31 [I,A]; A61K0008-34 [I,A]; A61K0008-35 [I,A]; A61K0008-37 [I,A]; A61K0008-46 [I,A]; A61K0008-64 [I,A]; A61K0008-72 [I,C*]; A61K0008-73 [I,A]; A61K0008-89 [I,A]; A61K0008-891 [I,A]; A61Q0001-02 [I,C*]; A61Q0001-02 [I,A]; A61Q0005-00 [I,C*]; A61Q0005-00 [I,A]; A61Q0005-10 [I,C*]; A61Q0005-10 [I,A]; A61Q0005-12 [I,C*]; A61Q0005-12 [I,A] |
| | ECLA | A61Q005/12; A61K008/19; A61K008/27; A61K008/46; A61Q005/00; A61Q005/10 |
| CN 1449737 | IPCI | A61K0007-06 [ICM, 7]; A61K0007-06 [ICS, 7] |
| | IPCR | A61K0008-00 [I,C*]; A61K0008-00 [I,A]; A61K0008-18 [I,C*]; A61K0008-18 [I,A]; A61K0008-19 [I,C*]; A61K0008-19 [I,A]; A61K0008-20 [I,A]; A61K0008-23 [I,A]; A61K0008-24 [I,A]; A61K0008-26 [I,A]; A61K0008-27 [I,A]; A61K0008-30 [I,C*]; A61K0008-31 [I,A]; A61K0008-34 [I,A]; A61K0008-35 [I,A]; A61K0008-37 [I,A]; A61K0008-46 [I,A]; A61K0008-64 [I,A]; A61K0008-72 [I,C*]; A61K0008-73 [I,A]; A61K0008-89 [I,A]; A61K0008-891 [I,A]; A61Q0001-02 |

STN Columbus

[I,C*]; A61Q0001-02 [I,A]; A61Q0005-00 [I,C*];
A61Q0005-00 [I,A]; A61Q0005-10 [I,C*]; A61Q0005-10
[I,A]; A61Q0005-12 [I,C*]; A61Q0005-12 [I,A]
ECLA A61Q005/12; A61K008/19; A61K008/27; A61K008/46;
A61Q005/00; A61Q005/10
BR 2003000873 IPCI A61K0007-06 [ICM,7]
IPCR A61K0008-00 [I,C*]; A61K0008-00 [I,A]; A61K0008-18
[I,C*]; A61K0008-18 [I,A]; A61K0008-19 [I,C*];
A61K0008-19 [I,A]; A61K0008-20 [I,A]; A61K0008-23
[I,A]; A61K0008-24 [I,A]; A61K0008-26 [I,A];
A61K0008-27 [I,A]; A61K0008-30 [I,C*]; A61K0008-31
[I,A]; A61K0008-34 [I,A]; A61K0008-35 [I,A];
A61K0008-37 [I,A]; A61K0008-46 [I,A]; A61K0008-64
[I,A]; A61K0008-72 [I,C*]; A61K0008-73 [I,A];
A61K0008-89 [I,A]; A61K0008-891 [I,A]; A61Q0001-02
[I,C*]; A61Q0001-02 [I,A]; A61Q0005-00 [I,C*];
A61Q0005-00 [I,A]; A61Q0005-10 [I,C*]; A61Q0005-10
[I,A]; A61Q0005-12 [I,C*]; A61Q0005-12 [I,A]
ECLA A61Q005/12; A61K008/19; A61K008/27; A61K008/46;
A61Q005/00; A61Q005/10
EP 1352630 IPCI A61K0008-19 [I,C]; A61K0008-30 [I,C]; A61Q0005-00
[I,C]; A61Q0005-10 [I,C]; A61Q0005-10 [I,A];
A61K0008-19 [I,A]; A61K0008-46 [I,A]; A61Q0005-00 [I,A]
IPCR A61K0008-00 [I,C*]; A61K0008-00 [I,A]; A61Q0005-10
[I,A]; A61K0008-18 [I,C*]; A61K0008-18 [I,A];
A61K0008-19 [I,C]; A61K0008-19 [I,A]; A61K0008-20
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A61K0008-26 [I,A]; A61K0008-27 [I,A]; A61K0008-30
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A61K0008-35 [I,A]; A61K0008-37 [I,A]; A61K0008-46
[I,A]; A61K0008-64 [I,A]; A61K0008-72 [I,C*];
A61K0008-73 [I,A]; A61K0008-89 [I,A]; A61K0008-891
[I,A]; A61Q0001-02 [I,C*]; A61Q0001-02 [I,A];
A61Q0005-00 [I,C]; A61Q0005-00 [I,A]; A61Q0005-10
[I,C]; A61Q0005-12 [I,C*]; A61Q0005-12 [I,A]
ECLA A61Q005/12; A61K008/19; A61K008/27; A61K008/46;
A61Q005/00; A61Q005/10
US 20030223944 IPCI A61K0007-075 [ICM,7]; A61K0007-06 [ICS,7]
IPCR A61K0008-19 [I,C*]; A61K0008-19 [I,A]; A61K0008-30
[I,C*]; A61K0008-46 [I,A]; A61Q0005-12 [I,C*];
A61Q0005-12 [I,A]
NCL 424/070.100; 510/119.000
ECLA A61K008/19; A61K008/46; A61Q005/12
JP 2003300840 IPCI A61K0008-00 [I,A]; A61Q0005-00 [I,A]; A61K0008-18
[I,A]; A61Q0001-02 [I,A]
IPCR A61K0008-00 [I,C*]; A61K0008-00 [I,A]; A61K0008-18
[I,C*]; A61K0008-18 [I,A]; A61K0008-19 [I,C*];
A61K0008-19 [I,A]; A61K0008-20 [I,A]; A61K0008-23
[I,A]; A61K0008-24 [I,A]; A61K0008-26 [I,A];
A61K0008-27 [I,A]; A61K0008-30 [I,C*]; A61K0008-31
[I,A]; A61K0008-34 [I,A]; A61K0008-35 [I,A];
A61K0008-37 [I,A]; A61K0008-46 [I,A]; A61K0008-64
[I,A]; A61K0008-72 [I,C*]; A61K0008-73 [I,A];
A61K0008-89 [I,A]; A61K0008-891 [I,A]; A61Q0001-02
[I,C*]; A61Q0001-02 [I,A]; A61Q0005-00 [I,C*];
A61Q0005-00 [I,A]; A61Q0005-10 [I,C*]; A61Q0005-10
[I,A]; A61Q0005-12 [I,C*]; A61Q0005-12 [I,A]
ECLA A61Q005/12; A61K008/19; A61K008/27; A61K008/46;
A61Q005/00; A61Q005/10

AB The invention relates to a treatment process which confers cosmetic

properties on hair fibers. The process consists of treating the fibers with a metal salt in the presence of a reducing agent, directly on the fiber to form the corresponding free metal. Thus, a lock of hair after being shampooed, was dried and an aq. soln. of AgNO₃ was applied onto the hair. After the addn. of NaBH₄, the natural pigmented hair was dark, with metallic brilliance reflected on it.

- ST metal salt hair cosmetic
- IT Alcohols, biological studies
 - RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process); PYP (Physical process); BIOL (Biological study); PROC (Process); USES (Uses)
 - (C1-4; metal treatment of hair fibers for cosmetics)
- IT Alkanes, biological studies
 - RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process); PYP (Physical process); BIOL (Biological study); PROC (Process); USES (Uses)
 - (C5-10; metal treatment of hair fibers for cosmetics)
- IT Polyelectrolytes
 - Surfactants**
 - (amphoteric; metal treatment of hair fibers for cosmetics)
- IT Fats and Glyceridic oils, biological studies
 - RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process); PYP (Physical process); BIOL (Biological study); PROC (Process); USES (Uses)
 - (animal; metal treatment of hair fibers for cosmetics)
- IT **Surfactants**
 - (**anionic**; metal treatment of hair fibers for cosmetics)
- IT Polyelectrolytes
 - Surfactants**
 - (cationic; metal treatment of hair fibers for cosmetics)
- IT Cosmetics
 - (emollients; metal treatment of hair fibers for cosmetics)
- IT Sulfates, reactions
 - RL: RCT (Reactant); RACT (Reactant or reagent)
 - (hydrogen; metal treatment of hair fibers for cosmetics)
- IT Antifoaming agents
- Antiperspirants
- Cosmetics
- Hair
- Hair preparations
- Perfumes
- Pigments, nonbiological
- Preservatives
- Reducing agents
- Shampoos
- Sunscreens
- Thickening agents
 - (metal treatment of hair fibers for cosmetics)
- IT Alkaline earth salts
 - Bromates
 - Carbonates, biological studies
 - Disulfides
 - Halides
 - Nitrates, biological studies
 - Paraffin oils
 - Phosphates, biological studies
 - Polymers, biological studies
 - Polysiloxanes, biological studies
 - Proteins
 - Rare earth salts

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Sulfates, biological studies

Thioethers

Thiosulfates

Transition metal salts

Vitamins

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);

PYP (Physical process); BIOL (Biological study); PROC (Process); USES

(Uses)

(metal treatment of hair fibers for cosmetics)

IT Bisulfites

Enzymes, reactions

Sulfites

Thiols, reactions

Thioredoxins

RL: RCT (Reactant); RACT (Reactant or reagent)

(metal treatment of hair fibers for cosmetics)

IT Cosmetics

(moisturizers; metal treatment of hair fibers for cosmetics)

IT **Surfactants**

(**nonionic**; metal treatment of hair fibers for cosmetics)

IT Peroxysulfates

RL: RCT (Reactant); RACT (Reactant or reagent)

(peroxymonosulfates; metal treatment of hair fibers for cosmetics)

IT Alcohols, biological studies

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);

PYP (Physical process); BIOL (Biological study); PROC (Process); USES

(Uses)

(polyhydric; metal treatment of hair fibers for cosmetics)

IT Sulfonic acids, biological studies

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);

PYP (Physical process); BIOL (Biological study); PROC (Process); USES

(Uses)

(salts; metal treatment of hair fibers for cosmetics)

IT Sulfinic acids

Thiols, reactions

RL: RCT (Reactant); RACT (Reactant or reagent)

(salts; metal treatment of hair fibers for cosmetics)

IT Salts, reactions

RL: RCT (Reactant); RACT (Reactant or reagent)

(thiol; metal treatment of hair fibers for cosmetics)

IT Lactones

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);

PYP (Physical process); BIOL (Biological study); PROC (Process); USES

(Uses)

(thiolactones; metal treatment of hair fibers for cosmetics)

IT Fats and Glyceridic oils, biological studies

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);

PYP (Physical process); BIOL (Biological study); PROC (Process); USES

(Uses)

(vegetable; metal treatment of hair fibers for cosmetics)

IT 64-17-5, Ethanol, biological studies 67-63-0, Isopropanol, biological

studies 67-64-1, Acetone, biological studies 78-93-3, Methyl ethyl

ketone, biological studies 79-20-9, Methyl acetate 110-71-4

123-86-4, Butyl acetate 141-78-6, EtOAc, biological studies

7429-90-5D, Aluminum, salts 7439-89-6D, Iron, salts 7439-98-7D,

Molybdenum, salts 7440-02-0D, Nickel, salts 7440-05-3D, Palladium,

salts 7440-06-4D, Platinum, salts 7440-22-4D, **Silver**, salts

7440-31-5D, Tin, salts 7440-32-6D, Titanium, salts 7440-33-7D,

Tungsten, salts 7440-36-0D, Antimony, salts 7440-50-8D, Copper, salts

7440-57-5D, Gold, salts 7440-66-6D, Zinc, salts 7440-74-6D, Indium,

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salts 7758-89-6, Cuprous chloride 7761-88-8, **Silver** nitrate,
biological studies 7775-41-9, **Silver** fluoride 7783-89-3,
Silver bromate 7783-90-6, **Silver** chloride, biological
studies 7783-96-2, **Silver** iodide 7785-23-1, **Silver**
bromide 7787-70-4, Cuprous bromide 10025-98-6, Dipotassium palladium
tetrachloride 10294-26-5, **Silver** sulfate 10294-28-7, Gold
tribromide 16903-35-8 16923-58-3, Disodium hexachloroplatinate
19045-66-0D, Thiocarbamic acid, salts 73506-93-1, Diethoxyethane
RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);
PYP (Physical process); BIOL (Biological study); PROC (Process); USES
(Uses)

(metal treatment of hair fibers for cosmetics)

IT 50-81-7, Ascorbic acid, reactions 53-57-6, NaDPH 58-68-4, NaDH
68-11-1, Thioglycolic acid, reactions 77-92-9D, Citric acid, salts
106-51-4, 2,5-Cyclohexadiene-1,4-dione, reactions 123-31-9,
Hydroquinone, reactions 280-64-8, 9-BBN 1758-73-2, Formamidinesulfinic
acid **2885-00-9**, 1-Octadecanethiol 3483-12-3,
Dithiothreitol 6838-83-1, Diisoamylborane 7772-98-7 7775-14-6
7803-51-2, Phosphine 13762-51-1 14451-43-5 16853-85-3 16940-66-2
17836-88-3 25895-60-7, Sodium cyanoborohydride 37318-49-3, Protein
disulfide isomerase 56553-60-7 131760-67-3 145626-87-5
RL: RCT (Reactant); RACT (Reactant or reagent)

(metal treatment of hair fibers for cosmetics)

RE.CNT 10 THERE ARE 10 CITED REFERENCES AVAILABLE FOR THIS RECORD
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L15 ANSWER 9 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2003:737150 CAPLUS

DN 139:250305

ED Entered STN: 19 Sep 2003

TI Invisible patch for the controlled delivery of cosmetic, dermatological,
and pharmaceutical active ingredients onto the skin

IN Shefer, Adi; Shefer, Samuel

PA USA

SO U.S. Pat. Appl. Publ., 17 pp., Cont.-in-part of U. S. Ser. No. 91,935.
CODEN: USXXCO

DT Patent

LA English

IC ICM A61K031-715

ICS A61K009-70

INCL 424449000; 514061000

CC 63-6 (Pharmaceuticals)

Section cross-reference(s): 62

FAN.CNT 2

| | PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
|----|----------------|------|----------|-----------------|----------|
| | ----- | ---- | ----- | ----- | ----- |
| PI | US 20030175333 | A1 | 20030918 | US 2003-376736 | 20030228 |
| | US 20030175328 | A1 | 20030918 | US 2002-91935 | 20020306 |
| | CA 2515098 | A1 | 20040916 | CA 2004-2515098 | 20040227 |

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| | | | | |
|--------------------|--|----------|----------------|----------|
| WO 2004078122 | A2 | 20040916 | WO 2004-US6106 | 20040227 |
| WO 2004078122 | A3 | 20050203 | | |
| W: | AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI | | | |
| RW: | BW, GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG | | | |
| EP 1603499 | A2 | 20051214 | EP 2004-715783 | 20040227 |
| R: | AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO, MK, CY, AL, TR, BG, CZ, EE, HU, SK | | | |
| JP 2006519263 | T | 20060824 | JP 2006-508924 | 20040227 |
| PRAI US 2002-91935 | A2 | 20020306 | | |
| US 2003-376736 | A | 20030228 | | |
| WO 2004-US6106 | W | 20040227 | | |

CLASS

| PATENT NO. | CLASS | PATENT FAMILY CLASSIFICATION CODES |
|----------------|-------|---|
| US 20030175333 | ICM | A61K031-715 |
| | ICS | A61K009-70 |
| | INCL | 424449000; 514061000 |
| | IPCI | A61K0031-715 [I,C*]; A61K0009-70 [ICS,7] |
| | IPCR | A61F0013-00 [I,C*]; A61F0013-00 [I,A]; A61F0013-02 [I,C*]; A61F0013-02 [I,A]; A61K0008-00 [I,C*]; A61K0008-00 [I,A]; A61K0008-02 [I,C*]; A61K0008-02 [I,A]; A61K0008-11 [I,C*]; A61K0008-11 [I,A]; A61K0008-30 [I,C*]; A61K0008-35 [I,A]; A61K0008-368 [I,A]; A61K0008-44 [I,A]; A61K0008-67 [I,A]; A61K0008-72 [I,C*]; A61K0008-72 [I,A]; A61K0008-73 [I,A]; A61K0008-96 [I,C*]; A61K0008-97 [I,A]; A61K0009-50 [I,C*]; A61K0009-50 [I,A]; A61K0009-51 [I,C*]; A61K0009-51 [I,A]; A61K0009-70 [I,C*]; A61K0009-70 [I,A]; A61K0031-01 [I,C*]; A61K0031-01 [I,A]; A61K0031-045 [I,C*]; A61K0031-045 [I,A]; A61K0031-047 [I,A]; A61K0031-05 [I,A]; A61K0031-075 [I,C*]; A61K0031-085 [I,A]; A61K0031-121 [I,C*]; A61K0031-121 [I,A]; A61K0031-155 [I,C*]; A61K0031-155 [I,A]; A61K0031-165 [I,C*]; A61K0031-165 [I,A]; A61K0031-345 [I,C*]; A61K0031-345 [I,A]; A61K0031-4453 [I,C*]; A61K0031-4453 [I,A]; A61K0031-545 [I,C*]; A61K0031-545 [I,A]; A61K0031-60 [I,C*]; A61K0031-60 [I,A]; A61K0031-616 [I,A]; A61K0031-65 [I,C*]; A61K0031-65 [I,A]; A61K0031-7042 [I,C*]; A61K0031-7048 [I,A]; A61K0033-00 [I,C*]; A61K0033-00 [I,A]; A61K0033-18 [I,C*]; A61K0033-18 [I,A]; A61K0033-28 [I,C*]; A61K0033-28 [I,A]; A61K0033-38 [I,C*]; A61K0033-38 [I,A]; A61K0036-18 [I,C*]; A61K0036-18 [I,A]; A61K0036-88 [I,C*]; A61K0036-896 [I,A]; A61K0045-00 [I,C*]; A61K0045-00 [I,A]; A61K0047-32 [I,C*]; A61K0047-32 [I,A]; A61K0047-34 [I,C*]; A61K0047-34 [I,A]; A61K0047-36 [I,C*]; A61K0047-36 [I,A]; A61K0047-38 [I,C*]; A61K0047-38 [I,A]; A61K0047-42 [I,C*]; A61K0047-42 [I,A]; A61L0015-16 [I,C*]; A61L0015-44 [I,A]; A61P0017-00 [I,C*]; A61P0017-00 [I,A]; A61P0017-02 [I,A]; A61P0017-10 [I,A]; A61P0017-12 [I,A]; A61P0017-16 [I,A]; A61Q0009-04 [I,C*]; A61Q0009-04 [I,A]; A61Q0017-04 [I,C*]; A61Q0017-04 [I,A]; A61Q0019-00 [I,C*]; |

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A61Q0019-00 [I,A]; A61Q0019-02 [I,C*]; A61Q0019-02 [I,A]; A61Q0019-04 [I,C*]; A61Q0019-04 [I,A];
 A61Q0019-08 [I,C*]; A61Q0019-08 [I,A]
 NCL 424/449.000; 514/061.000
 ECLA A61K008/02C; A61K008/35; A61K008/368; A61K008/44;
 A61K008/67C; A61K008/67H; A61K008/67L; A61K008/97;
 A61K009/70E; A61L015/44; A61Q009/04; A61Q019/00;
 A61Q019/04; A61Q019/08; K61K
 US 20030175328 IPCI A61K0009-70 [ICM,7]
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 A61K0008-72 [I,C*]; A61K0008-72 [I,A]; A61K0008-73 [I,A]; A61K0008-96 [I,C*]; A61K0008-97 [I,A];
 A61K0009-50 [I,C*]; A61K0009-50 [I,A]; A61K0009-51 [I,C*]; A61K0009-51 [I,A]; A61K0009-70 [I,C*];
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 A61K0033-18 [I,C*]; A61K0033-18 [I,A]; A61K0033-28 [I,C*]; A61K0033-28 [I,A]; A61K0033-38 [I,C*];
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 A61K0047-42 [I,C*]; A61K0047-42 [I,A]; A61L0015-16 [I,C*]; A61L0015-44 [I,A]; A61P0017-00 [I,C*];
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 A61Q0009-04 [I,C*]; A61Q0009-04 [I,A]; A61Q0017-04 [I,C*]; A61Q0017-04 [I,A]; A61Q0019-00 [I,C*];
 A61Q0019-00 [I,A]; A61Q0019-02 [I,C*]; A61Q0019-02 [I,A]; A61Q0019-04 [I,C*]; A61Q0019-04 [I,A];
 A61Q0019-08 [I,C*]; A61Q0019-08 [I,A]
 NCL 424/449.000
 ECLA A61K008/02C; A61K008/35; A61K008/368; A61K008/44;
 A61K008/67C; A61K008/67H; A61K008/67L; A61K008/97;
 A61K009/70E; A61L015/44; A61Q009/04; A61Q019/00;
 A61Q019/04; A61Q019/08; K61K
 CA 2515098 IPCI A61K0009-70 [ICM,7]; A61K0007-00 [ICS,7]; A61K0045-00 [ICS,7]; A61M0037-00 [ICS,7]
 IPCR A61F0013-00 [I,C*]; A61F0013-00 [I,A]; A61K [I,S];
 A61K0009-70 [I,C*]; A61K0009-70 [I,A]; A61K0045-00 [I,C*]; A61K0045-00 [I,A]; A61M0037-00 [I,C*];
 A61M0037-00 [I,A]
 WO 2004078122 IPCI A61K [ICM,7]

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| EP 1603499 | IPCR | A61F0013-00 [I,C*]; A61F0013-00 [I,A]; A61K [I,S]; A61K0009-70 [I,C*]; A61K0009-70 [I,A]; A61K0045-00 [I,C*]; A61K0045-00 [I,A]; A61M0037-00 [I,C*]; A61M0037-00 [I,A] |
| | IPCI | A61F0013-00 [ICM,7] |
| | IPCR | A61F0013-00 [I,C*]; A61F0013-00 [I,A]; A61K [I,S]; A61K0009-70 [I,C*]; A61K0009-70 [I,A]; A61K0045-00 [I,C*]; A61K0045-00 [I,A]; A61M0037-00 [I,C*]; A61M0037-00 [I,A] |
| JP 2006519263 | IPCI | A61K0008-02 [I,A]; A61K0008-73 [I,A]; A61K0008-81 [I,A]; A61K0008-84 [I,A]; A61K0008-88 [I,A]; A61K0008-72 [I,C*]; A61K0008-34 [I,A]; A61K0008-60 [I,A]; A61K0008-46 [I,A]; A61K0008-41 [I,A]; A61K0008-37 [I,A]; A61K0008-55 [I,A]; A61K0008-58 [I,A]; A61Q0019-00 [I,A]; A61K0008-33 [I,A]; A61K0008-43 [I,A]; A61K0008-49 [I,A]; A61K0008-36 [I,A]; A61K0008-30 [I,C*]; A61K0009-70 [I,A]; A61K0047-28 [I,A]; A61K0047-36 [I,A]; A61K0047-38 [I,A]; A61K0047-32 [I,A]; A61K0047-42 [I,A]; A61K0047-34 [I,A]; A61K0047-10 [I,A]; A61K0047-20 [I,A]; A61K0047-18 [I,A]; A61K0047-16 [I,C*]; A61K0047-14 [I,A]; A61K0047-12 [I,A]; A61K0047-24 [I,A]; A61K0045-00 [I,A]; A61K0047-22 [I,A] |
| | IPCR | A61K0008-02 [I,C]; A61K0008-02 [I,A]; A61F0013-00 [I,C*]; A61F0013-00 [I,A]; A61K [I,S]; A61K0008-30 [I,C]; A61K0008-33 [I,A]; A61K0008-34 [I,A]; A61K0008-36 [I,A]; A61K0008-37 [I,A]; A61K0008-41 [I,A]; A61K0008-43 [I,A]; A61K0008-46 [I,A]; A61K0008-49 [I,A]; A61K0008-55 [I,A]; A61K0008-58 [I,A]; A61K0008-60 [I,A]; A61K0008-72 [I,C]; A61K0008-73 [I,A]; A61K0008-81 [I,A]; A61K0008-84 [I,A]; A61K0008-88 [I,A]; A61K0009-70 [I,C]; A61K0009-70 [I,A]; A61K0045-00 [I,C]; A61K0045-00 [I,A]; A61K0047-10 [I,C]; A61K0047-10 [I,A]; A61K0047-12 [I,C]; A61K0047-12 [I,A]; A61K0047-14 [I,C]; A61K0047-14 [I,A]; A61K0047-16 [I,C]; A61K0047-18 [I,A]; A61K0047-20 [I,C]; A61K0047-20 [I,A]; A61K0047-22 [I,C]; A61K0047-22 [I,A]; A61K0047-24 [I,C]; A61K0047-24 [I,A]; A61K0047-28 [I,C]; A61K0047-28 [I,A]; A61K0047-32 [I,C]; A61K0047-32 [I,A]; A61K0047-34 [I,C]; A61K0047-34 [I,A]; A61K0047-36 [I,C]; A61K0047-36 [I,A]; A61K0047-38 [I,C]; A61K0047-38 [I,A]; A61K0047-42 [I,C]; A61K0047-42 [I,A]; A61M0037-00 [I,C*]; A61M0037-00 [I,A]; A61Q0019-00 [I,C]; A61Q0019-00 [I,A] |
| | FTERM | 4C076/AA72; 4C076/AA95; 4C076/BB31; 4C076/CC01; 4C076/CC03; 4C076/CC04; 4C076/CC18; 4C076/DD03; 4C076/DD04; 4C076/DD07; 4C076/DD08; 4C076/DD09; 4C076/DD13; 4C076/DD17; 4C076/DD38A; 4C076/DD66A; 4C076/EE06A; 4C076/EE10A; 4C076/EE12A; 4C076/EE13A; 4C076/EE17A; 4C076/EE23A; 4C076/EE26A; 4C076/EE27; 4C076/EE30A; 4C076/EE31A; 4C076/EE32A; 4C076/EE38A; 4C076/FF31; 4C076/FF35; 4C083/AA112; 4C083/AB032; 4C083/AC122; 4C083/AC131; 4C083/AC181; 4C083/AC371; 4C083/AC391; 4C083/AC421; 4C083/AC441; 4C083/AC532; 4C083/AC682; 4C083/AC772; 4C083/AC781; 4C083/AC791; 4C083/AD041; 4C083/AD042; 4C083/AD051; 4C083/AD071; 4C083/AD072; 4C083/AD091; 4C083/AD111; 4C083/AD131; 4C083/AD151; 4C083/AD201; 4C083/AD202; 4C083/AD211; 4C083/AD241; 4C083/AD261; 4C083/AD271; 4C083/AD281; |

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4C083/AD282; 4C083/AD351; 4C083/AD391; 4C083/AD642;
 4C083/AD662; 4C083/CC02; 4C083/DD12; 4C083/EE12;
 4C083/EE13; 4C083/EE14; 4C083/EE16; 4C083/EE22;
 4C084/AA17; 4C084/MA32; 4C084/MA63; 4C084/NA10;
 4C084/ZA891

- AB The present invention relates to a patch for controlled topical or transdermal delivery of effective levels of cosmetic, dermatol., and pharmaceutical active ingredients onto the skin, hair follicles, and sebaceous glands, with minimal discomfort and ease of use. The patch can be transparent or clear and comprises a rate-controlling matrix layer. The matrix layer comprises water-sensitive, bioadhesive, film forming polymers, a water sol. oligomer, and a **surfactant**. The cosmetic, dermatol., and pharmaceutical active ingredients are sol. or dispersed in the matrix. The patch becomes tacky when wetted and adheres onto the skin. The adhesive properties of the patch are sufficient to maintain the patch in place on the skin for the recommended treatment period while allowing the patch to be readily removed without causing skin irritation or leaving adhesive residue on the skin. For example, an antibiotic patch contained polyvinyl alc. 50, PVP 1, polysorbate 20 5, Maltrin 180 10, lactitol 5, glycerin 10, and chloramphenicol 0.55%.
- ST patch bioadhesive polymer oligosaccharide **surfactant**; antibiotic patch PVA PVP polysorbate chloramphenicol
- IT Glycosides
 RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study); USES (Uses)
 (alkyl polyglycosides; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT **Surfactants**
 (amphoteric; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT **Surfactants**
 (anionic; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT **Surfactants**
 (cationic; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Essential oils
 RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study); USES (Uses)
 (clove; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Hair preparations
 (conditioners; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Cosmetics
 (depilatories; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Acne
 Burn
 Dandruff
 Pruritus
 Rhus diversiloba
 Rhus toxicodendron
 (drugs for; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Alcohols, biological studies
 Amides, biological studies
 Esters, biological studies
 RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study); USES (Uses)

STN Columbus

- (ethoxylated; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Hair preparations
 - (growth stimulants; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Vein, disease
 - (hemorrhoid, drugs for; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Syrups (sweetening agents)
 - (hydrolyzed starch; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Allergy inhibitors
 - Aloe barbadensis
 - Analgesics
 - Anti-infective agents
 - Anti-inflammatory agents
 - Antibacterial agents
 - Antibiotics
 - Antiemetics
 - Antihistamines
 - Antimicrobial agents
 - Antioxidants
 - Antiperspirants
 - Antitussives
 - Antiviral agents
 - Chelating agents
 - Chemotherapy
 - Cholinergic antagonists
 - Deodorants
 - Disinfectants
 - Fungicides
 - Hemostatics
 - Immunomodulators
 - Insecticides
 - Radical scavengers
 - Sunscreens
 - Suntanning agents
 - Vasoconstrictors
 - Vasodilators
 - Wound healing promoters
 - (invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Amine oxides
 - Amino acids, biological studies
 - Carbohydrates, biological studies
 - Caseins, biological studies
 - Flavonoids
 - Gelatins, biological studies
 - Glycerides, biological studies
 - Lanolin
 - Lecithins
 - Oligosaccharides, biological studies
 - Paraffin oils
 - Peptides, biological studies
 - Polyamides, biological studies
 - Polyesters, biological studies
 - Polyoxyalkylenes, biological studies
 - Polyoxyalkylenes, biological studies
 - Polysaccharides, biological studies
 - Proteins

STN Columbus

- Retinoids
- Vitamins
- RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);
- USES (Uses)
- (invisible patches contg. bioadhesive polymers and **surfactants**
-)
- IT Anesthetics
- (local; invisible patches contg. bioadhesive polymers and
- surfactants**)
- IT Cosmetics
- (moisturizers; invisible patches contg. bioadhesive polymers and
- surfactants**)
- IT **Surfactants**
- (**nonionic**; invisible patches contg. bioadhesive polymers and
- surfactants**)
- IT Amines, biological studies
- RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);
- USES (Uses)
- (polyamines, nonpolymeric; invisible patches contg. bioadhesive
- polymers and **surfactants**)
- IT Alcohols, biological studies
- RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);
- USES (Uses)
- (polyhydric, propoxylated; invisible patches contg. bioadhesive
- polymers and **surfactants**)
- IT Quaternary ammonium compounds, biological studies
- RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);
- USES (Uses)
- (polymers; invisible patches contg. bioadhesive polymers and
- surfactants**)
- IT Skin, disease
- (rash, drugs for; invisible patches contg. bioadhesive polymers and
- surfactants**)
- IT Cosmetics
- (skin-lightening; invisible patches contg. bioadhesive polymers and
- surfactants**)
- IT Drug delivery systems
- (tapes; invisible patches contg. bioadhesive polymers and
- surfactants**)
- IT Cosmetics
- (wrinkle-preventing; invisible patches contg. bioadhesive polymers and
- surfactants**)
- IT **Surfactants**
- (**zwitterionic**; invisible patches contg. bioadhesive polymers
- and **surfactants**)
- IT 36574-66-0D, N-coco acyl derivs.
- RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);
- USES (Uses)
- (cocoamidopropylbetaine; invisible patches contg. bioadhesive polymers
- and **surfactants**)
- IT 68-26-8, Retinol 96-26-4, Dihydroxyacetone 814-71-1, Calcium
- thioglycolate** 34452-51-2, Potassium **thioglycolate**
- RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
- (invisible patches contg. bioadhesive polymers and **surfactants**
-)
- IT 50-70-4, Sorbitol, biological studies 50-70-4D, Sorbitol, oligomers
- contg. 50-78-2, Aspirin 50-81-7, Vitamin C, biological studies
- 50-99-7D, Glucose, esters 50-99-7D, D-Glucose, oligomers contg.
- 55-56-1, Chlorhexidine 56-81-5, Glycerin, biological studies 56-86-0D,
- Glutamic acid, N-acyl derivs. 57-48-7D, Fructose, oligomers contg.

STN Columbus

57-50-1D, Sucrose, esters 57-50-1D, Sucrose, oligomers contg. 57-55-6, Propylene glycol, biological studies 58-86-6D, Xylose, oligomers contg. 59-23-4D, Galactose, oligomers contg. 59-87-0, Nitrofurazone 60-54-8, Tetracycline 69-65-8D, Mannitol, oligomers contg. 69-72-7, Salicylic acid, biological studies 69-79-4D, Maltose, oligomers contg. 87-99-0D, Xylitol, oligomers contg. 106-11-6, Diethylene glycol monostearate 107-36-8D, Isethionic acid, cocoyl derivs. 108-46-3, Resorcinol, biological studies 108-95-2, Phenol, biological studies 114-07-8, Erythromycin 115-83-3, Pentaerythritol tetrastearate 144-55-8, Sodium bicarbonate, biological studies 151-21-3, Sodium lauryl sulfate, biological studies 404-86-4, Capsaicin 497-19-8, Sodium carbonate, biological studies 585-86-4D, Lactitol, oligomers contg. 585-88-6D, Maltitol, oligomers contg. 770-35-4, Phenoxyisopropanol 1338-41-6, Sorbitan monostearate 1406-18-4, Vitamin E 2216-51-5 3380-34-5, Triclosan 3458-28-4D, D-Mannose, oligomers contg. 6284-40-8 7439-97-6, Mercury, biological studies 7440-22-4, **Silver**, biological studies 7553-56-2, Iodine, biological studies 8011-96-9, Calamine 8050-81-5, Simethicone 9000-01-5, Gum arabic 9002-89-5, Polyvinyl alcohol 9002-98-6 9003-05-8, Polyacrylamide 9003-39-8, Polyvinylpyrrolidone 9004-64-2, Hydroxypropyl cellulose 9005-25-8, Starch, biological studies 9005-25-8D, Starch, hydrolyzates 9005-64-5, Polysorbate 20 9011-13-6, Styrene-maleic anhydride copolymer 9011-16-9, Methyl vinyl ether-maleic anhydride copolymer 11099-07-3, Glycerin stearate 11111-12-9, Cephalosporin 11140-06-0, Glycerin palmitate 12694-22-3, Diglyceryl monostearate 13718-94-0D, Palatinose, oligomers contg. 15687-27-1, Ibuprofen 18323-44-9, Clindamycin 25322-68-3, Polyethylene glycol 25322-69-4 25655-41-8, Povidone iodine 26658-19-5, Sorbitan tristearate 27195-16-0, Sucrose distearate 30233-64-8, Glyceryl monobehenate 39529-26-5, Decaglyceryl decastearate 42852-72-2 53998-08-6, Sarcosinate 63119-59-5, Diglycerin distearate 68424-04-4, Polydextrose 71185-87-0, Hexaglyceryl tristearate 75537-01-8, Gantrez S-97 95461-64-6, Decaglyceryl pentastearate 99734-29-9, Tetraglyceryl tristearate 99880-64-5, Glyceryl dibehenate 106392-12-5, Polyoxyethylene polyoxypropylene block copolymer
RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study); USES (Uses)

(invisible patches contg. bioadhesive polymers and **surfactants**)

IT 56-75-7, Chloramphenicol 94-09-7, Benzocaine

RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)

(invisible patches contg. bioadhesive polymers and **surfactants**)

L15 ANSWER 10 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 1992:536001 CAPLUS

DN 117:136001

OREF 117:23503a,23506a

ED Entered STN: 04 Oct 1992

TI Aqueous emulsion for temporary protection of **silver** and copper surfaces against tarnishing

IN Grossmann, Hermann

PA Doduco GmbH und Co. Dr. Eugen Duerrwaechter, Germany

SO Eur. Pat. Appl., 6 pp.

CODEN: EPXXDW

DT Patent

LA German

IC ICM C23F011-16

CC 56-10 (Nonferrous Metals and Alloys)

FAN.CNT 1

STN Columbus

| | PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
|------|---------------------------|------|----------|-----------------|----------|
| PI | EP 492487 | A1 | 19920701 | EP 1991-121903 | 19911220 |
| | EP 492487 | B1 | 19960320 | | |
| | R: DE, ES, FR, GB, IT, NL | | | | |
| | DE 4041596 | A1 | 19920702 | DE 1990-4041596 | 19901222 |
| | ES 2086471 | T3 | 19960701 | ES 1991-121903 | 19911220 |
| PRAI | DE 1990-4041596 | A | 19901222 | | |
| | DE 1991-4124955 | A | 19910727 | | |

CLASS

| PATENT NO. | CLASS | PATENT FAMILY CLASSIFICATION CODES |
|------------|--|--|
| EP 492487 | ICM | C23F011-16 |
| | IPCI | C23F0011-16 [ICM,5]; C23F0011-10 [ICM,5,C*] |
| | IPCR | C23F0011-10 [I,C*]; C23F0011-16 [I,A] |
| | ECLA | C23F011/16B |
| DE 4041596 | IPCI | C23F0011-12 [ICM,5]; C23F0011-16 [ICS,5]; C23F0011-10 [ICS,5,C*]; C09K0015-06 [ICA,5]; C09K0015-12 [ICA,5]; C09K0015-00 [ICA,5,C*]; B01F0017-42 [ICA,5]; B01F0017-38 [ICA,5] |
| | IPCR | C23F0011-10 [I,C*]; C23F0011-16 [I,A] |
| | ECLA | C23F011/16B |
| ES 2086471 | IPCI | C23F0011-16 [ICM,6]; C23F0011-10 [ICM,6,C*] |
| | IPCR | C23F0011-10 [I,C*]; C23F0011-16 [I,A] |
| | ECLA | C23F011/16B |
| AB | The emulsion of pH 1-10 (preferably 2-4) comprises a hydrophobic inhibitor of a C _≥ 12 thioalc. with ≥ 1 SH group and its ester 0.05-50 (preferably 2-20), emulsifier 0.05-50 (2-20), and an anionic or nonionic surfactant ≤ 2 (0.05-1 g/L). The emulsifier comprises an alkoxyated and preferably ethoxyated branched C ₄ -20 alc., an alkyl or alkylphenyl ether of polyethylene glycol. Ag , Cu, and their alloys are treated with the emulsion at >T (m.p. of inhibitor), rinsed with H ₂ O at <T, and dried with hot air. An example emulsion of pH 3 and suitable for treatment of Ag and Ag alloys contains octadecanethiol 0.5-30, polyethylene glycol alkyl ether 0.5-30, and SDS ≤ 1 g/L H ₂ O. | |
| ST | tarnishing inhibitor silver copper; thiol SDS tarnishing inhibitor silver ; SDS thiol tarnishing inhibitor copper; polyethylene glycol ether tarnishing inhibitor | |
| IT | Thiols, uses RL: USES (Uses) (corrosion inhibitors, for copper and silver , with emulsifiers of alkyl or alkylphenyl ether of polyethylene glycol) | |
| IT | Tarnishing (of silver and copper alloys, aq. emulsion for prevention of) | |
| IT | Corrosion inhibitors (thiols, with emulsifiers of alkyl or alkyl Ph ether of polyethylene glycol) | |
| IT | Alcohols, compounds RL: PROC (Process) (C ₈ -16, ethoxyated, corrosion inhibitor emulsion contg., thiol, for copper and silver and their alloys) | |
| IT | copper alloy, base silver alloy, base RL: RCT (Reactant); RACT (Reactant or reagent) (tarnishing of, thiol inhibitor for) | |
| IT | 25322-68-3D, Polyethylene glycol, alkyl and alkylphenyl ethers 151-21-3, uses RL: PROC (Process) | |

STN Columbus

(corrosion inhibitor emulsion contg., thiol, for copper and **silver** and their alloys)

IT 2885-00-9, Octadecanethiol

RL: PROC (Process)

(corrosion inhibitors, for copper and **silver**, with emulsifiers of alkyl or alkylphenyl ether of polyethylene glycol)

IT 7440-22-4, **Silver**, reactions 7440-50-8, Copper, reactions

RL: RCT (Reactant); RACT (Reactant or reagent)

(tarnishing of, thiol inhibitor for)

L15 ANSWER 11 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 1991:89162 CAPLUS

DN 114:89162

OREF 114:15093a,15096a

ED Entered STN: 09 Mar 1991

TI **Silver** metal liquidlike films (MELLFs). The effect of **surfactants**

AU Yogeve, D.; Efrima, S.

CS Dep. Chem., Ben-Gurion Univ. Negev, Beer-Sheva, 84105, Israel

SO Langmuir (1991), 7(2), 267-71

CODEN: LANGD5; ISSN: 0743-7463

DT Journal

LA English

CC 66-4 (Surface Chemistry and Colloids)

Section cross-reference(s): 73, 74

AB The effects of **surfactants** on the prodn. and stabilization of **Ag** metal liquidlike films (MELLFs) were studied. The main role of the **surfactant** is in stabilizing the **Ag** MELLFs and improving their properties (reflectivity, "fluidity"). A variety of different **surfactants** were found to be active, and of those investigated, **anionic** fluoroalkyl **surfactants** seem to be the most effective. In the case of **anionic surfactants**, the counteraction has a significant effect on the **Ag** MELLF, esp. if it is a surface-active agent in itself. The effects of the **surfactants** on the interfacial tension and their effect on the measured reflectivities of the MELLFs are discussed in the context of the interfacial colloidal model of **Ag** MELLFs.

ST **silver** metal liquidlike film formation; **surfactant** effect metal liquidlike film; interfacial tension metal liquidlike film

IT Films

(metal liq.-like, **surfactant** effects on formation of)

IT Interfacial tension

(of **surfactant** solns., **silver** metal liq.-like film formation in relation to)

IT Sulfonic acids, compounds

RL: PRP (Properties)

(perfluoroalkane, ammonium and potassium salts, **surfactant** effect of, on **silver** metal liq.-like film formation)

IT **Surfactants**

(**silver** metal liq.-like film formation in presence of)

IT Carboxylic acids, compounds

RL: PRP (Properties)

(perfluoro, ammonium salts, **surfactant** effect of, on **silver** metal liq.-like film formation)

IT 7440-22-4, **Silver**, uses and miscellaneous

RL: USES (Uses)

(liq.-like metal film formation by, **surfactant** effects on)

IT 577-11-7 2885-00-9, 1-Octadecanethiol 9002-93-1,

Triton X 100 52584-45-9, Monflor 31 57534-41-5, Zonyl FSN

60529-61-5, Monflor 32 67479-85-0, Zonyl FSC 67479-86-1, Zonyl FSP

RL: PRP (Properties)

STN Columbus

(silver metal liq.-like film formation in presence of)

L15 ANSWER 12 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 1987:33631 CAPLUS

DN 106:33631

OREF 106:5655a,5658a

ED Entered STN: 07 Feb 1987

TI Maleimide copolymer and thermoplastic resin prepared by using this copolymer

IN Kimura, Atsushi; Toyooka, Yutaka; Kishida, Kazuo

PA Mitsubishi Rayon Co., Ltd., Japan

SO PCT Int. Appl., 41 pp.

CODEN: PIXXD2

DT Patent

LA Japanese

IC ICM C08F002-18

ICS C08F212-04; C08L033-14; C08L035-06; C08L051-04

CC 35-4 (Chemistry of Synthetic High Polymers)

Section cross-reference(s): 38

FAN.CNT 1

| | PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
|------|------------------------|------|----------|-----------------|----------|
| | ----- | ---- | ----- | ----- | ----- |
| PI | WO 8604337 | A1 | 19860731 | WO 1986-JP17 | 19860117 |
| | W: AU, US | | | | |
| | RW: DE, FR, GB, IT, NL | | | | |
| | JP 61163903 | A | 19860724 | JP 1985-4907 | 19850117 |
| | JP 61174248 | A | 19860805 | JP 1985-12705 | 19850128 |
| | AU 8653567 | A | 19860813 | AU 1986-53567 | 19860117 |
| | EP 208790 | A1 | 19870121 | EP 1986-900840 | 19860117 |
| | R: DE, FR, GB, IT, NL | | | | |
| | CA 1262299 | A1 | 19891010 | CA 1986-518902 | 19860923 |
| PRAI | JP 1985-4907 | A | 19850117 | | |
| | JP 1985-12705 | A | 19850128 | | |
| | WO 1986-JP17 | A | 19860117 | | |

CLASS

| PATENT NO. | CLASS | PATENT FAMILY CLASSIFICATION CODES |
|-------------|-------|--|
| ----- | ----- | ----- |
| WO 8604337 | ICM | C08F002-18 |
| | ICS | C08F212-04; C08L033-14; C08L035-06; C08L051-04 |
| | IPCI | C08F0002-18 [ICM, 4]; C08F0002-12 [ICM, 4, C*]; C08F0212-04 [ICS, 4]; C08F0212-00 [ICS, 4, C*]; C08L0033-14 [ICS, 4]; C08L0033-00 [ICS, 4, C*]; C08L0035-06 [ICS, 4]; C08L0035-00 [ICS, 4, C*]; C08L0051-04 [ICS, 4]; C08L0051-00 [ICS, 4, C*] |
| | IPCR | C08F0002-12 [I, C*]; C08F0002-18 [I, A]; C08F0222-00 [I, C*]; C08F0222-40 [I, A]; C08L0035-00 [I, C*]; C08L0035-06 [I, A]; C08L0051-00 [I, C*]; C08L0051-04 [I, A] |
| | ECLA | C08F222/40; C08L035/06+B5; C08L051/04+B2 |
| JP 61163903 | IPCI | C08F0002-18 [ICM, 4]; C08F0002-12 [ICM, 4, C*]; C08F0212-04 [ICS, 4]; C08F0212-00 [ICS, 4, C*]; C08F0002-00 [ICA, 4] |
| JP 61174248 | IPCI | C08L0033-18 [ICM, 4]; C08L0033-00 [ICM, 4, C*]; C08L0035-06 [ICS, 4]; C08L0035-00 [ICS, 4, C*]; C08L0051-04 [ICS, 4]; C08L0051-00 [ICS, 4, C*] |
| | IPCR | C08L0033-00 [I, C*]; C08L0033-00 [I, A]; C08L0007-00 [I, C*]; C08L0007-00 [I, A]; C08L0021-00 [I, C*]; C08L0021-00 [I, A]; C08L0023-00 [I, C*]; C08L0023-00 [I, A]; C08L0033-02 [I, A]; C08L0033-18 [I, A]; |

STN Columbus

C08L0033-24 [I,A]; C08L0035-00 [I,C*]; C08L0035-06 [I,A]; C08L0051-00 [I,C*]; C08L0051-00 [I,A]; C08L0051-02 [I,A]; C08L0051-04 [I,A]; C08L0101-00 [I,C*]; C08L0101-00 [I,A]

AU 8653567 IPCI C08F0002-18 [ICM,4]; C08F0002-12 [ICM,4,C*]; C08F0212-04 [ICS,4]; C08F0212-00 [ICS,4,C*]; C08L0033-14 [ICS,4]; C08L0033-00 [ICS,4,C*]; C08L0035-06 [ICS,4]; C08L0035-00 [ICS,4,C*]; C08L0051-04 [ICS,4]; C08L0051-00 [ICS,4,C*]

IPCR C08F0002-12 [I,C*]; C08F0002-18 [I,A]; C08F0222-00 [I,C*]; C08F0222-40 [I,A]; C08L0035-00 [I,C*]; C08L0035-06 [I,A]; C08L0051-00 [I,C*]; C08L0051-04 [I,A]

EP 208790 ECLA C08F222/40; C08L035/06+B5; C08L051/04+B2

IPCI C08F0002-18 [ICM,4]; C08F0002-12 [ICM,4,C*]; C08F0212-04 [ICS,4]; C08F0212-00 [ICS,4,C*]; C08L0033-14 [ICS,4]; C08L0033-00 [ICS,4,C*]; C08L0035-06 [ICS,4]; C08L0035-00 [ICS,4,C*]; C08L0051-04 [ICS,4]; C08L0051-00 [ICS,4,C*]

IPCR C08F0002-12 [I,C*]; C08F0002-18 [I,A]; C08F0222-00 [I,C*]; C08F0222-40 [I,A]; C08L0035-00 [I,C*]; C08L0035-06 [I,A]; C08L0051-00 [I,C*]; C08L0051-04 [I,A]

CA 1262299 ECLA C08F222/40; C08L035/06+B5; C08L051/04+B2

IPCI C08F0212-04 [ICM,4]; C08F0212-00 [ICM,4,C*]; C08L0025-02 [ICS,4]; C08L0025-00 [ICS,4,C*]; C08L0051-04 [ICS,4]; C08L0051-00 [ICS,4,C*]

IPCR C08F0212-00 [I,C*]; C08F0212-04 [I,A]; C08L0025-00 [I,C*]; C08L0025-02 [I,A]; C08L0051-00 [I,C*]; C08L0051-04 [I,A]

AB A maleimide polymer with excellent heat stability during high-temp. molding and giving a product with excellent resistance to discoloration, heat, and impact when blended with a graft rubber, is prepd. by polymn. of a monomer selected from an arom. vinyl monomer, an unsatd. nitrile, and Me methacrylate 50-95, a maleimide 5-50, and other monomers 0-30% in the presence of a Ca phosphate-based dispersing agent and a **nonionic surfactant** [RO(CH₂CH₂O)_n]mPO(OA)₃-m (R = C8-30 alkyl, aralkyl; A = H, metal; m = 1-3, n = 5-50). The process minimizes the scale formation of formed polymers on a reactor wall during polymn. Thus, a mixt. of arylonitrile 20, styrene 170, and N-phenylmaleimide 10 parts in 100 parts water contg. AIBN 0.1, tert-Bu benzoate 0.1, tert-dodecyl **mercaptan** 0.3, Gafac GB 520 0.003, and Ca₃PO₄ 0.5 part was suspension-polymd. at 80° for 3 h and at 120° for 2 h to give polymer beads (particle diam. 180 μ, glass-transition temp. 125°). During the polymn., no scale formation was obsd. A blend of 55 parts maleimide copolymer and 45 parts graft polymer from polybutadiene 50, acrylonitrile 15, and styrene 35 parts contg. Mg stearate 0.3, tris(nonylphenyl) phosphite 0.1, and Antage W 400 0.2 phr was injection-molded at 280-290° to give a sample exhibiting yellowing index (at 280°) 31, notched Izod impact strength 16.4 kg-cm/cm², Rockwell hardness (R) 102, and Vicat softening point 108°, with no **silver** streak formation, compared with 44, 16, 101, and 104, with **silver** streak formation, when a maleimide copolymer prepd. in the presence of poly(vinyl alc.) as a dispersing agent was used.

ST phenylmaleimide copolymer suspension polymn; acrylonitrile copolymer suspension polymn; styrene copolymer suspension polymn; calcium phosphate dispersant suspension polymn; polyethylene glycol lauryl ether phosphate;

STN Columbus

nonionic phosphate **surfactant** suspension polymn; scale prevention
suspension polymn dispersant; ABS blend maleimide copolymer molding; heat
stability maleimide copolymer molding

IT Plastics, molded

RL: USES (Uses)

(ABS polymer-maleimide-contg. polymers, heat- and impact-resistant,
heat-stable)

IT Heat-resistant materials

(maleimide-contg. polymers, heat stability improvement of)

IT Dispersing agents

(polyalkylene glycol phosphate-tricalcium phosphate, in suspension
polymn. of maleimide-contg. monomer mixts., for scale formation
prevention)

IT Scale (coating)

(prevention of, on reactor wall during suspension polymn. of
maleimide-contg. monomer mixts., dispersing agents for)

IT Polymerization

(suspension, of maleimide-contg. monomer mixts., dispersing agents for,
for scale formation prevention)

IT 9003-56-9

RL: USES (Uses)

(phenylmaleimide copolymer blends, heat-stable, resistant to
discoloration, heat and impact)

IT 31621-07-5P, Acrylonitrile-N-phenylmaleimide-styrene copolymer

94858-30-7P, Acrylonitrile- α -methylstyrene-N-phenylmaleimide-styrene
copolymer 101482-57-9P, Acrylonitrilemethyl
methacrylate-N-phenylmaleimide-styrene copolymer

RL: PREP (Preparation)

(prepn. of, by suspension polymn., dispersing agents for, for improved
heat stability and scale prevention during polymn.)

IT 51811-79-1, Gafac RE 610

RL: USES (Uses)

(suspending agents, Gafac RE 610, in suspension polymn. of
maleimide-contg. monomer mixts., for scale formation prevention during
polymn.)

IT 35604-29-6, Gafac GB 520

RL: USES (Uses)

(suspension agent, Gafac GB 520, in suspension polymn. of
maleimide-contg. monomer mixts., for scale formation prevention during
polymn.)

IT 7758-87-4, Tricalcium phosphate

RL: USES (Uses)

(suspension agent, in suspension polymn. of maleimide-contg. monomer
mixts., for scale formation prevention during polymn.)

RE.CNT 7 THERE ARE 7 CITED REFERENCES AVAILABLE FOR THIS RECORD

RE

(1) Anon; JP 4983785 A

(2) Anon; JP 5495689 A

(3) Anon; JP 57125242 A CAPLUS

(4) Anon; JP 57167341 A CAPLUS

(5) Anon; JP 58129043 A CAPLUS

(6) Anon; JP 58206657 A CAPLUS

(7) Anon; JP 59184243 A CAPLUS

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(FILE 'HOME' ENTERED AT 00:05:08 ON 23 MAY 2009)

STN Columbus

FILE 'CAPLUS' ENTERED AT 00:05:27 ON 23 MAY 2009
S 22811-02-5/REG# OR 10220-46-9/REG# OR 2917-26-2/REG# OR 28

L1 FILE 'REGISTRY' ENTERED AT 00:12:43 ON 23 MAY 2009
1 S 2885-00-9/RN

L2 FILE 'CAPLUS' ENTERED AT 00:12:44 ON 23 MAY 2009
2011 S L1

L3 FILE 'REGISTRY' ENTERED AT 00:12:44 ON 23 MAY 2009
1 S 2917-26-2/RN

L4 FILE 'CAPLUS' ENTERED AT 00:12:45 ON 23 MAY 2009
1621 S L3

L5 FILE 'REGISTRY' ENTERED AT 00:12:45 ON 23 MAY 2009
1 S 10220-46-9/RN

L6 FILE 'CAPLUS' ENTERED AT 00:12:45 ON 23 MAY 2009
50 S L5

L7 FILE 'REGISTRY' ENTERED AT 00:12:46 ON 23 MAY 2009
1 S 22811-02-5/RN

L8 FILE 'CAPLUS' ENTERED AT 00:12:46 ON 23 MAY 2009
6 S L7
L9 32684 S L8 OR L6 OR L4 OR L2 OR THIOGLYCOLATE OR MERCAPTOACETATE OR H
L10 84695 S (NONIONIC OR NON-IONIC OR ANIONIC OR ZWITTERIONIC) AND SURFAC
L11 319 S L9 AND L10
L12 6680 S METAL TREAT##### OR TREAT##### METAL
L13 1 S L11 AND L12
L14 522045 S SILVER OR AG
L15 12 S L11 AND L14

=> s (nonionic or non-ionic) and anionic and zwitterionic and surfactant#

79712 NONIONIC
1054666 NON
307432 IONIC
9398 NON-IONIC
(NON(W) IONIC)
134021 ANIONIC
13094 ZWITTERIONIC
275066 SURFACTANT#

L16 1173 (NONIONIC OR NON-IONIC) AND ANIONIC AND ZWITTERIONIC AND SURFAC
ANT#

=> s l11 and l16

L17 3 L11 AND L16

=> d 1-3 all

L17 ANSWER 1 OF 3 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2008:619503 CAPLUS

DN 148:545131

ED Entered STN: 23 May 2008

TI Detergent compositions in the form of microemulsions and use thereof in
the treatment of alopecia

IN Ben Alloum, Abdelkrim

PA Morocco

STN Columbus

SO PCT Int. Appl., 63pp.
 CODEN: PIXXD2
 DT Patent
 LA French
 CC 62-4 (Essential Oils and Cosmetics)
 FAN.CNT 1

| | PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
|------|---------------|--|----------|-----------------|----------|
| PI | WO 2008060130 | A2 | 20080522 | WO 2007-MA11 | 20071105 |
| | WO 2008060130 | A3 | 20081211 | | |
| | W: | AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BH, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP, KR, KZ, LA, LC, LK, LR, LS, LT, LU, LY, MA, MD, ME, MG, MK, MN, MW, MX, MY, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RS, RU, SC, SD, SE, SG, SK, SL, SM, SV, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, ZA, ZM, ZW | | | |
| | RW: | AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, LV, MC, MT, NL, PL, PT, RO, SE, SI, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG, BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW, AM, AZ, BY, KG, KZ, MD, RU, TJ, TM, AP, EA, EP, OA | | | |
| PRAI | MA 2006-29458 | A | 20061116 | | |

CLASS

| PATENT NO. | CLASS | PATENT FAMILY CLASSIFICATION CODES |
|---------------|-------|--|
| WO 2008060130 | IPCI | A61Q0007-00 [I,A]; A61Q0019-10 [I,A]; A61P0017-14 [I,A]; A61K0008-37 [I,A]; A61K0008-06 [I,A]; A61K0008-39 [I,A]; A61K0008-55 [I,A]; A61K0008-86 [I,A]; A61Q0007-00 [I,C]; A61Q0007-00 [I,A]; A61K0008-04 [I,C]; A61K0008-06 [I,A]; A61K0008-30 [I,C]; A61K0008-37 [I,A]; A61K0008-39 [I,A]; A61K0008-55 [I,A]; A61K0008-72 [I,C]; A61K0008-86 [I,A]; A61P0017-00 [I,C]; A61P0017-14 [I,A]; A61Q0019-10 [I,C]; A61Q0019-10 [I,A] |
| | IPCR | A61Q0007-00 [I,C]; A61Q0007-00 [I,A]; A61K0008-04 [I,C]; A61K0008-06 [I,A]; A61K0008-30 [I,C]; A61K0008-37 [I,A]; A61K0008-39 [I,A]; A61K0008-55 [I,A]; A61K0008-72 [I,C]; A61K0008-86 [I,A]; A61P0017-00 [I,C]; A61P0017-14 [I,A]; A61Q0019-10 [I,C]; A61Q0019-10 [I,A] |
| | ECLA | A61K008/06C; A61K008/36C; A61K008/92C; A61Q007/00 |

OS MARPAT 148:545131

AB The invention relates to detergent compns. in the form of stable, transparent oil-in-water-type microemulsions which are prepd. in accordance with the invention and which take the form of a liq. or gel. The aforementioned compns. comprise water, electrolytes, fatty acids, a combination of fatty acid salt type surface-active agents and at least one **nonionic** surface-active agent, an oil preferably selected from oils contg. long-chain triglycerides and, if desired, other auxiliary agents, additives and active principles. Said compns. can be used, in particular, to clean and condition keratinous matter such as hair or skin. The inventive compns. can micro-emulsify sebum on contact. The invention also relates to a cosmetic method for the treatment of androgenic alopecia or the prevention of hair loss. A microemulsion contained sunflower oil 3.26, free fatty acids 2.51, glycerin 2.04, copra oil fatty acids 19.84, Tergitol NP-9 16.32, sodium lactate 1.02, sodium chloride 0.65, disodium EDTA 0.16, and water 54.20%. Efficacy of the compn. in patient with alopecia is shown.

ST detergent microemulsion alopecia oil **surfactant** hair loss

STN Columbus

- IT Alcohols, biological studies
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
(C9-11, ethoxylated; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Fatty acids, biological studies
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
(alkali metal salts; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Phenols, biological studies
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
(alkyl; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Alcohols, biological studies
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
(amino; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT **Surfactants**
(anionic; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Fats and Glyceridic oils, biological studies
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
(avocado; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Fats and Glyceridic oils, biological studies
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
(babassu; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Fats and Glyceridic oils, biological studies
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
(borage seed; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT **Surfactants**
(cationic; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Alopecia
Cosmetic microemulsions
Detergents
Electrolytes
Human
Surfactants
(detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Amines, biological studies
Coconut oil
Corn oil
Fatty acids, biological studies
Linseed oil
Olive oil
Palm oil
Soybean oil
Sunflower oil
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
(detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Alcohols, biological studies
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
(ethoxylated; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Fats and Glyceridic oils, biological studies
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)

STN Columbus

- (evening primrose; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Alkali metal salts
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
(fatty acid salts; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Amides, biological studies
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
(fatty; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Glycerides, biological studies
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
(long-chain; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Alopecia
(male pattern; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT **Surfactants**
(**nonionic**; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Alcohols, biological studies
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
(polyhydric; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Fatty acids, biological studies
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
(potassium salts; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Amino acids, biological studies
Carboxylic acids, biological studies
Fatty acids, biological studies
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
(salts; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Fatty acids, biological studies
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
(sodium salts; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Fats and Glyceridic oils, biological studies
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
(vegetable; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT Fats and Glyceridic oils, biological studies
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
(wheat germ; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT **Surfactants**
(**zwitterionic**; detergent compns. in form of microemulsions and use in treatment of alopecia)
- IT 50-21-5D, Lactic acid, salts 50-70-4D, Sorbitol, esters 56-81-5D, Glycerol, esters 56-84-8D, Aspartic acid, salts 57-50-1D, Sucrose, esters 72-17-3, Sodium lactate 77-92-9D, Citric acid, salts 87-69-4D, Tartaric acid, salts 98-11-3D, Benzenesulfonic acid, alkyl derivs., salts 104-15-4, p-Toluenesulfonic acid, biological studies 367-51-1, Sodium **thioglycolate** 7447-40-7, Potassium chloride, biological studies 7647-14-5, Sodium chloride, biological studies 7664-38-2D, Phosphoric acid, salts 7757-82-6, Sodium sulfate, biological studies 9016-45-9, Tergitol NP-9 12125-02-9, Ammonium chloride, biological studies 12441-09-7D, Sorbitan, esters
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)

STN Columbus

(detergent compns. in form of microemulsions and use in treatment of alopecia)

L17 ANSWER 2 OF 3 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2005:216634 CAPLUS

DN 142:284776

ED Entered STN: 11 Mar 2005

TI Method and compositions for straightening hair using a reducing and an oxidizing agent in combination with heat

IN Mueller, Burkhard; Schellin, Aaltje; Neubueser, Inge

PA Hans Schwarzkopf & Henkel GmbH & Co. KG, Germany

SO PCT Int. Appl., 49 pp.

CODEN: PIXXD2

DT Patent

LA German

IC ICM A61K007-09

ICS A61K007-075

CC 62-3 (Essential Oils and Cosmetics)

FAN.CNT 1

| | PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
|------|---|------|----------|------------------|----------|
| PI | WO 2005020943 | A1 | 20050310 | WO 2004-EP9151 | 20040814 |
| | W: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW | | | | |
| | RW: BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW, AM, AZ, BY, KG, KZ, MD, RU, TJ, TM, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG | | | | |
| | DE 10338883 | A1 | 20050324 | DE 2003-10338883 | 20030823 |
| | BR 2004009291 | A | 20060411 | BR 2004-9291 | 20040814 |
| | EP 1656184 | A1 | 20060517 | EP 2004-764143 | 20040814 |
| | EP 1656184 | B1 | 20080326 | | |
| | R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, FI, RO, CY, TR, BG, CZ, EE, HU, PL, SK | | | | |
| | JP 2007503379 | T | 20070222 | JP 2006-523591 | 20040814 |
| | AT 390175 | T | 20080415 | AT 2004-764143 | 20040814 |
| | ES 2300812 | T3 | 20080616 | ES 2004-764143 | 20040814 |
| | US 20060150344 | A1 | 20060713 | US 2005-297707 | 20051208 |
| | HK 1086211 | A1 | 20080815 | HK 2006-106137 | 20060526 |
| PRAI | DE 2003-10338883 | A | 20030823 | | |
| | WO 2004-EP9151 | W | 20040814 | | |

CLASS

| PATENT NO. | CLASS | PATENT FAMILY CLASSIFICATION CODES |
|---------------|-------|--|
| WO 2005020943 | ICM | A61K007-09 |
| | ICS | A61K007-075 |
| | IPCI | A61K0007-09 [ICM,7]; A61K0007-075 [ICS,7] |
| | IPCR | A61K0008-30 [I,C*]; A61K0008-41 [I,A]; A61K0008-49 [I,A]; A61K0008-65 [I,A]; A61K0008-72 [I,C*]; A61K0008-73 [I,A]; A61K0008-81 [I,A]; A61Q0005-12 [I,C*]; A61Q0005-12 [I,A] |
| | ECLA | A61K008/41; A61K008/41L; A61K008/49F1; A61K008/65; A61K008/73C; A61K008/81K4; A61K008/81R; A61Q005/12; K61K |

STN Columbus

| | | |
|---------------|-------|--|
| DE 10338883 | IPCI | A61K0007-09 [ICM, 7] |
| | IPCR | A61K0008-30 [I,C*]; A61K0008-41 [I,A]; A61K0008-49 [I,A]; A61K0008-65 [I,A]; A61K0008-72 [I,C*]; A61K0008-73 [I,A]; A61K0008-81 [I,A]; A61Q0005-12 [I,C*]; A61Q0005-12 [I,A] |
| | ECLA | A61K008/41; A61K008/41L; A61K008/49F1; A61K008/65; A61K008/73C; A61K008/81K4; A61K008/81R; A61Q005/12; K61K |
| BR 2004009291 | IPCI | A61K0007-09 [ICM, 7]; A61K0007-075 [ICS, 7] |
| | ECLA | A61K008/41; A61K008/41L; A61K008/49F1; A61K008/65; A61K008/73C; A61K008/81K4; A61K008/81R; A61Q005/12; K61K |
| EP 1656184 | IPCI | A61Q0005-04 [I,C]; A61Q0005-04 [I,A]; A61K0008-30 [I,C]; A61K0008-41 [I,A]; A61K0008-44 [I,A]; A61K0008-64 [I,A]; A61K0008-65 [I,A]; A61K0008-72 [I,C]; A61K0008-81 [I,A]; A61K0008-898 [I,A]; A61K0008-96 [I,C]; A61K0008-98 [I,A]; A61Q0005-12 [I,C]; A61Q0005-12 [I,A] |
| | IPCR | A61K0008-49 [I,A]; A61K0008-73 [I,A] |
| | ECLA | A61K008/41; A61K008/41L; A61K008/49F1; A61K008/65; A61K008/73C; A61K008/81K4; A61K008/81R; A61Q005/12; K61K |
| JP 2007503379 | IPCI | A61K0008-892 [I,A]; A61K0008-81 [I,A]; A61K0008-41 [I,A]; A61K0008-891 [I,A]; A61K0008-72 [I,C*]; A61K0008-64 [I,A]; A61Q0005-12 [I,A]; A61K0008-22 [I,A]; A61K0008-19 [I,C*]; A61K0008-46 [I,A]; A61K0008-30 [I,C*] |
| | IPCR | A61K0008-72 [I,C]; A61K0008-892 [I,A]; A61K0008-19 [I,C]; A61K0008-22 [I,A]; A61K0008-30 [I,C]; A61K0008-41 [I,A]; A61K0008-46 [I,A]; A61K0008-49 [I,A]; A61K0008-64 [I,A]; A61K0008-65 [I,A]; A61K0008-73 [I,A]; A61K0008-81 [I,A]; A61K0008-891 [I,A]; A61Q0005-12 [I,C]; A61Q0005-12 [I,A] |
| | FTERM | 4C083/AB082; 4C083/AB312; 4C083/AB411; 4C083/AB412; 4C083/AC022; 4C083/AC072; 4C083/AC122; 4C083/AC172; 4C083/AC182; 4C083/AC302; 4C083/AC352; 4C083/AC422; 4C083/AC482; 4C083/AC612; 4C083/AC642; 4C083/AC691; 4C083/AC692; 4C083/AC771; 4C083/AC772; 4C083/AC782; 4C083/AC852; 4C083/AC892; 4C083/AD131; 4C083/AD132; 4C083/AD151; 4C083/AD152; 4C083/AD161; 4C083/AD162; 4C083/AD281; 4C083/AD282; 4C083/AD411; 4C083/AD412; 4C083/BB32; 4C083/BB34; 4C083/BB36; 4C083/BB53; 4C083/CC31; 4C083/CC33; 4C083/DD06; 4C083/DD23; 4C083/DD27; 4C083/DD38; 4C083/EE05; 4C083/EE06; 4C083/EE07; 4C083/EE21; 4C083/EE28 |
| AT 390175 | IPCI | A61Q0005-04 [I,C]; A61Q0005-04 [I,A]; A61K0008-30 [I,C]; A61K0008-41 [I,A]; A61K0008-64 [I,A]; A61K0008-65 [I,A]; A61K0008-72 [I,C]; A61K0008-81 [I,A]; A61K0008-898 [I,A]; A61K0008-96 [I,C]; A61K0008-98 [I,A]; A61Q0005-12 [I,C]; A61Q0005-12 [I,A] |
| | IPCR | A61Q0005-04 [I,C]; A61Q0005-04 [I,A]; A61K0008-30 [I,C]; A61K0008-41 [I,A]; A61K0008-49 [I,A]; A61K0008-64 [I,A]; A61K0008-65 [I,A]; A61K0008-72 [I,C]; A61K0008-73 [I,A]; A61K0008-81 [I,A]; A61K0008-898 [I,A]; A61K0008-96 [I,C]; A61K0008-98 [I,A]; A61Q0005-12 [I,C]; A61Q0005-12 [I,A] |
| | ECLA | A61K008/41; A61K008/41L; A61K008/49F1; A61K008/65; A61K008/73C; A61K008/81K4; A61K008/81R; A61Q005/12; K61K |
| ES 2300812 | IPCI | A61Q0005-04 [I,C]; A61Q0005-04 [I,A]; A61K0008-30 |

STN Columbus

[I,C]; A61K0008-41 [I,A]; A61K0008-44 [I,A];
A61K0008-64 [I,A]; A61K0008-65 [I,A]; A61K0008-72
[I,C]; A61K0008-81 [I,A]; A61K0008-898 [I,A];
A61K0008-96 [I,C]; A61K0008-98 [I,A]; A61Q0005-12
[I,C]; A61Q0005-12 [I,A]
IPCR A61Q0005-04 [I,C]; A61Q0005-04 [I,A]; A61K0008-30
[I,C]; A61K0008-41 [I,A]; A61K0008-44 [I,A];
A61K0008-49 [I,A]; A61K0008-64 [I,A]; A61K0008-65
[I,A]; A61K0008-72 [I,C]; A61K0008-73 [I,A];
A61K0008-81 [I,A]; A61K0008-898 [I,A]; A61K0008-96
[I,C]; A61K0008-98 [I,A]; A61Q0005-12 [I,C];
A61Q0005-12 [I,A]
ECLA A61K008/41; A61K008/41L; A61K008/49F1; A61K008/65;
A61K008/73C; A61K008/81K4; A61K008/81R; A61Q005/12;
K61K
US 20060150344 IPCI A61K0008-00 [I,A]
IPCR A61K0008-00 [I,A]; A61K0008-00 [I,C]
NCL 008/405.000
ECLA A61K008/898; A61K008/41L; A61K008/58C; A61K008/64;
A61K008/64C; A61K008/65; A61K008/73C; A61K008/81K4;
A61K008/81R; A61K008/891; A61Q005/12; K61K
HK 1086211 IPCI A61Q [I,S]; A61K [N,S]
IPCR A61K0008-30 [I,C*]; A61K0008-41 [I,A]; A61K0008-49
[I,A]; A61K0008-65 [I,A]; A61K0008-72 [I,C*];
A61K0008-73 [I,A]; A61K0008-81 [I,A]; A61Q0005-12
[I,C*]; A61Q0005-12 [I,A]
ECLA A61K008/41; A61K008/41L; A61K008/49F1; A61K008/65;
A61K008/73C; A61K008/81K4; A61K008/81R; A61Q005/12;
K61K
AB The invention concerns a method and compns. for straightening hair by (i)
applying an aq. soln. that contains a keratin-reducing agent (A); (ii)
rinsing the reducing-agent contg. soln. after a time period; (iii) drying
the hair; (iv) exposing the hair to straightening under heat treatment at
120-220 °C by ironing; (v) applying an aq. soln. that contains an
oxidn. agent (B); (vi) rinsing off the soln. after a time period elapsed.
Both A and B solns. contain conditioning agents selected from the group of
cationic polymers, quaternary ammonium compds., silicones and protein
hydrolyzates. Thus a component A included (wt./wt.%): 1,2-propylene
glycol 2.00; cetyl/stearyl alc. (50-50% mixt.) 9.00; Lanette E 0.50; Brij
35 P 0.50; Natrosol 250 HR 0.25; ammonia (25% aq.soln.) 5.00; Turpinal SL
0.25; ammonium **thioglycolate** (71% aq.soln.) 18.00; ammonium bicarbonate
4.00; Promois Silk 1000 1.00; Dow Corning 1403 fluid 0.50; perfume 1.00;
water to 100. Component B contained (wt./wt.%): cetearyl alc. 4.00;
Eumulgin B3 0.50; ammonia (25% aq.soln.) 0.80; dipicolinic acid 0.10;
Turpinal SL 1.70; Rheocare CTH(E) 1.00; hydrogen peroxide (50% aq.soln.)
4.00; water to 100.
ST hair straightening compn reducing oxidizing agent conditioner heat
IT Polysiloxanes, biological studies
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
((aminoethyl)amino]propyl hydroxy, di-Me; method and compns. for
straightening hair using reducing and oxidizing agents in combination
with heat)
IT **Surfactants**
(amphoteric; method and compns. for straightening hair using reducing
and oxidizing agents in combination with heat)
IT **Surfactants**
(**anionic**; method and compns. for straightening hair using
reducing and oxidizing agents in combination with heat)
IT Polyelectrolytes

STN Columbus

- (cationic; method and compns. for straightening hair using reducing and oxidizing agents in combination with heat)
- IT Hair preparations
(conditioners; method and compns. for straightening hair using reducing and oxidizing agents in combination with heat)
- IT Cyclosiloxanes
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
(di-Me; method and compns. for straightening hair using reducing and oxidizing agents in combination with heat)
- IT Quaternary ammonium compounds, biological studies
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
(ester group-contg.; method and compns. for straightening hair using reducing and oxidizing agents in combination with heat)
- IT Fibroin
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
(hydrolyzates; method and compns. for straightening hair using reducing and oxidizing agents in combination with heat)
- IT Onium compounds
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
(imidazolium compds., 2-(C9-19 and C9-19-unsatd. alkyl)-1-[(C10-20 and C10-20-unsatd. amido)ethyl]-4,5-dihydro-1-Me, Me sulfates, Rewoquat W 575PG; method and compns. for straightening hair using reducing and oxidizing agents in combination with heat)
- IT Heat treatment
Oxidizing agents
Reducing agents
Viscosity
(method and compns. for straightening hair using reducing and oxidizing agents in combination with heat)
- IT Polysiloxanes, biological studies
Protein hydrolyzates
Quaternary ammonium compounds, biological studies
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
(method and compns. for straightening hair using reducing and oxidizing agents in combination with heat)
- IT **Surfactants**
(**nonionic**; method and compns. for straightening hair using reducing and oxidizing agents in combination with heat)
- IT Hair preparations
(straighteners; method and compns. for straightening hair using reducing and oxidizing agents in combination with heat)
- IT **Surfactants**
(**zwitterionic**; method and compns. for straightening hair using reducing and oxidizing agents in combination with heat)
- IT 112-02-7, Dehyquart A-CA 2809-21-4, Turpinal SL 5421-46-5, Ammonium **thioglycolate** 7651-02-7, Tegoamide S18 7722-84-1, Hydrogen peroxide, biological studies 8045-77-0, Lanette E 9002-92-0, Brij 35 P 9004-62-0, Natrosol 250 HR 9006-65-9, Dimethicone 16962-53-1D, Trimethyl ammonium, alkyl halogenide derivs. 17000-00-9D, Methylammonium, trialkyl halogenide derivs. 17000-01-0D, Dimethylammonium, dialkyl halogenide derivs. 17301-53-0, Genamin KDMP 26062-79-3, Merquat 100 26161-33-1, Rheocare CTH(E) 31692-79-2, Dimethiconol 32208-04-1, Dehyquart F75 81859-24-7, Polymer JR 400 195868-36-1, Phenyltrimethicone 205537-77-5, Dow Corning 1403 473664-54-9, Salcare SC 96
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
(method and compns. for straightening hair using reducing and oxidizing agents in combination with heat)

RE.CNT 12 THERE ARE 12 CITED REFERENCES AVAILABLE FOR THIS RECORD
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L17 ANSWER 3 OF 3 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2003:737150 CAPLUS

DN 139:250305

ED Entered STN: 19 Sep 2003

TI Invisible patch for the controlled delivery of cosmetic, dermatological, and pharmaceutical active ingredients onto the skin

IN Shefer, Adi; Shefer, Samuel

PA USA

SO U.S. Pat. Appl. Publ., 17 pp., Cont.-in-part of U. S. Ser. No. 91,935.
CODEN: USXXCO

DT Patent

LA English

IC ICM A61K031-715

ICS A61K009-70

INCL 424449000; 514061000

CC 63-6 (Pharmaceuticals)

Section cross-reference(s): 62

FAN.CNT 2

| | PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
|------|---|------|----------|-----------------|----------|
| PI | US 20030175333 | A1 | 20030918 | US 2003-376736 | 20030228 |
| | US 20030175328 | A1 | 20030918 | US 2002-91935 | 20020306 |
| | CA 2515098 | A1 | 20040916 | CA 2004-2515098 | 20040227 |
| | WO 2004078122 | A2 | 20040916 | WO 2004-US6106 | 20040227 |
| | WO 2004078122 | A3 | 20050203 | | |
| | W: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI | | | | |
| | RW: BW, GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG | | | | |
| | EP 1603499 | A2 | 20051214 | EP 2004-715783 | 20040227 |
| | R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO, MK, CY, AL, TR, BG, CZ, EE, HU, SK | | | | |
| | JP 2006519263 | T | 20060824 | JP 2006-508924 | 20040227 |
| PRAI | US 2002-91935 | A2 | 20020306 | | |
| | US 2003-376736 | A | 20030228 | | |
| | WO 2004-US6106 | W | 20040227 | | |

CLASS

| PATENT NO. | CLASS | PATENT FAMILY CLASSIFICATION CODES |
|----------------|-------|------------------------------------|
| US 20030175333 | ICM | A61K031-715 |
| | ICS | A61K009-70 |

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| | |
|----------------|--|
| INCL | 424449000; 514061000 |
| IPCI | A61K0031-715 [ICM,7]; A61K0009-70 [ICS,7] |
| IPCR | A61F0013-00 [I,C*]; A61F0013-00 [I,A]; A61F0013-02 [I,C*]; A61F0013-02 [I,A]; A61K0008-00 [I,C*]; A61K0008-00 [I,A]; A61K0008-02 [I,C*]; A61K0008-02 [I,A]; A61K0008-11 [I,C*]; A61K0008-11 [I,A]; A61K0008-30 [I,C*]; A61K0008-35 [I,A]; A61K0008-368 [I,A]; A61K0008-44 [I,A]; A61K0008-67 [I,A]; A61K0008-72 [I,C*]; A61K0008-72 [I,A]; A61K0008-73 [I,A]; A61K0008-96 [I,C*]; A61K0008-97 [I,A]; A61K0009-50 [I,C*]; A61K0009-50 [I,A]; A61K0009-51 [I,C*]; A61K0009-51 [I,A]; A61K0009-70 [I,C*]; A61K0009-70 [I,A]; A61K0031-01 [I,C*]; A61K0031-01 [I,A]; A61K0031-045 [I,C*]; A61K0031-045 [I,A]; A61K0031-047 [I,A]; A61K0031-05 [I,A]; A61K0031-075 [I,C*]; A61K0031-085 [I,A]; A61K0031-121 [I,C*]; A61K0031-121 [I,A]; A61K0031-155 [I,C*]; A61K0031-155 [I,A]; A61K0031-165 [I,C*]; A61K0031-165 [I,A]; A61K0031-345 [I,C*]; A61K0031-345 [I,A]; A61K0031-4453 [I,C*]; A61K0031-4453 [I,A]; A61K0031-545 [I,C*]; A61K0031-545 [I,A]; A61K0031-60 [I,C*]; A61K0031-60 [I,A]; A61K0031-616 [I,A]; A61K0031-65 [I,C*]; A61K0031-65 [I,A]; A61K0031-7042 [I,C*]; A61K0031-7048 [I,A]; A61K0033-00 [I,C*]; A61K0033-00 [I,A]; A61K0033-18 [I,C*]; A61K0033-18 [I,A]; A61K0033-28 [I,C*]; A61K0033-28 [I,A]; A61K0033-38 [I,C*]; A61K0033-38 [I,A]; A61K0036-18 [I,C*]; A61K0036-18 [I,A]; A61K0036-88 [I,C*]; A61K0036-896 [I,A]; A61K0045-00 [I,C*]; A61K0045-00 [I,A]; A61K0047-32 [I,C*]; A61K0047-32 [I,A]; A61K0047-34 [I,C*]; A61K0047-34 [I,A]; A61K0047-36 [I,C*]; A61K0047-36 [I,A]; A61K0047-38 [I,C*]; A61K0047-38 [I,A]; A61K0047-42 [I,C*]; A61K0047-42 [I,A]; A61L0015-16 [I,C*]; A61L0015-44 [I,A]; A61P0017-00 [I,C*]; A61P0017-00 [I,A]; A61P0017-02 [I,A]; A61P0017-10 [I,A]; A61P0017-12 [I,A]; A61P0017-16 [I,A]; A61Q0009-04 [I,C*]; A61Q0009-04 [I,A]; A61Q0017-04 [I,C*]; A61Q0017-04 [I,A]; A61Q0019-00 [I,C*]; A61Q0019-00 [I,A]; A61Q0019-02 [I,C*]; A61Q0019-02 [I,A]; A61Q0019-04 [I,C*]; A61Q0019-04 [I,A]; A61Q0019-08 [I,C*]; A61Q0019-08 [I,A] |
| NCL | 424/449.000; 514/061.000 |
| ECLA | A61K008/02C; A61K008/35; A61K008/368; A61K008/44; A61K008/67C; A61K008/67H; A61K008/67L; A61K008/97; A61K009/70E; A61L015/44; A61Q009/04; A61Q019/00; A61Q019/04; A61Q019/08; K61K |
| US 20030175328 | IPCI A61K0009-70 [ICM,7] |
| | IPCR A61F0013-00 [I,C*]; A61F0013-00 [I,A]; A61F0013-02 [I,C*]; A61F0013-02 [I,A]; A61K0008-00 [I,C*]; A61K0008-00 [I,A]; A61K0008-02 [I,C*]; A61K0008-02 [I,A]; A61K0008-11 [I,C*]; A61K0008-11 [I,A]; A61K0008-30 [I,C*]; A61K0008-35 [I,A]; A61K0008-368 [I,A]; A61K0008-44 [I,A]; A61K0008-67 [I,A]; A61K0008-72 [I,C*]; A61K0008-72 [I,A]; A61K0008-73 [I,A]; A61K0008-96 [I,C*]; A61K0008-97 [I,A]; A61K0009-50 [I,C*]; A61K0009-50 [I,A]; A61K0009-51 [I,C*]; A61K0009-51 [I,A]; A61K0009-70 [I,C*]; A61K0009-70 [I,A]; A61K0031-01 [I,C*]; A61K0031-01 [I,A]; A61K0031-045 [I,C*]; A61K0031-045 [I,A]; A61K0031-047 [I,A]; A61K0031-05 [I,A]; A61K0031-075 |

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 NCL 424/449.000
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 A61K008/67C; A61K008/67H; A61K008/67L; A61K008/97;
 A61K009/70E; A61L015/44; A61Q009/04; A61Q019/00;
 A61Q019/04; A61Q019/08; K61K
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 [ICS,7]; A61M0037-00 [ICS,7]
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4C076/CC03; 4C076/CC04; 4C076/CC18; 4C076/DD03;
4C076/DD04; 4C076/DD07; 4C076/DD08; 4C076/DD09;
4C076/DD13; 4C076/DD17; 4C076/DD38A; 4C076/DD66A;
4C076/EE06A; 4C076/EE10A; 4C076/EE12A; 4C076/EE13A;
4C076/EE17A; 4C076/EE23A; 4C076/EE26A; 4C076/EE27;
4C076/EE30A; 4C076/EE31A; 4C076/EE32A; 4C076/EE38A;
4C076/FF31; 4C076/FF35; 4C083/AA112; 4C083/AB032;
4C083/AC122; 4C083/AC131; 4C083/AC181; 4C083/AC371;
4C083/AC391; 4C083/AC421; 4C083/AC441; 4C083/AC532;
4C083/AC682; 4C083/AC772; 4C083/AC781; 4C083/AC791;
4C083/AD041; 4C083/AD042; 4C083/AD051; 4C083/AD071;
4C083/AD072; 4C083/AD091; 4C083/AD111; 4C083/AD131;
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4C083/AD282; 4C083/AD351; 4C083/AD391; 4C083/AD642;
4C083/AD662; 4C083/CC02; 4C083/DD12; 4C083/EE12;
4C083/EE13; 4C083/EE14; 4C083/EE16; 4C083/EE22;
4C084/AA17; 4C084/MA32; 4C084/MA63; 4C084/NA10;
4C084/ZA891

AB The present invention relates to a patch for controlled topical or transdermal delivery of effective levels of cosmetic, dermatol., and pharmaceutical active ingredients onto the skin, hair follicles, and sebaceous glands, with minimal discomfort and ease of use. The patch can be transparent or clear and comprises a rate-controlling matrix layer. The matrix layer comprises water-sensitive, bioadhesive, film forming polymers, a water sol. oligomer, and a **surfactant**. The cosmetic, dermatol., and pharmaceutical active ingredients are sol. or dispersed in the matrix. The patch becomes tacky when wetted and adheres onto the skin. The adhesive properties of the patch are sufficient to maintain the patch in place on the skin for the recommended treatment period while allowing the patch to be readily removed without causing skin irritation or leaving adhesive residue on the skin. For example, an antibiotic patch contained polyvinyl alc. 50, PVP 1, polysorbate 20 5, Maltrin 180 10, lactitol 5, glycerin 10, and chloramphenicol 0.55%.

ST patch bioadhesive polymer oligosaccharide **surfactant**; antibiotic patch PVA PVP polysorbate chloramphenicol

STN Columbus

- IT Glycosides
RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);
USES (Uses)
(alkyl polyglycosides; invisible patches contg. bioadhesive polymers
and **surfactants**)
- IT **Surfactants**
(amphoteric; invisible patches contg. bioadhesive polymers and
surfactants)
- IT **Surfactants**
(**anionic**; invisible patches contg. bioadhesive polymers and
surfactants)
- IT **Surfactants**
(cationic; invisible patches contg. bioadhesive polymers and
surfactants)
- IT Essential oils
RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);
USES (Uses)
(clove; invisible patches contg. bioadhesive polymers and
surfactants)
- IT Hair preparations
(conditioners; invisible patches contg. bioadhesive polymers and
surfactants)
- IT Cosmetics
(depilatories; invisible patches contg. bioadhesive polymers and
surfactants)
- IT Acne
Burn
Dandruff
Pruritus
Rhus diversiloba
Rhus toxicodendron
(drugs for; invisible patches contg. bioadhesive polymers and
surfactants)
- IT Alcohols, biological studies
Amides, biological studies
Esters, biological studies
RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);
USES (Uses)
(ethoxylated; invisible patches contg. bioadhesive polymers and
surfactants)
- IT Hair preparations
(growth stimulants; invisible patches contg. bioadhesive polymers and
surfactants)
- IT Vein, disease
(hemorrhoid, drugs for; invisible patches contg. bioadhesive polymers
and **surfactants**)
- IT Syrups (sweetening agents)
(hydrolyzed starch; invisible patches contg. bioadhesive polymers and
surfactants)
- IT Allergy inhibitors
Aloe barbadensis
Analgesics
Anti-infective agents
Anti-inflammatory agents
Antibacterial agents
Antibiotics
Antiemetics
Antihistamines
Antimicrobial agents
Antioxidants

STN Columbus

Antiperspirants
Antitussives
Antiviral agents
Chelating agents
Chemotherapy
Cholinergic antagonists
Deodorants
Disinfectants
Fungicides
Hemostatics
Immunomodulators
Insecticides
Radical scavengers
Sunscreens
Suntanning agents
Vasoconstrictors
Vasodilators
Wound healing promoters
 (invisible patches contg. bioadhesive polymers and **surfactants**
)

IT Amine oxides
Amino acids, biological studies
Carbohydrates, biological studies
Caseins, biological studies
Flavonoids
Gelatins, biological studies
Glycerides, biological studies
Lanolin
Lecithins
Oligosaccharides, biological studies
Paraffin oils
Peptides, biological studies
Polyamides, biological studies
Polyesters, biological studies
Polyoxyalkylenes, biological studies
Polyoxyalkylenes, biological studies
Polysaccharides, biological studies
Proteins
Retinoids
Vitamins
RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);
USES (Uses)
 (invisible patches contg. bioadhesive polymers and **surfactants**
)

IT Anesthetics
 (local; invisible patches contg. bioadhesive polymers and
 surfactants)

IT Cosmetics
 (moisturizers; invisible patches contg. bioadhesive polymers and
 surfactants)

IT **Surfactants**
 (**nonionic**; invisible patches contg. bioadhesive polymers and
 surfactants)

IT Amines, biological studies
RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);
USES (Uses)
 (polyamines, nonpolymeric; invisible patches contg. bioadhesive
 polymers and **surfactants**)

IT Alcohols, biological studies
RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);

STN Columbus

- USES (Uses)
(polyhydric, propoxylated; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Quaternary ammonium compounds, biological studies
RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);
USES (Uses)
(polymers; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Skin, disease
(rash, drugs for; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Cosmetics
(skin-lightening; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Drug delivery systems
(tapes; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Cosmetics
(wrinkle-preventing; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT **Surfactants**
(**zwitterionic**; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT 36574-66-0D, N-coco acyl derivs.
RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);
USES (Uses)
(cocoamidopropylbetaine; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT 68-26-8, Retinol 96-26-4, Dihydroxyacetone 814-71-1, Calcium **thioglycolate** 34452-51-2, Potassium **thioglycolate**
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
(invisible patches contg. bioadhesive polymers and **surfactants**)
- IT 50-70-4, Sorbitol, biological studies 50-70-4D, Sorbitol, oligomers contg. 50-78-2, Aspirin 50-81-7, Vitamin C, biological studies 50-99-7D, Glucose, esters 50-99-7D, D-Glucose, oligomers contg. 55-56-1, Chlorhexidine 56-81-5, Glycerin, biological studies 56-86-0D, Glutamic acid, N-acyl derivs. 57-48-7D, Fructose, oligomers contg. 57-50-1D, Sucrose, esters 57-50-1D, Sucrose, oligomers contg. 57-55-6, Propylene glycol, biological studies 58-86-6D, Xylose, oligomers contg. 59-23-4D, Galactose, oligomers contg. 59-87-0, Nitrofurazone 60-54-8, Tetracycline 69-65-8D, Mannitol, oligomers contg. 69-72-7, Salicylic acid, biological studies 69-79-4D, Maltose, oligomers contg. 87-99-0D, Xylitol, oligomers contg. 106-11-6, Diethylene glycol monostearate 107-36-8D, Isethionic acid, cocoyl derivs. 108-46-3, Resorcinol, biological studies 108-95-2, Phenol, biological studies 114-07-8, Erythromycin 115-83-3, Pentaerythritol tetrastearate 144-55-8, Sodium bicarbonate, biological studies 151-21-3, Sodium lauryl sulfate, biological studies 404-86-4, Capsaicin 497-19-8, Sodium carbonate, biological studies 585-86-4D, Lactitol, oligomers contg. 585-88-6D, Maltitol, oligomers contg. 770-35-4, Phenoxyisopropanol 1338-41-6, Sorbitan monostearate 1406-18-4, Vitamin E 2216-51-5 3380-34-5, Triclosan 3458-28-4D, D-Mannose, oligomers contg. 6284-40-8 7439-97-6, Mercury, biological studies 7440-22-4, Silver, biological studies 7553-56-2, Iodine, biological studies 8011-96-9, Calamine 8050-81-5, Simethicone 9000-01-5, Gum arabic 9002-89-5, Polyvinyl alcohol 9002-98-6 9003-05-8, Polyacrylamide 9003-39-8, Polyvinylpyrrolidone 9004-64-2, Hydroxypropyl cellulose 9005-25-8, Starch, biological studies 9005-25-8D, Starch, hydrolyzates 9005-64-5, Polysorbate 20 9011-13-6, Styrene-maleic anhydride copolymer

STN Columbus

9011-16-9, Methyl vinyl ether-maleic anhydride copolymer 11099-07-3, Glycerin stearate 11111-12-9, Cephalosporin 11140-06-0, Glycerin palmitate 12694-22-3, Diglyceryl monostearate 13718-94-0D, Palatinose, oligomers contg. 15687-27-1, Ibuprofen 18323-44-9, Clindamycin 25322-68-3, Polyethylene glycol 25322-69-4 25655-41-8, Povidone iodine 26658-19-5, Sorbitan tristearate 27195-16-0, Sucrose distearate 30233-64-8, Glyceryl monobehenate 39529-26-5, Decaglyceryl decastearate 42852-72-2 53998-08-6, Sarcosinate 63119-59-5, Diglycerin distearate 68424-04-4, Polydextrose 71185-87-0, Hexaglyceryl tristearate 75537-01-8, Gantrez S-97 95461-64-6, Decaglyceryl pentastearate 99734-29-9, Tetraglyceryl tristearate 99880-64-5, Glyceryl dibehenate 106392-12-5, Polyoxyethylene polyoxypropylene block copolymer
 RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);
 USES (Uses)

(invisible patches contg. bioadhesive polymers and **surfactants**)

IT 56-75-7, Chloramphenicol 94-09-7, Benzocaine

RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)

(invisible patches contg. bioadhesive polymers and **surfactants**)

=> d his

(FILE 'HOME' ENTERED AT 00:05:08 ON 23 MAY 2009)

FILE 'CAPLUS' ENTERED AT 00:05:27 ON 23 MAY 2009

S 22811-02-5/REG# OR 10220-46-9/REG# OR 2917-26-2/REG# OR 28

FILE 'REGISTRY' ENTERED AT 00:12:43 ON 23 MAY 2009

L1 1 S 2885-00-9/RN

FILE 'CAPLUS' ENTERED AT 00:12:44 ON 23 MAY 2009

L2 2011 S L1

FILE 'REGISTRY' ENTERED AT 00:12:44 ON 23 MAY 2009

L3 1 S 2917-26-2/RN

FILE 'CAPLUS' ENTERED AT 00:12:45 ON 23 MAY 2009

L4 1621 S L3

FILE 'REGISTRY' ENTERED AT 00:12:45 ON 23 MAY 2009

L5 1 S 10220-46-9/RN

FILE 'CAPLUS' ENTERED AT 00:12:45 ON 23 MAY 2009

L6 50 S L5

FILE 'REGISTRY' ENTERED AT 00:12:46 ON 23 MAY 2009

L7 1 S 22811-02-5/RN

FILE 'CAPLUS' ENTERED AT 00:12:46 ON 23 MAY 2009

L8 6 S L7

L9 32684 S L8 OR L6 OR L4 OR L2 OR THIOGLYCOLATE OR MERCAPTOACETATE OR H

L10 84695 S (NONIONIC OR NON-IONIC OR ANIONIC OR ZWITTERIONIC) AND SURFAC

L11 319 S L9 AND L10

L12 6680 S METAL TREAT##### OR TREAT##### METAL

L13 1 S L11 AND L12

L14 522045 S SILVER OR AG

L15 12 S L11 AND L14

L16 1173 S (NONIONIC OR NON-IONIC) AND ANIONIC AND ZWITTERIONIC AND SURF

STN Columbus

L17 3 S L11 AND L16

=> s l11 and l14

L18 12 L11 AND L14

=> s l18 not l15

L19 0 L18 NOT L15

=> d l18 1-12 all

L18 ANSWER 1 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2008:1046144 CAPLUS

DN 149:312963

ED Entered STN: 29 Aug 2008

TI Preparation of conductive supported noble metal nanoparticle catalysts

IN Stucky, Galen D.; Zheng, Nanfeng

PA The Regents of the University of California, USA

SO U.S. Pat. Appl. Publ., 35pp.

CODEN: USXXCO

DT Patent

LA English

INCL 428403000; 216055000; 428402000; 264005000; 264007000; 502100000;
502300000; 502159000; 502355000; 502350000

CC 56-4 (Nonferrous Metals and Alloys)

Section cross-reference(s): 57, 67

FAN.CNT 1

| | PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
|------|-----------------|------|----------|-----------------|----------|
| PI | US 20080206562 | A1 | 20080828 | US 2008-13436 | 20080112 |
| PRAI | US 2007-884668P | P | 20070112 | | |

CLASS

| PATENT NO. | CLASS | PATENT FAMILY CLASSIFICATION CODES |
|----------------|-------|--|
| US 20080206562 | INCL | 428403000; 216055000; 428402000; 264005000; 264007000; 502100000; 502300000; 502159000; 502355000; 502350000 |
| | IPCI | B32B0015-02 [I,A]; C23F0001-00 [I,A]; B29B0009-00 [I,A]; B29B0009-16 [I,A]; B01J0031-06 [I,A]; B01J0021-04 [I,A]; B01J0021-08 [I,A]; B01J0023-34 [I,A]; B01J0023-16 [I,C*]; B01J0029-00 [I,A]; B01J0021-18 [I,A]; B01J0021-00 [I,C*]; B01J0027-06 [I,A]; B01J0023-42 [I,A]; B01J0023-44 [I,A]; B01J0023-50 [I,A]; B01J0023-52 [I,A]; B01J0023-48 [I,C*]; B01J0027-02 [I,A]; B01J0027-24 [I,A]; B01J0031-02 [I,A]; B01J0023-755 [I,A]; B01J0031-26 [I,A] |
| | NCL | 428/403.000; 216/055.000; 216/083.000; 264/005.000; 264/007.000; 428/402.000; 502/080.000; 502/087.000; 502/100.000; 502/150.000; 502/159.000; 502/167.000; 502/168.000; 502/171.000; 502/180.000; 502/181.000; 502/200.000; 502/216.000; 502/232.000; 502/300.000; 502/325.000; 502/337.000; 502/339.000; 502/340.000; 502/344.000; 502/345.000; 502/347.000; 502/349.000; 502/350.000; 502/355.000 |

AB The prepn. of elec.-conductive noble metal nanoparticle catalysts on catalyst supports such as alumina, silica, titania, clays, zeolites, or carbon black, is described.

ST gold **silver** palladium nanocatalyst support sol gel micelle ceramic

IT Solvents

(aprotic; prepn. of conductive supported noble metal nanoparticle

- catalysts)
- IT Polyethers, uses
RL: MOA (Modifier or additive use); USES (Uses)
(arom., alkyl-, **surfactants**; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Thiols, uses
RL: MOA (Modifier or additive use); USES (Uses)
(caps on catalyst nanoparticles; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Bentonite, processes
Carbon black, processes
Clays, processes
Diatomite
Silica gel, processes
Zeolites (synthetic), processes
RL: PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)
(catalyst supports; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Nanoparticles
(catalysts; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Alcohols, uses
RL: MOA (Modifier or additive use); USES (Uses)
(ethoxylated, **surfactants**; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Hydrocarbons, processes
RL: PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)
(fluoro, catalyst supports; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT **Surfactants**
(in coatings; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Electroluminescent devices
Molecular electronic devices
Optoelectronics
Secondary batteries
Semiconductor devices
Sensors
Solar cells
(nanocatalysts for; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Photolysis catalysts
(nanocatalysts; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Catalysts
Semiconductor materials
(nanoparticles; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT **Surfactants**
(**nonionic**; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Silsesquioxanes
RL: RGT (Reagent); RACT (Reactant or reagent)
(octyl- and hexyl-; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT Dyes
(org.-, functional mol.; prepn. of conductive supported noble metal nanoparticle catalysts)

STN Columbus

- IT Calcination
Catalyst supports
Etching
Reducing agents
(prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 7440-44-0, Carbon, processes
RL: PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)
(activated, catalyst supports; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 64-17-5, Ethanol, uses
RL: NUU (Other use, unclassified); USES (Uses)
(buffer soln.; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 49543-63-7, 4-(tert-Butyl)benzyl **mercaptan**
RL: MOA (Modifier or additive use); USES (Uses)
(cap on nanoparticles; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 1322-36-7, Dodecanethiol
RL: MOA (Modifier or additive use); USES (Uses)
(caps on catalyst nanoparticles; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 7440-02-0P, Nickel, preparation 7440-05-3P, Palladium, preparation
7440-06-4P, Platinum, preparation 7440-22-4P, **Silver**,
preparation 7440-50-8P, Copper, preparation 7440-57-5P, Gold,
preparation 12006-51-8P, AuCu
RL: CAT (Catalyst use); SPN (Synthetic preparation); PREP (Preparation);
USES (Uses)
(catalyst nanoparticles; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 1309-48-4, Magnesium oxide (MgO), processes 1314-23-4, Zirconia,
processes 1344-28-1, Aluminum oxide (Al₂O₃), processes 7631-86-9,
Silica, processes 7782-42-5, Graphite, processes 13463-67-7, Titania,
processes
RL: PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)
(catalyst supports; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 1306-38-3, Cerium oxide (CeO₂), uses 1313-13-9, Manganese oxide (MnO₂),
uses 1313-96-8, Niobium oxide (Nb₂O₅)
RL: MOA (Modifier or additive use); USES (Uses)
(coatings on colloidal silica; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 12638-19-6P
RL: CAT (Catalyst use); SPN (Synthetic preparation); PREP (Preparation);
USES (Uses)
(nanoparticles; prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 2966-50-9, **Silver** trifluoroacetate 14024-17-0, Iron acetyl
acetate 14024-61-4 14024-64-7 16902-59-3 17927-72-9 19443-16-4
19443-17-5 23894-00-0 23894-03-3 24772-51-8 27858-32-8, Titanium
diisopropoxide bis(ethyl acetoacetate) 62905-51-5 65574-21-2
65583-10-0 66197-44-2 82269-80-5 93918-06-0, Aluminum sec-butoxide
bis(ethyl acetoacetate) 98719-26-7 140190-96-1 144665-26-9
204522-78-1 299957-41-8 380240-62-0 1050499-47-2 1050499-48-3
1050499-49-4 1050499-50-7 1050499-51-8 1050499-52-9 1050499-53-0
1050499-54-1
RL: RCT (Reactant); RACT (Reactant or reagent)
(precursors; prepn. of conductive supported noble metal nanoparticle catalysts)

STN Columbus

- IT 1313-99-1, Nickel oxide, uses 1345-25-1, Ferrous oxide, uses
11104-61-3, Cobalt oxide
RL: MOA (Modifier or additive use); USES (Uses)
(prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 78-07-9, Ethyltriethoxysilane 78-10-4, Tetraethoxysilane 681-84-5,
Tetramethoxysilane 682-01-9, Tetrapropoxysilane 1185-55-3,
Methyltrimethoxysilane 1336-21-6, Ammonium hydroxide ((NH₄)(OH))
2031-67-6, Methyltriethoxysilane 4766-57-8, Tetrabutoxysilane
30232-12-3 192082-40-9, Mercaptoundecanoic acid
RL: RGT (Reagent); RACT (Reactant or reagent)
(prepn. of conductive supported noble metal nanoparticle catalysts)
- IT 1722-26-5, Triethylamine-borane 4856-95-5 7337-45-3,
tert-Butylamine-borane 13774-81-7, Ammonia-borane
RL: RGT (Reagent); RACT (Reactant or reagent)
(reducing agents; prepn. of conductive supported noble metal
nanoparticle catalysts)
- IT 67-66-3, Chloroform, uses 71-43-2, Benzene, uses 75-09-2,
Dichloromethane, uses 108-88-3, Toluene, uses 110-54-3, Hexane, uses
110-82-7, Cyclohexane, uses
RL: NUU (Other use, unclassified); USES (Uses)
(solvent; prepn. of conductive supported noble metal nanoparticle
catalysts)
- IT 14243-64-2
RL: PEP (Physical, engineering or chemical process); PROC (Process)
(substrates; prepn. of conductive supported noble metal nanoparticle
catalysts)
- IT 577-11-7, Sodium bis(2-ethylhexyl) sulfosuccinate 9002-89-5, Polyvinyl
alcohol 9002-92-0, Brij 30 9004-98-2, Brij 97 9036-19-5,
(Octylphenoxy)polyethoxyethanol 12441-09-7D, Sorbitan, ester derivs.
27251-32-7
RL: MOA (Modifier or additive use); USES (Uses)
(**surfactants**; prepn. of conductive supported noble metal
nanoparticle catalysts)

L18 ANSWER 2 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2007:415891 CAPLUS

DN 146:463862

ED Entered STN: 16 Apr 2007

TI Discoloration prevention of metals using organic ultra-thin films and
methods therefor

IN Liang, Chenghao; Yang, Changjiang; Huang, Naibao

PA Dalian Maritime University, Peop. Rep. China

SO Faming Zhuanli Shenqing Gongkai Shuomingshu, 10pp.

CODEN: CNXXEV

DT Patent

LA Chinese

CC 42-10 (Coatings, Inks, and Related Products)

Section cross-reference(s): 46, 56

FAN.CNT 1

| | PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
|------|------------------|------|----------|------------------|----------|
| PI | CN 1943882 | A | 20070411 | CN 2006-10134093 | 20061026 |
| PRAI | CN 2006-10134093 | | 20061026 | | |

CLASS

| PATENT NO. | CLASS | PATENT FAMILY CLASSIFICATION CODES |
|------------|-------|---|
| CN 1943882 | IPC1 | B05D0007-14 [I,A]; B05D0007-24 [I,A]; B05D0003-10 [I,A]; C23C0022-05 [I,A]; C07C0321-04 [I,A]; C07C0321-00 [I,C*] |

STN Columbus

IPCR B05D0007-14 [I,C]; B05D0007-14 [I,A]

OS MARPAT 146:463862

AB Film-forming solns. contain 0.001-1 mol/L alkyl thiols and 0.001-1 mol/L **surfactants**. Thus, a coating soln. on **Ag** contained stearyl thiol 15, polyethylene glycol nonylphenyl ether 7, hexadecyltrimethylammonium bromide 2, Pluronic 64 7 g/L.

ST metal discoloration prevention coating **surfactant** thiol; **silver** discoloration prevention coating **surfactant** thiol

IT **Surfactants**
(**anionic**; coating materials contg. thiols and **surfactants** for discoloration prevention of metals)

IT **Surfactants**
(cationic; coating materials contg. thiols and **surfactants** for discoloration prevention of metals)

IT Discoloration prevention
(coating materials contg. thiols and **surfactants** for discoloration prevention of metals)

IT Quaternary ammonium compounds, uses
Thiols, uses
RL: TEM (Technical or engineered material use); USES (Uses)
(coating materials contg. thiols and **surfactants** for discoloration prevention of metals)

IT Coating materials
(discoloration-resistant; coating materials contg. thiols and **surfactants** for discoloration prevention of metals)

IT 691397-13-4, Pluronic L 64
RL: TEM (Technical or engineered material use); USES (Uses)
(Pluronic L 64; coating materials contg. thiols and **surfactants** for discoloration prevention of metals)

IT 57-09-0, Hexadecyltrimethylammonium bromide **2885-00-9**, Stearylmercaptan 7440-22-4, **Silver**, uses 9016-45-9, Polyethylene glycol nonylphenyl ether
RL: TEM (Technical or engineered material use); USES (Uses)
(coating materials contg. thiols and **surfactants** for discoloration prevention of metals)

L18 ANSWER 3 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2007:150387 CAPLUS

DN 146:236227

ED Entered STN: 09 Feb 2007

TI Conductive adhesive composition comprising pressure sensitive adhesive and electrolyte

IN Menon, Vinod P.; Kumar, Kanta; Nelson, Carl T.; Rizzardi, Don A.

PA 3M Innovative Properties Company, USA

SO U.S. Pat. Appl. Publ., 20pp.
CODEN: USXXCO

DT Patent

LA English

INCL 600391000; 600392000; 252500000

CC 63-7 (Pharmaceuticals)

FAN.CNT 1

| | PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
|----|--|------|----------|-----------------|----------|
| PI | US 20070032719 | A1 | 20070208 | US 2005-197216 | 20050804 |
| | AU 2006278717 | A1 | 20070215 | AU 2006-278717 | 20060801 |
| | CA 2617273 | A1 | 20070215 | CA 2006-2617273 | 20060801 |
| | WO 2007019115 | A1 | 20070215 | WO 2006-US29794 | 20060801 |
| | W: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, | | | | |

STN Columbus

GE, GH, GM, HN, HR, HU, ID, IL, IN, IS, JP, KE, KG, KM, KN, KP,
 KR, KZ, LA, LC, LK, LR, LS, LT, LU, LV, LY, MA, MD, MG, MK, MN,
 MW, MX, MZ, NA, NG, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RS, RU,
 SC, SD, SE, SG, SK, SL, SM, SY, TJ, TM, TN, TR, TT, TZ, UA, UG,
 US, UZ, VC, VN, ZA, ZM, ZW
 RW: AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE,
 IS, IT, LT, LU, LV, MC, NL, PL, PT, RO, SE, SI, SK, TR, BF, BJ,
 CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG, BW, GH,
 GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW, AM, AZ, BY,
 KG, KZ, MD, RU, TJ, TM
 EP 1917318 A1 20080507 EP 2006-789019 20060801
 R: AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE,
 IS, IT, LI, LT, LU, LV, MC, NL, PL, PT, RO, SE, SI, SK, TR
 JP 2009503235 T 20090129 JP 2008-525088 20060801
 MX 2008001425 A 20080416 MX 2008-1425 20080129
 KR 2008040689 A 20080508 KR 2008-702725 20080201
 CN 101238189 A 20080806 CN 2006-80028822 20080204
 IN 2008CN00571 A 20081128 IN 2008-CN571 20080204
 PRAI US 2005-197216 A 20050804
 WO 2006-US29794 W 20060801
 CLASS
 PATENT NO. CLASS PATENT FAMILY CLASSIFICATION CODES

 US 20070032719 INCL 600391000; 600392000; 252500000
 IPCI A61B0005-04 [I,A]; H01B0001-12 [I,A]; H01B0001-00 [I,A]
 IPCR A61B0005-04 [I,C]; A61B0005-04 [I,A]; H01B0001-00
 [I,C]; H01B0001-00 [I,A]; H01B0001-12 [I,C];
 H01B0001-12 [I,A]
 NCL 600/391.000; 252/500.000; 600/392.000
 ECLA C09J009/02; A61B005/0408F; A61N001/04; C09J133/04+B4;
 C09J133/06+B2; H01B001/20; K61B; M08L; M08L; M08L
 AU 2006278717 IPCI C09J0009-00 [I,C]; C09J0009-02 [I,A]
 IPCR C09J0009-00 [I,C]; C09J0009-02 [I,A]
 ECLA C09J009/02; A61B005/0408F; A61N001/04; C09J133/04+B4;
 C09J133/06+B2; H01B001/20; K61B; M08L; M08L; M08L
 CA 2617273 IPCI A61B0005-0408 [I,A]; A61B0018-14 [I,A]; A61K0050-00
 [I,A]; A61N0001-04 [I,A]; C09J0009-02 [I,A];
 C09J0009-00 [I,C*]; C09J0011-06 [I,A]; C09J0011-02
 [I,C*]
 IPCR C09J0009-00 [I,C]; C09J0009-02 [I,A]; A61B0005-0408
 [I,C]; A61B0005-0408 [I,A]; A61B0018-14 [I,C];
 A61B0018-14 [I,A]; A61K0050-00 [I,C]; A61K0050-00
 [I,A]; A61N0001-04 [I,C]; A61N0001-04 [I,A];
 C09J0011-02 [I,C]; C09J0011-06 [I,A]
 WO 2007019115 IPCI C09J0009-02 [I,A]; C09J0009-00 [I,C*]
 IPCR C09J0009-00 [I,C]; C09J0009-02 [I,A]
 ECLA C09J009/02; A61B005/0408F; A61N001/04; C09J133/04+B4;
 C09J133/06+B2; H01B001/20; K61B; M08L; M08L; M08L
 EP 1917318 IPCI C09J0009-02 [I,A]; C09J0009-00 [I,C*]
 IPCR C09J0009-00 [I,C]; C09J0009-02 [I,A]
 JP 2009503235 IPCI C09J0201-00 [I,A]; C09J0009-02 [I,A]; C09J0009-00
 [I,C*]; C09J0004-02 [I,A]; A61L0024-00 [I,A];
 A61N0001-04 [I,A]
 FTERM 4C053/BB04; 4C053/BB06; 4C053/BB07; 4C053/BB23;
 4C053/BB35; 4C053/BB36; 4C081/AA10; 4C081/AA12;
 4C081/AC04; 4C081/BB03; 4C081/BB04; 4C081/CA061;
 4C081/CA071; 4C081/CA081; 4C081/CA101; 4C081/CA16;
 4C081/CA181; 4C081/CA211; 4C081/CA281; 4C081/CE07;
 4C081/CE09; 4C081/CE10; 4C081/DA02; 4C081/DA12;
 4C081/DB07; 4C081/DC03; 4C081/DC04; 4J040/FA041;

STN Columbus

4J040/FA081; 4J040/FA091; 4J040/FA101; 4J040/FA131;
4J040/FA141; 4J040/FA161; 4J040/FA281; 4J040/FA291;
4J040/HB04; 4J040/HB10; 4J040/HB11; 4J040/HB14;
4J040/HC01; 4J040/HD02; 4J040/HD18; 4J040/HD23;
4J040/JA03; 4J040/JB09; 4J040/KA12; 4J040/KA13;
4J040/KA32; 4J040/KA38; 4J040/KA39; 4J040/MA14;
4J040/NA02

MX 2008001425 IPCI C09J0009-02 [I,A]; C09J0009-00 [I,C*]
KR 2008040689 IPCI C09J0009-02 [I,A]; C09J0009-00 [I,C*]
CN 101238189 IPCI C09J0009-02 [I,A]; C09J0009-00 [I,C*]
IN 2008CN00571 IPCI C09J0009-02 [ICM,7]; C09J0009-00 [ICM,7,C*]

OS MARPAT 146:236227

AB A conductive adhesive compn. is provided and articles that include the adhesive compn. as a component thereof. The conductive adhesive compn. comprises: (a) pressure sensitive adhesive; (b) electrolyte comprising water sol. or water dispersible org. chloride; and (c) humectant. In some embodiments, the conductive adhesive compn. is a bicontinuous compn. comprising an aq. phase and an oil phase, and the bicontinuous compn. may be derived from a polymerizable microemulsion compn., the microemulsion compn. comprising: an aq. phase comprising one or more hydrophilic monomers or oligomers and/or one or more amphiphilic monomers or oligomers in water, the water-sol. or water-dispersible org. chloride, **surfactant** and humectant; and an oil phase comprising one or more hydrophobic monomers or oligomers. Biomedical articles such as biomedical electrodes, may incorporate the foregoing adhesive as a component. For example, adhesive precursor comprised of acrylic acid 15 g, 2-hydroxyethyl methacrylate 20 g, tetrakis(hydroxymethyl)phosphonium chloride 11 g, 1,3-butylene glycol 25 g, glycerol 10 g, water 19 g, Irgacure 2959 0.55 g and polyethylene glycol diacrylate 0.15 g. The precursor was coated using a knife coater onto a release liner as substrate. The knife was set so that a 25 mil (0.64 mm) thick coating was obtained. Polymn. was induced in the coated microemulsion by exposure to UV radiation. A total dose of 1800 mJ/cm² was applied over approx. 7 min, forming a conductive, bicontinuous adhesive. This conductive adhesive had an excellent adhesion to human skin.

ST polymer acrylate electrolyte chloride conductive adhesive

IT Polyurethanes, biological studies

RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)
(acrylates; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)

IT Electric conductors

(adhesive; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)

IT Fats and Glyceridic oils, biological studies

RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)
(almond, amidopropalkonium chloride; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)

IT **Surfactants**

(**anionic**; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)

IT Fats and Glyceridic oils, biological studies

RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)
(avocado, amidopropalkonium chloride; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)

IT **Surfactants**

(**cationic**; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)

IT Onium compounds

RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)
(chloride; conductive adhesive compn. comprising pressure sensitive

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- adhesive and electrolyte)
- IT Quaternary ammonium compounds, biological studies
 - RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)
 - (chlorides; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Fatty acids, biological studies
 - RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)
 - (coco, trimethylammonium chloride; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Chain transfer agents
 - Crosslinking agents
 - Electrodes
 - Electrolytes
 - Human
 - Humectants
 - Hydrogels
 - Surfactants**
 - (conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Alcohols, uses
 - Thiols, uses
 - RL: NUU (Other use, unclassified); USES (Uses)
 - (conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Acrylic polymers, biological studies
 - RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)
 - (conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Sulfonium compounds
 - RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)
 - (conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Adhesives
 - (conductive; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Soybean oil
 - RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)
 - (dimethylammonium chloride; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT **Surfactants**
 - (**nonionic**; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Chlorides, biological studies
 - RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)
 - (org.; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Adhesives
 - (pressure-sensitive; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT Fatty acids, biological studies
 - RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)
 - (tallow, bishydroxyethyl/dime quaternary ammonium compds.; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT 558-13-4, Carbon tetrabromide 25103-09-7, Isooctyl **thioglycolate**, uses
 - RL: NUU (Other use, unclassified); USES (Uses)
 - (conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)
- IT 1070-70-8, 1,4-Butanediol diacrylate 1321-74-0, Divinylbenzene, reactions 10526-04-2, 1,8-Octanediol diacrylate 13048-33-4,

STN Columbus

1,6-Hexanediol diacrylate

RL: RCT (Reactant); RACT (Reactant or reagent)

(conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)

IT 56-34-8, Tetraethylammonium chloride 56-37-1, Benzyltriethylammonium chloride 56-81-5, Glycerin, biological studies 56-93-9, Benzyltrimethylammonium chloride 57-55-6, Propylene glycol, biological studies 67-48-1 77-99-6, Trimethylolpropane 88-12-0D, polymer 107-21-1, Ethylene glycol, biological studies 107-88-0, 1,3-Butanediol 110-63-4, 1,4-Butanediol, biological studies 112-00-5, Dodecyltrimethylammonium chloride 112-02-7, Hexadecyltrimethylammonium chloride 112-03-8, Octadecyltrimethylammonium chloride 124-64-1, Tetrakis(hydroxymethyl)phosphonium chloride 139-08-2, Tetradecyldimethylbenzylammonium chloride 593-81-7D, Trimethylammonium chloride, coco fatty acid derivs. 7173-51-5 9004-98-2, Brij 98 9042-76-6 17301-53-0, Behenyltrimethylammonium chloride 24567-53-1, Phosphonium chloride 25265-71-8, Dipropylene glycol 26570-48-9, Polyethylene oxide diacrylate 26597-36-4 32862-91-2, Oxonium chloride 60182-11-8, Polyethylene glycol acrylate 93507-51-8 106797-53-9, IRGACURE 2959 123776-56-7 145687-02-1, Pemulen TR 2 463965-14-2 923929-97-9 923929-99-1 924299-17-2, Hetoxol OL 35

RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)

(conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)

IT 7783-90-6, **Silver** chloride, biological studies

RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)

(conductive ink soln.; conductive adhesive compn. comprising pressure sensitive adhesive and electrolyte)

L18 ANSWER 4 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2005:1062684 CAPLUS

DN 143:351549

ED Entered STN: 05 Oct 2005

TI Water-based sulfur-containing composition chemical mechanical polishing of nonferrous metals

IN Johns, Peter Gamon; Harrison, Clare Elizabeth

PA Middlesex Silver Co. Limited, UK

SO Brit. UK Pat. Appl., 29 pp.

CODEN: BAXXDU

DT Patent

LA English

IC ICM C23F011-16

ICS C23F011-00

CC 57-7 (Ceramics)

Section cross-reference(s): 56

FAN.CNT 1

| | PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
|----|--|------|----------|-----------------|----------|
| | ----- | ---- | ----- | ----- | ----- |
| PI | GB 2412666 | A | 20051005 | GB 2004-7163 | 20040330 |
| | GB 2412666 | B | 20081008 | | |
| | AU 2005229275 | A1 | 20051013 | AU 2005-229275 | 20050324 |
| | CA 2559989 | A1 | 20051013 | CA 2005-2559989 | 20050324 |
| | WO 2005095675 | A1 | 20051013 | WO 2005-GB50043 | 20050324 |
| | W: | | | | |
| | AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, | | | | |
| | CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, | | | | |
| | GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, | | | | |
| | LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, | | | | |
| | NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SM, | | | | |
| | SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW | | | | |

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RW: BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW, AM,
 AZ, BY, KG, KZ, MD, RU, TJ, TM, AT, BE, BG, CH, CY, CZ, DE, DK,
 EE, ES, FI, FR, GB, GR, HU, IE, IS, IT, LT, LU, MC, NL, PL, PT,
 RO, SE, SI, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML,
 MR, NE, SN, TD, TG

EP 1730325 A1 20061213 EP 2005-718135 20050324
 R: AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE,
 IS, IT, LI, LT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR
 CN 1946878 A 20070411 CN 2005-80013434 20050324
 JP 2007537354 T 20071220 JP 2007-505641 20050324
 IN 2006DN05356 A 20070713 IN 2006-DN5356 20060915
 MX 2006010964 A 20061116 MX 2006-10964 20060925
 US 20070277906 A1 20071206 US 2007-594477 20070702
 PRAI GB 2004-7163 A 20040330
 WO 2005-GB50043 W 20050324

CLASS

| PATENT NO. | CLASS | PATENT FAMILY CLASSIFICATION CODES |
|---------------|-------|---|
| GB 2412666 | ICM | C23F011-16 |
| | ICS | C23F011-00 |
| | IPCI | C23F0011-10 [I,C]; C23F0011-16 [I,A]; C23F0011-00 [I,C]; C23F0011-00 [I,A] |
| | IPCR | C09G0001-00 [I,C*]; C09G0001-02 [I,A]; C11D0003-00 [I,C*]; C11D0003-00 [I,A]; C11D0003-34 [I,C*]; C11D0003-34 [I,A]; C11D0011-00 [I,C*]; C11D0011-00 [I,A] |
| | ECLA | C23F011/16; C23F011/16B |
| AU 2005229275 | IPCI | C11D0003-00 [I,C*]; C09G0001-00 [I,C*]; C11D0003-34 [I,C*]; C11D0011-00 [I,C*]; C23F0011-10 [I,C*]; C11D0003-00 [I,A]; C09G0001-02 [I,A]; C11D0003-34 [I,A]; C11D0011-00 [I,A]; C23F0011-16 [I,A] |
| | IPCR | C11D0003-00 [I,C*]; C11D0003-00 [I,A]; C09G0001-00 [I,C*]; C09G0001-02 [I,A]; C11D0003-34 [I,C*]; C11D0003-34 [I,A]; C11D0011-00 [I,C*]; C11D0011-00 [I,A]; C23F0011-10 [I,C*]; C23F0011-16 [I,A] |
| | ECLA | C23F011/16; C23F011/16B |
| CA 2559989 | IPCI | C09G0001-02 [I,A]; C09G0001-00 [I,C*]; C11D0003-00 [I,A]; C11D0003-34 [I,A]; C11D0011-00 [I,A]; C23F0011-16 [I,A]; C23F0011-10 [I,C*] |
| | IPCR | C23F0011-10 [I,C]; C23F0011-16 [I,A]; C09G0001-00 [I,C]; C09G0001-02 [I,A]; C11D0003-00 [I,C]; C11D0003-00 [I,A]; C11D0003-34 [I,C]; C11D0003-34 [I,A]; C11D0011-00 [I,C]; C11D0011-00 [I,A] |
| | ECLA | C23F011/16; C23F011/16B |
| WO 2005095675 | IPCI | C23F0011-16 [ICM, 7]; C23F0011-10 [ICM, 7,C*]; C11D0003-00 [ICS, 7]; C11D0003-34 [ICS, 7]; C11D0011-00 [ICS, 7]; C09G0001-02 [ICS, 7]; C09G0001-00 [ICS, 7,C*] |
| | IPCR | C09G0001-00 [I,C*]; C09G0001-02 [I,A]; C11D0003-00 [I,C*]; C11D0003-00 [I,A]; C11D0003-34 [I,C*]; C11D0003-34 [I,A]; C11D0011-00 [I,C*]; C11D0011-00 [I,A]; C23F0011-10 [I,C*]; C23F0011-16 [I,A] |
| | ECLA | C23F011/16; C23F011/16B |
| EP 1730325 | IPCI | C23F0011-16 [I,A]; C23F0011-10 [I,C*]; C11D0003-00 [I,A]; C11D0003-34 [I,A]; C11D0011-00 [I,A]; C09G0001-02 [I,A]; C09G0001-00 [I,C*] |
| | IPCR | C23F0011-10 [I,C]; C23F0011-16 [I,A]; C09G0001-00 [I,C]; C09G0001-02 [I,A]; C11D0003-00 [I,C]; C11D0003-00 [I,A]; C11D0003-34 [I,C]; C11D0003-34 [I,A]; C11D0011-00 [I,C]; C11D0011-00 [I,A] |
| | ECLA | C23F011/16; C23F011/16B |

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CN 1946878 IPCI C23F0011-16 [I,A]; C23F0011-10 [I,C*]; C11D0003-00 [I,A]; C11D0003-34 [I,A]; C11D0011-00 [I,A]; C09G0001-02 [I,A]; C09G0001-00 [I,C*]
 IPCR C23F0011-10 [I,C]; C23F0011-16 [I,A]; C09G0001-00 [I,C*]; C09G0001-02 [I,A]; C11D0003-00 [I,C*]; C11D0003-00 [I,A]; C11D0003-34 [I,C*]; C11D0003-34 [I,A]; C11D0011-00 [I,C*]; C11D0011-00 [I,A]
 ECLA C23F011/16; C23F011/16B
 JP 2007537354 IPCI C23C0022-58 [I,A]; C11D0003-34 [I,A]; C23C0022-68 [I,A]; C23C0022-05 [I,C*]; C11D0003-20 [I,A]; C11D0001-52 [I,A]; C11D0001-38 [I,C*]; C11D0001-72 [I,A]; C11D0001-79 [I,A]; C11D0001-755 [I,A]; C11D0001-75 [I,A]; C11D0001-722 [I,A]; C11D0001-14 [I,A]; C11D0001-02 [I,C*]; C11D0001-90 [I,A]; C11D0001-88 [I,C*]; C11D0003-04 [I,A]; C11D0001-68 [I,A]; C09K0003-14 [I,A]
 IPCR C23C0022-05 [I,C]; C23C0022-58 [I,A]; C09G0001-00 [I,C*]; C09G0001-02 [I,A]; C09K0003-14 [I,C]; C09K0003-14 [I,A]; C11D0001-02 [I,C]; C11D0001-14 [I,A]; C11D0001-38 [I,C]; C11D0001-52 [I,A]; C11D0001-68 [I,C]; C11D0001-68 [I,A]; C11D0001-72 [I,C]; C11D0001-722 [I,C]; C11D0001-722 [I,A]; C11D0001-75 [I,C]; C11D0001-75 [I,A]; C11D0001-755 [I,C]; C11D0001-755 [I,A]; C11D0001-79 [I,C]; C11D0001-79 [I,A]; C11D0001-88 [I,C]; C11D0001-90 [I,A]; C11D0003-00 [I,C*]; C11D0003-00 [I,A]; C11D0003-04 [I,C]; C11D0003-04 [I,A]; C11D0003-20 [I,C]; C11D0003-20 [I,A]; C11D0003-34 [I,C]; C11D0003-34 [I,A]; C11D0011-00 [I,C*]; C11D0011-00 [I,A]; C23C0022-68 [I,A]; C23F0011-10 [I,C*]; C23F0011-16 [I,A]
 FTERM 4H003/AB27; 4H003/AC02; 4H003/AC10; 4H003/AC13; 4H003/AD04; 4H003/BA12; 4H003/DA15; 4H003/EA12; 4H003/EA19; 4H003/EB05; 4H003/EB18; 4H003/EB21; 4H003/ED02; 4H003/FA05; 4K026/AA01; 4K026/AA06; 4K026/CA15; 4K026/CA37; 4K026/DA02; 4K026/DA03
 IN 2006DN05356 IPCI C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C*]
 MX 2006010964 IPCI C09G0001-02 [ICM,7]; C09G0001-00 [ICM,7,C*]; C11D0011-00 [ICS,7]; C11D0003-00 [ICS,7]; C11D0003-34 [ICS,7]; C23F0011-16 [ICS,7]; C23F0011-10 [ICS,7,C*]
 US 20070277906 IPCI C23F0011-16 [I,A]; C23F0011-10 [I,C*]; C09G0001-02 [I,A]; C09G0001-00 [I,C*]; C11D0011-00 [I,A]; C11D0003-00 [I,A]; C11D0003-34 [I,A]
 NCL 148/022.000
 OS MARPAT 143:351549
 AB A compn. and assocd. method of manuf. of a water based compn. comprising a treatment agent selected from an alkanethiol, alkyl thioglycollate, and dialkyl sulfide or dialkyl disulfide. The compn. also includes at least one of an amphoteric, **non-ionic** or cationic **surfactant**, where the treatment agent is directly dissolved or dispersed the water contg. the amphoteric, **non-ionic** or cationic **surfactant**. The compn. is particularly useful for the treatment of **Ag**-Cu-Ge alloy, copper, brass, and nickel. A solid polishing medium can also be included in the compn., for example, silica or pptd. chalk, alumina, or silica.
 ST chalk alumina silica alkanethiol thioglycollate chem mech polishing copper
 IT Thiols, processes
 RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)
 (alkanethiol; water-based sulfur-contg. compn. chem. mech. polishing of

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- metals)
- IT Disulfides
RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)
(alkyl; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT Chalk
Diatomite
RL: TEM (Technical or engineered material use); USES (Uses)
(as abrasive; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT **Surfactants**
(cationic; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT Polishing
(chem.-mech.; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT Polishing materials
(paste; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT Thioethers
RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)
(water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT 1344-28-1, Alumina, uses
RL: TEM (Technical or engineered material use); USES (Uses)
(abrasive; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT 9004-82-4, Sodium laureth sulfate
RL: MOA (Modifier or additive use); USES (Uses)
(**anionic surfactant**; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT 7631-86-9, Silica, uses
RL: TEM (Technical or engineered material use); USES (Uses)
(as abrasive; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT 36574-66-0D, N-coco acyl derivs.
RL: MOA (Modifier or additive use); USES (Uses)
(cocamidopropyl betaine, **surfactant**; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT 7440-02-0, Nickel, processes 7440-50-8, Copper, processes 11144-43-7
12597-71-6, Brass, processes 74969-69-0
RL: PEP (Physical, engineering or chemical process); PYP (Physical process); PROC (Process)
(polished substrate; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT 62-56-6, Thiourea, uses **2885-00-9, Octadecyl mercaptan**
RL: TEM (Technical or engineered material use); USES (Uses)
(polishing compn. component; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT **2917-26-2, Hexadecyl mercaptan**
RL: MOA (Modifier or additive use); USES (Uses)
(**surfactant**; water-based sulfur-contg. compn. chem. mech. polishing of metals)
- IT 68-11-1D, alkyl esters
RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)

STN Columbus

(water-based sulfur-contg. compn. chem. mech. polishing of metals)

RE.CNT 6 THERE ARE 6 CITED REFERENCES AVAILABLE FOR THIS RECORD

RE

- (1) Anon; EP 0492487 A1 CAPLUS
- (2) Anon; GB 0956927 A
- (3) Anon; GB 1117510 A
- (4) Anon; US 3503883 A
- (5) Anon; US 3518098 A
- (6) Anon; US 5650385 A CAPLUS

L18 ANSWER 5 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2005:622423 CAPLUS

DN 143:295501

ED Entered STN: 19 Jul 2005

TI Single Etch Patterning of Stacked **Silver** and Molybdenum Alloy Layers on Glass Using Microcontact Wave Printing

AU Burdinski, Dirk; Brans, Harold J. A.; Decre, Michel M. J.

CS Philips Research, Eindhoven, 5656 AA, Neth.

SO Journal of the American Chemical Society (2005), 127(31), 10786-10787
CODEN: JACSAT; ISSN: 0002-7863

PB American Chemical Society

DT Journal

LA English

CC 74-13 (Radiation Chemistry, Photochemistry, and Photographic and Other Reprographic Processes)

Section cross-reference(s): 56

AB Stacked thin layers of **silver** alloy (AgPdCu) and MoCr layers on 10

× 15 cm² glass substrates were patterned by microcontact wave printing and etching. Patterns of etch-resistant **octadecanethiol** self-assembled monolayers (SAMs) were wave printed with regular backplane stabilized PDMS stamps. Pattern development was achieved by etching both metal layers in a single step, employing a nitric acid-based etching bath. Trifluoroacetic acid and a nitrite salt were identified as essential bath components for a homogeneous etching process. Etch defects could be eliminated by the addn. of a decanesulfonate, which stabilizes the SAM resist via a defect healing mechanism.

ST etching **silver** molybdenum alloy electrode display

IT Liquid crystal displays

(active matrix; single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing as electrodes for)

IT **Surfactants**

(**anionic**; single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)

IT Lithography

(microcontact printing; single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)

IT Autocatalysis

Electrodes

Etching

Glass substrates

Self-assembled monolayers

(single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)

IT 64-19-7, Acetic acid, processes 76-05-1, Trifluoroacetic acid, processes
7632-00-0, Sodium nitrite 7664-38-2, Phosphoric acid, processes
7697-37-2, Nitric acid, processes

STN Columbus

RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); PROC (Process)
(etchant; single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)

IT 2885-00-9, 1-Octadecanethiol

RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PROC (Process); USES (Uses)

(ink, self-assembled monolayer; single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)

IT 188820-19-1 317855-00-8

RL: CPS (Chemical process); DEV (Device component use); PEP (Physical, engineering or chemical process); PROC (Process); USES (Uses)

(single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)

IT 13419-61-9, Sodium decane sulfonate

RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); PROC (Process)

(**surfactant** for etching soln.; single etch patterning of stacked **silver** and molybdenum alloy layers on glass using microcontact wave printing)

RE.CNT 31 THERE ARE 31 CITED REFERENCES AVAILABLE FOR THIS RECORD
RE

- (1) Addison, C; Chem Rev 1980, V80, P21 CAPLUS
- (2) Balbaud, F; Corros Sci 2000, V42, P1685 CAPLUS
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L18 ANSWER 6 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2004:847649 CAPLUS

DN 141:353637

STN Columbus

ED Entered STN: 15 Oct 2004
 TI Pretreatment of **Ag**-alloy surface with organosulfur compounds for
 tarnishing prevention
 IN Johns, Peter Gammon; Harrison, Clare Elizabeth
 PA Middlesex Silver Co. Limited, UK
 SO PCT Int. Appl., 43 pp.
 CODEN: PIXXD2
 DT Patent
 LA English
 IC ICM C23F011-16
 CC 56-6 (Nonferrous Metals and Alloys)
 FAN.CNT 1

| | PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
|------|---|------|----------|------------------|----------|
| PI | WO 2004087996 | A1 | 20041014 | WO 2004-GB1373 | 20040330 |
| | W: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, VZ, VN, YU, ZA, ZM, ZW | | | | |
| | RW: BW, GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW, AM, AZ, BY, KG, KZ, MD, RU, TJ, TM, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG | | | | |
| | AU 2004225693 | A1 | 20041014 | AU 2004-225693 | 20040330 |
| | CA 2520807 | A1 | 20041014 | CA 2004-2520807 | 20040330 |
| | EP 1611267 | A1 | 20060104 | EP 2004-724313 | 20040330 |
| | R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO, MK, CY, AL, TR, BG, CZ, EE, HU, PL, SK | | | | |
| | CN 1780937 | A | 20060531 | CN 2004-80011375 | 20040330 |
| | JP 2006523266 | T | 20061012 | JP 2006-506057 | 20040330 |
| | IN 2005DN04346 | A | 20070831 | IN 2005-DN4346 | 20050926 |
| | MX 2005010452 | A | 20060510 | MX 2005-10452 | 20050928 |
| | US 20070039665 | A1 | 20070222 | US 2005-551476 | 20050929 |
| PRAI | GB 2003-7290 | A | 20030331 | | |
| | WO 2004-GB1373 | W | 20040330 | | |

CLASS

| PATENT NO. | CLASS | PATENT FAMILY CLASSIFICATION CODES |
|---------------|-------|--|
| WO 2004087996 | ICM | C23F011-16 |
| | IPCI | C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C*] |
| | IPCR | C23F0011-10 [I,C*]; C23F0011-16 [I,A] |
| | ECLA | C23F011/16; C23F011/16B |
| AU 2004225693 | IPCI | C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C*] |
| | IPCR | C23F0011-10 [I,C*]; C23F0011-16 [I,A] |
| | ECLA | C23F011/16; C23F011/16B |
| CA 2520807 | IPCI | C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C*] |
| | IPCR | C23F0011-10 [I,C*]; C23F0011-16 [I,A] |
| | ECLA | C23F011/16; C23F011/16B |
| EP 1611267 | IPCI | C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C*] |
| | IPCR | C23F0011-10 [I,C*]; C23F0011-16 [I,A] |
| | ECLA | C23F011/16; C23F011/16B |
| CN 1780937 | IPCI | C23F0011-16 [I,A]; C23F0011-10 [I,C*] |
| | ECLA | C23F011/16; C23F011/16B |
| JP 2006523266 | IPCI | C23F0011-00 [I,A]; C22C0005-06 [I,A]; C22C0005-08 [I,A] |
| | IPCR | C23F0011-00 [I,C]; C23F0011-00 [I,A]; C22C0005-06 [I,C]; C22C0005-06 [I,A]; C22C0005-08 [I,A]; C23F0011-10 [I,C*]; C23F0011-16 [I,A] |

STN Columbus

FTERM 4K062/AA01; 4K062/BB21; 4K062/BC22; 4K062/FA16
 IN 2005DN04346 IPCI C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C*]
 MX 2005010452 IPCI C23F0011-16 [ICM,7]; C23F0011-10 [ICM,7,C*]
 ECLA C23F011/16; C23F011/16B
 US 20070039665 IPCI C23G0001-00 [I,A]; C23C0022-58 [I,A]; C23C0022-05
 [I,C*]
 NCL 148/271.000; 134/002.000

AB The **Ag** alloys contg. minor Ge (esp. **Ag**-Cu-Ge alloys) to decrease the fire stain discoloration are pretreated on the surface with an alkanethiol, alkyl thioglycollate, dialkyl sulfide, or dialkyl disulfide to prevent tarnishing. The treatment with organosulfur compds. is suitable for manufd. **Ag**-alloy articles to prevent tarnished appearance during transit and the subsequent extended display without special packaging. The **Ag**-alloy surface is optionally treated with aq. soln. contg. an alkanethiol, alkyl thioglycollate, dialkyl sulfide, or dialkyl disulfide, as well as a mixt. of **anionic surfactant** and amphoteric or **nonionic surfactant** to solubilize the treatment agent. The typical ternary alloy contains **Ag** 80-96, Cu 1-19.9, and Ge 0.1-5%.

ST **silver** copper germanium alloy tarnishing prevention organosulfur

IT **Surfactants**
 (**anionic**, in tarnishing prevention; **Ag**-alloy surface treated with organosulfur compds. for tarnishing prevention)

IT **Surfactants**
 (in tarnishing prevention; **Ag**-alloy surface treated with organosulfur compds. for tarnishing prevention)

IT **Surfactants**
 (**nonionic**, in tarnishing prevention; **Ag**-alloy surface treated with organosulfur compds. for tarnishing prevention)

IT Tarnishing
 (prevention of; **Ag**-alloy surface treated with organosulfur compds. for tarnishing prevention)

IT Thioethers
 Thiols, uses
 RL: TEM (Technical or engineered material use); USES (Uses)
 (tarnishing prevention by; **Ag**-alloy surface treated with organosulfur compds. for tarnishing prevention)

IT 7440-56-4, Germanium, uses
 RL: MOA (Modifier or additive use); USES (Uses)
 (**Ag** alloys contg., tarnishing prevention on; **Ag**-alloy surface treated with organosulfur compds. for tarnishing prevention)

IT 106-94-5, n-Propyl bromide
 RL: TEM (Technical or engineered material use); USES (Uses)
 (solvent, in tarnishing prevention; **Ag**-alloy surface treated with organosulfur compds. for tarnishing prevention)

IT 2885-00-9, Octadecyl **mercaptan** 2917-26-2, Cetyl **mercaptan**
 RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); PROC (Process)
 (tarnishing prevention by; **Ag**-alloy surface treated with organosulfur compds. for tarnishing prevention)

IT 39282-03-6, Sterling **silver** 103221-24-5 476614-10-5 476614-12-7 476614-13-8
 RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); PROC (Process)
 (tarnishing prevention on; **Ag**-alloy surface treated with organosulfur compds. for tarnishing prevention)

IT 9080-17-5, Ammonium polysulfide
 RL: CPS (Chemical process); PEP (Physical, engineering or chemical process); PROC (Process)

STN Columbus

(test soln. with, for tarnishing; **Ag**-alloy surface treated
with organosulfur compds. for tarnishing prevention)

RE.CNT 9 THERE ARE 9 CITED REFERENCES AVAILABLE FOR THIS RECORD
RE

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L18 ANSWER 7 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2003:851241 CAPLUS

DN 139:330251

ED Entered STN: 30 Oct 2003

TI **Silver** (carboxylate-n-alkyl thiolate) particles for photothermographic
of thermographic imaging

IN Ghyzel, Peter J.; Lelental, Mark; Dickinson, David A.; Pitt, Alan R.;
Wear, Trevor J.

PA Eastman Kodak Company, USA

SO U.S., 14 pp.

CODEN: USXXAM

DT Patent

LA English

IC ICM G03C001-498

INCL 430619000; 430611000; 430620000; 430631000

CC 74-2 (Radiation Chemistry, Photochemistry, and Photographic and Other
Reprographic Processes)

FAN.CNT 1

| | PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
|------|--|------|----------|-----------------|----------|
| PI | US 6638708 | B1 | 20031028 | US 2002-200417 | 20020722 |
| | EP 1385047 | A1 | 20040128 | EP 2003-77179 | 20030710 |
| | R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO, MK, CY, AL, TR, BG, CZ, EE, HU, SK | | | | |
| | JP 2004054276 | A | 20040219 | JP 2003-199297 | 20030718 |
| PRAI | US 2002-200417 | A | 20020722 | | |

CLASS

| PATENT NO. | CLASS | PATENT FAMILY CLASSIFICATION CODES |
|---------------|-------|--|
| US 6638708 | ICM | G03C001-498 |
| | INCL | 430619000; 430611000; 430620000; 430631000 |
| | IPCI | G03C0001-498 [ICM, 7] |
| | IPCR | B41M0005-30 [I,C*]; B41M0005-323 [I,A]; G03C0001-498 [I,C*]; G03C0001-498 [I,A] |
| | NCL | 430/619.000; 430/611.000; 430/620.000; 430/631.000 |
| | ECLA | G03C001/498B; G03C001/498E1 |
| EP 1385047 | IPCI | G03C0001-498 [ICM, 7] |
| | IPCR | B41M0005-30 [I,C*]; B41M0005-323 [I,A]; G03C0001-498 [I,C*]; G03C0001-498 [I,A] |
| | ECLA | G03C001/498B; G03C001/498E1 |
| JP 2004054276 | IPCI | G03C0001-498 [ICM, 7]; B41M0005-30 [ICS, 7] |
| | IPCR | G03C0001-498 [I,A]; G03C0001-498 [I,C*] |
| | FTERM | 2H026/AA07; 2H026/BB46; 2H123/AB00; 2H123/AB03; 2H123/AB25; 2H123/AB28; 2H123/BC00; 2H123/BC12; 2H123/CB00; 2H123/CB03 |

STN Columbus

AB The present disclosure relates to dispersions of **silver**
(carboxylate-n-alkyl thiolate). The carboxylates are typically **silver**
salts of long chain fatty acids and the n-alkyl thiolate is preferably
1-dodecanethiol. These **silver** (carboxylate-n-alkyl thiolate) particles
can be used to formulate imaging forming compns. that are useful in aq.
thermog. or photothermog. imaging elements.

ST photog emulsion **silver** carboxylate alkyl thiolate particle photothermog

IT Photographic emulsions
(heat-developable; **silver** (carboxylate-n-alkyl thiolate)
particles for photothermog. of thermog. imaging)

IT **Surfactants**
(**nonionic**; **silver** (carboxylate-n-alkyl thiolate)
particles for photothermog. of thermog. imaging)

IT Nanoparticles
(**silver** (carboxylate-n-alkyl thiolate) particles for
photothermog. of thermog. imaging)

IT 111-31-9, 1-Hexanethiol 112-55-0, 1-Dodecanethiol 112-85-6, Behenic
acid **2885-00-9**, 1-Octadecanethiol

RL: TEM (Technical or engineered material use); USES (Uses)
(**silver** (carboxylate-n-alkyl thiolate) particles for
photothermog. of thermog. imaging)

RE.CNT 5 THERE ARE 5 CITED REFERENCES AVAILABLE FOR THIS RECORD

RE

(1) Anon; EP 0803764 A1 2001 CAPLUS

(2) Goffe; US 3666477 A 1972 CAPLUS

(3) Lelental; US 6391537 B2 2002 CAPLUS

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Silver n-Octadecanethiolate Layered Materials P2266

(5) Voicu, R; Thermal Behavior of a Self-Assembled Silver n-Dodecanethiolate
Layered Material Monitored by DSC P2642

L18 ANSWER 8 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2003:798402 CAPLUS

DN 139:311931

ED Entered STN: 12 Oct 2003

TI Metal coating of hair fibers for cosmetics

IN Vic, Gabin; Livoreil, Aude; Giroud, Franck

PA L'oreal, Fr.

SO Fr. Demande, 18 pp.
CODEN: FRXXBL

DT Patent

LA French

IC ICM A61K007-075

CC 62-3 (Essential Oils and Cosmetics)

FAN.CNT 1

| | PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
|----|--|------|----------|-----------------|----------|
| | ----- | ---- | ----- | ----- | ----- |
| PI | FR 2838050 | A1 | 20031010 | FR 2002-4352 | 20020408 |
| | FR 2838050 | B1 | 20060714 | | |
| | CN 1449737 | A | 20031022 | CN 2003-108449 | 20030331 |
| | CN 1213719 | C | 20050810 | | |
| | BR 2003000873 | A | 20040817 | BR 2003-873 | 20030403 |
| | EP 1352630 | A2 | 20031015 | EP 2003-290860 | 20030407 |
| | EP 1352630 | A3 | 20040324 | | |
| | EP 1352630 | B1 | 20060301 | | |
| | R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO, MK, CY, AL, TR, BG, CZ, EE, HU, SK | | | | |
| | US 20030223944 | A1 | 20031204 | US 2003-407911 | 20030407 |
| | JP 2003300840 | A | 20031021 | JP 2003-104420 | 20030408 |

STN Columbus

JP 3759120
 PRAI FR 2002-4352
 US 2002-372455P

B2 20060322
 A 20020408
 P 20020416

CLASS

| PATENT NO. | CLASS | PATENT FAMILY CLASSIFICATION CODES |
|---------------|-------|---|
| FR 2838050 | ICM | A61K007-075 |
| | IPCI | A61K0007-075 [ICM, 7] |
| | IPCR | A61K0008-00 [I,C*]; A61K0008-00 [I,A]; A61K0008-18 [I,C*]; A61K0008-18 [I,A]; A61K0008-19 [I,C*]; A61K0008-19 [I,A]; A61K0008-20 [I,A]; A61K0008-23 [I,A]; A61K0008-24 [I,A]; A61K0008-26 [I,A]; A61K0008-27 [I,A]; A61K0008-30 [I,C*]; A61K0008-31 [I,A]; A61K0008-34 [I,A]; A61K0008-35 [I,A]; A61K0008-37 [I,A]; A61K0008-46 [I,A]; A61K0008-64 [I,A]; A61K0008-72 [I,C*]; A61K0008-73 [I,A]; A61K0008-89 [I,A]; A61K0008-891 [I,A]; A61Q0001-02 [I,C*]; A61Q0001-02 [I,A]; A61Q0005-00 [I,C*]; A61Q0005-00 [I,A]; A61Q0005-10 [I,C*]; A61Q0005-10 [I,A]; A61Q0005-12 [I,C*]; A61Q0005-12 [I,A] |
| | ECLA | A61Q005/12; A61K008/19; A61K008/27; A61K008/46; A61Q005/00; A61Q005/10 |
| CN 1449737 | IPCI | A61K0007-06 [ICM, 7]; A61K0007-06 [ICS, 7] |
| | IPCR | A61K0008-00 [I,C*]; A61K0008-00 [I,A]; A61K0008-18 [I,C*]; A61K0008-18 [I,A]; A61K0008-19 [I,C*]; A61K0008-19 [I,A]; A61K0008-20 [I,A]; A61K0008-23 [I,A]; A61K0008-24 [I,A]; A61K0008-26 [I,A]; A61K0008-27 [I,A]; A61K0008-30 [I,C*]; A61K0008-31 [I,A]; A61K0008-34 [I,A]; A61K0008-35 [I,A]; A61K0008-37 [I,A]; A61K0008-46 [I,A]; A61K0008-64 [I,A]; A61K0008-72 [I,C*]; A61K0008-73 [I,A]; A61K0008-89 [I,A]; A61K0008-891 [I,A]; A61Q0001-02 [I,C*]; A61Q0001-02 [I,A]; A61Q0005-00 [I,C*]; A61Q0005-00 [I,A]; A61Q0005-10 [I,C*]; A61Q0005-10 [I,A]; A61Q0005-12 [I,C*]; A61Q0005-12 [I,A] |
| | ECLA | A61Q005/12; A61K008/19; A61K008/27; A61K008/46; A61Q005/00; A61Q005/10 |
| BR 2003000873 | IPCI | A61K0007-06 [ICM, 7] |
| | IPCR | A61K0008-00 [I,C*]; A61K0008-00 [I,A]; A61K0008-18 [I,C*]; A61K0008-18 [I,A]; A61K0008-19 [I,C*]; A61K0008-19 [I,A]; A61K0008-20 [I,A]; A61K0008-23 [I,A]; A61K0008-24 [I,A]; A61K0008-26 [I,A]; A61K0008-27 [I,A]; A61K0008-30 [I,C*]; A61K0008-31 [I,A]; A61K0008-34 [I,A]; A61K0008-35 [I,A]; A61K0008-37 [I,A]; A61K0008-46 [I,A]; A61K0008-64 [I,A]; A61K0008-72 [I,C*]; A61K0008-73 [I,A]; A61K0008-89 [I,A]; A61K0008-891 [I,A]; A61Q0001-02 [I,C*]; A61Q0001-02 [I,A]; A61Q0005-00 [I,C*]; A61Q0005-00 [I,A]; A61Q0005-10 [I,C*]; A61Q0005-10 [I,A]; A61Q0005-12 [I,C*]; A61Q0005-12 [I,A] |
| | ECLA | A61Q005/12; A61K008/19; A61K008/27; A61K008/46; A61Q005/00; A61Q005/10 |
| EP 1352630 | IPCI | A61K0008-19 [I,C]; A61K0008-30 [I,C]; A61Q0005-00 [I,C]; A61Q0005-10 [I,C]; A61Q0005-10 [I,A]; A61K0008-19 [I,A]; A61K0008-46 [I,A]; A61Q0005-00 [I,A] |
| | IPCR | A61K0008-00 [I,C*]; A61K0008-00 [I,A]; A61Q0005-10 [I,A]; A61K0008-18 [I,C*]; A61K0008-18 [I,A]; A61K0008-19 [I,C]; A61K0008-19 [I,A]; A61K0008-20 [I,A]; A61K0008-23 [I,A]; A61K0008-24 [I,A]; A61K0008-26 [I,A]; A61K0008-27 [I,A]; A61K0008-30 [I,C]; A61K0008-31 [I,A]; A61K0008-34 [I,A]; A61K0008-35 [I,A]; A61K0008-37 [I,A]; A61K0008-46 [I,A]; A61K0008-64 [I,A]; A61K0008-72 [I,C*]; A61K0008-73 [I,A]; A61K0008-89 [I,A]; A61K0008-891 [I,A]; A61Q0001-02 [I,C*]; A61Q0001-02 [I,A]; A61Q0005-00 [I,C*]; A61Q0005-00 [I,A]; A61Q0005-10 [I,C*]; A61Q0005-10 [I,A]; A61Q0005-12 [I,C*]; A61Q0005-12 [I,A] |

STN Columbus

[I,C]; A61K0008-31 [I,A]; A61K0008-34 [I,A];
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[I,A]; A61K0008-64 [I,A]; A61K0008-72 [I,C*];
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[I,A]; A61Q0001-02 [I,C*]; A61Q0001-02 [I,A];
A61Q0005-00 [I,C]; A61Q0005-00 [I,A]; A61Q0005-10
[I,C]; A61Q0005-12 [I,C*]; A61Q0005-12 [I,A]
ECLA A61Q005/12; A61K008/19; A61K008/27; A61K008/46;
A61Q005/00; A61Q005/10
US 20030223944 IPCI A61K0007-075 [ICM,7]; A61K0007-06 [ICS,7]
IPCR A61K0008-19 [I,C*]; A61K0008-19 [I,A]; A61K0008-30
[I,C*]; A61K0008-46 [I,A]; A61Q0005-12 [I,C*];
A61Q0005-12 [I,A]
NCL 424/070.100; 510/119.000
ECLA A61K008/19; A61K008/46; A61Q005/12
JP 2003300840 IPCI A61K0008-00 [I,A]; A61Q0005-00 [I,A]; A61K0008-18
[I,A]; A61Q0001-02 [I,A]
IPCR A61K0008-00 [I,C*]; A61K0008-00 [I,A]; A61K0008-18
[I,C*]; A61K0008-18 [I,A]; A61K0008-19 [I,C*];
A61K0008-19 [I,A]; A61K0008-20 [I,A]; A61K0008-23
[I,A]; A61K0008-24 [I,A]; A61K0008-26 [I,A];
A61K0008-27 [I,A]; A61K0008-30 [I,C*]; A61K0008-31
[I,A]; A61K0008-34 [I,A]; A61K0008-35 [I,A];
A61K0008-37 [I,A]; A61K0008-46 [I,A]; A61K0008-64
[I,A]; A61K0008-72 [I,C*]; A61K0008-73 [I,A];
A61K0008-89 [I,A]; A61K0008-891 [I,A]; A61Q0001-02
[I,C*]; A61Q0001-02 [I,A]; A61Q0005-00 [I,C*];
A61Q0005-00 [I,A]; A61Q0005-10 [I,C*]; A61Q0005-10
[I,A]; A61Q0005-12 [I,C*]; A61Q0005-12 [I,A]
ECLA A61Q005/12; A61K008/19; A61K008/27; A61K008/46;
A61Q005/00; A61Q005/10
AB The invention relates to a treatment process which confers cosmetic
properties on hair fibers. The process consists of treating the fibers
with a metal salt in the presence of a reducing agent, directly on the
fiber to form the corresponding free metal. Thus, a lock of hair after
being shampooed, was dried and an aq. soln. of AgNO₃ was applied onto the
hair. After the addn. of NaBH₄, the natural pigmented hair was dark, with
metallic brilliance reflected on it.
ST metal salt hair cosmetic
IT Alcohols, biological studies
RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);
PYP (Physical process); BIOL (Biological study); PROC (Process); USES
(Uses)
(C1-4; metal treatment of hair fibers for cosmetics)
IT Alkanes, biological studies
RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);
PYP (Physical process); BIOL (Biological study); PROC (Process); USES
(Uses)
(C5-10; metal treatment of hair fibers for cosmetics)
IT Polyelectrolytes
Surfactants
(amphoteric; metal treatment of hair fibers for cosmetics)
IT Fats and Glyceridic oils, biological studies
RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);
PYP (Physical process); BIOL (Biological study); PROC (Process); USES
(Uses)
(animal; metal treatment of hair fibers for cosmetics)
IT **Surfactants**
(anionic; metal treatment of hair fibers for cosmetics)
IT Polyelectrolytes

Surfactants

(cationic; metal treatment of hair fibers for cosmetics)

IT Cosmetics

(emollients; metal treatment of hair fibers for cosmetics)

IT Sulfates, reactions

RL: RCT (Reactant); RACT (Reactant or reagent)

(hydrogen; metal treatment of hair fibers for cosmetics)

IT Antifoaming agents

Antiperspirants

Cosmetics

Hair

Hair preparations

Perfumes

Pigments, nonbiological

Preservatives

Reducing agents

Shampoos

Sunscreens

Thickening agents

(metal treatment of hair fibers for cosmetics)

IT Alkaline earth salts

Bromates

Carbonates, biological studies

Disulfides

Halides

Nitrates, biological studies

Paraffin oils

Phosphates, biological studies

Polymers, biological studies

Polysiloxanes, biological studies

Proteins

Rare earth salts

Sulfates, biological studies

Thioethers

Thiosulfates

Transition metal salts

Vitamins

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);

PYP (Physical process); BIOL (Biological study); PROC (Process); USES

(Uses)

(metal treatment of hair fibers for cosmetics)

IT Bisulfites

Enzymes, reactions

Sulfites

Thiols, reactions

Thioredoxins

RL: RCT (Reactant); RACT (Reactant or reagent)

(metal treatment of hair fibers for cosmetics)

IT Cosmetics

(moisturizers; metal treatment of hair fibers for cosmetics)

IT **Surfactants****(nonionic;** metal treatment of hair fibers for cosmetics)

IT Peroxysulfates

RL: RCT (Reactant); RACT (Reactant or reagent)

(peroxymonosulfates; metal treatment of hair fibers for cosmetics)

IT Alcohols, biological studies

RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);

PYP (Physical process); BIOL (Biological study); PROC (Process); USES

(Uses)

(polyhydric; metal treatment of hair fibers for cosmetics)

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- IT Sulfonic acids, biological studies
 RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);
 PYP (Physical process); BIOL (Biological study); PROC (Process); USES
 (Uses)
 (salts; metal treatment of hair fibers for cosmetics)
- IT Sulfinic acids
 Thiols, reactions
 RL: RCT (Reactant); RACT (Reactant or reagent)
 (salts; metal treatment of hair fibers for cosmetics)
- IT Salts, reactions
 RL: RCT (Reactant); RACT (Reactant or reagent)
 (thiol; metal treatment of hair fibers for cosmetics)
- IT Lactones
 RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);
 PYP (Physical process); BIOL (Biological study); PROC (Process); USES
 (Uses)
 (thiolactones; metal treatment of hair fibers for cosmetics)
- IT Fats and Glyceridic oils, biological studies
 RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);
 PYP (Physical process); BIOL (Biological study); PROC (Process); USES
 (Uses)
 (vegetable; metal treatment of hair fibers for cosmetics)
- IT 64-17-5, Ethanol, biological studies 67-63-0, Isopropanol, biological
 studies 67-64-1, Acetone, biological studies 78-93-3, Methyl ethyl
 ketone, biological studies 79-20-9, Methyl acetate 110-71-4
 123-86-4, Butyl acetate 141-78-6, EtOAc, biological studies
 7429-90-5D, Aluminum, salts 7439-89-6D, Iron, salts 7439-98-7D,
 Molybdenum, salts 7440-02-0D, Nickel, salts 7440-05-3D, Palladium,
 salts 7440-06-4D, Platinum, salts 7440-22-4D, **Silver**, salts
 7440-31-5D, Tin, salts 7440-32-6D, Titanium, salts 7440-33-7D,
 Tungsten, salts 7440-36-0D, Antimony, salts 7440-50-8D, Copper, salts
 7440-57-5D, Gold, salts 7440-66-6D, Zinc, salts 7440-74-6D, Indium,
 salts 7758-89-6, Cuprous chloride 7761-88-8, **Silver** nitrate,
 biological studies 7775-41-9, **Silver** fluoride 7783-89-3,
Silver bromate 7783-90-6, **Silver** chloride, biological
 studies 7783-96-2, **Silver** iodide 7785-23-1, **Silver**
 bromide 7787-70-4, Cuprous bromide 10025-98-6, Dipotassium palladium
 tetrachloride 10294-26-5, **Silver** sulfate 10294-28-7, Gold
 tribromide 16903-35-8 16923-58-3, Disodium hexachloroplatinate
 19045-66-0D, Thiocarbamic acid, salts 73506-93-1, Diethoxyethane
 RL: COS (Cosmetic use); PEP (Physical, engineering or chemical process);
 PYP (Physical process); BIOL (Biological study); PROC (Process); USES
 (Uses)
 (metal treatment of hair fibers for cosmetics)
- IT 50-81-7, Ascorbic acid, reactions 53-57-6, NaDPH 58-68-4, NaDH
 68-11-1, Thioglycolic acid, reactions 77-92-9D, Citric acid, salts
 106-51-4, 2,5-Cyclohexadiene-1,4-dione, reactions 123-31-9,
 Hydroquinone, reactions 280-64-8, 9-BBN 1758-73-2, Formamidinesulfinic
 acid **2885-00-9**, 1-**Octadecanethiol** 3483-12-3,
 Dithiothreitol 6838-83-1, Diisoamylborane 7772-98-7 7775-14-6
 7803-51-2, Phosphine 13762-51-1 14451-43-5 16853-85-3 16940-66-2
 17836-88-3 25895-60-7, Sodium cyanoborohydride 37318-49-3, Protein
 disulfide isomerase 56553-60-7 131760-67-3 145626-87-5
 RL: RCT (Reactant); RACT (Reactant or reagent)
 (metal treatment of hair fibers for cosmetics)

RE.CNT 10 THERE ARE 10 CITED REFERENCES AVAILABLE FOR THIS RECORD
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L18 ANSWER 9 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 2003:737150 CAPLUS
 DN 139:250305
 ED Entered STN: 19 Sep 2003
 TI Invisible patch for the controlled delivery of cosmetic, dermatological,
 and pharmaceutical active ingredients onto the skin
 IN Shefer, Adi; Shefer, Samuel
 PA USA
 SO U.S. Pat. Appl. Publ., 17 pp., Cont.-in-part of U. S. Ser. No. 91,935.
 CODEN: USXXCO
 DT Patent
 LA English
 IC ICM A61K031-715
 ICS A61K009-70
 INCL 424449000; 514061000
 CC 63-6 (Pharmaceuticals)
 Section cross-reference(s): 62

FAN.CNT 2

| | PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
|------|---|------|----------|-----------------|----------|
| PI | US 20030175333 | A1 | 20030918 | US 2003-376736 | 20030228 |
| | US 20030175328 | A1 | 20030918 | US 2002-91935 | 20020306 |
| | CA 2515098 | A1 | 20040916 | CA 2004-2515098 | 20040227 |
| | WO 2004078122 | A2 | 20040916 | WO 2004-US6106 | 20040227 |
| | WO 2004078122 | A3 | 20050203 | | |
| | W: AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI RW: BW, GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR, BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG | | | | |
| | EP 1603499 | A2 | 20051214 | EP 2004-715783 | 20040227 |
| | R: AT, BE, CH, DE, DK, ES, FR, GB, GR, IT, LI, LU, NL, SE, MC, PT, IE, SI, LT, LV, FI, RO, MK, CY, AL, TR, BG, CZ, EE, HU, SK | | | | |
| | JP 2006519263 | T | 20060824 | JP 2006-508924 | 20040227 |
| PRAI | US 2002-91935 | A2 | 20020306 | | |
| | US 2003-376736 | A | 20030228 | | |
| | WO 2004-US6106 | W | 20040227 | | |

CLASS

| PATENT NO. | CLASS | PATENT FAMILY CLASSIFICATION CODES |
|----------------|-------|---|
| US 20030175333 | ICM | A61K031-715 |
| | ICS | A61K009-70 |
| | INCL | 424449000; 514061000 |
| | IPCI | A61K0031-715 [ICM,7]; A61K0009-70 [ICS,7] |
| | IPCR | A61F0013-00 [I,C*]; A61F0013-00 [I,A]; A61F0013-02 [I,C*]; A61F0013-02 [I,A]; A61K0008-00 [I,C*]; A61K0008-00 [I,A]; A61K0008-02 [I,C*]; A61K0008-02 [I,A]; A61K0008-11 [I,C*]; A61K0008-11 [I,A]; |

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A61K0008-30 [I,C*]; A61K0008-35 [I,A]; A61K0008-368 [I,A]; A61K0008-44 [I,A]; A61K0008-67 [I,A]; A61K0008-72 [I,C*]; A61K0008-72 [I,A]; A61K0008-73 [I,A]; A61K0008-96 [I,C*]; A61K0008-97 [I,A]; A61K0009-50 [I,C*]; A61K0009-50 [I,A]; A61K0009-51 [I,C*]; A61K0009-51 [I,A]; A61K0009-70 [I,C*]; A61K0009-70 [I,A]; A61K0031-01 [I,C*]; A61K0031-01 [I,A]; A61K0031-045 [I,C*]; A61K0031-045 [I,A]; A61K0031-047 [I,A]; A61K0031-05 [I,A]; A61K0031-075 [I,C*]; A61K0031-085 [I,A]; A61K0031-121 [I,C*]; A61K0031-121 [I,A]; A61K0031-155 [I,C*]; A61K0031-155 [I,A]; A61K0031-165 [I,C*]; A61K0031-165 [I,A]; A61K0031-345 [I,C*]; A61K0031-345 [I,A]; A61K0031-4453 [I,C*]; A61K0031-4453 [I,A]; A61K0031-545 [I,C*]; A61K0031-545 [I,A]; A61K0031-60 [I,C*]; A61K0031-60 [I,A]; A61K0031-616 [I,A]; A61K0031-65 [I,C*]; A61K0031-65 [I,A]; A61K0031-7042 [I,C*]; A61K0031-7048 [I,A]; A61K0033-00 [I,C*]; A61K0033-00 [I,A]; A61K0033-18 [I,C*]; A61K0033-18 [I,A]; A61K0033-28 [I,C*]; A61K0033-28 [I,A]; A61K0033-38 [I,C*]; A61K0033-38 [I,A]; A61K0036-18 [I,C*]; A61K0036-18 [I,A]; A61K0036-88 [I,C*]; A61K0036-896 [I,A]; A61K0045-00 [I,C*]; A61K0045-00 [I,A]; A61K0047-32 [I,C*]; A61K0047-32 [I,A]; A61K0047-34 [I,C*]; A61K0047-34 [I,A]; A61K0047-36 [I,C*]; A61K0047-36 [I,A]; A61K0047-38 [I,C*]; A61K0047-38 [I,A]; A61K0047-42 [I,C*]; A61K0047-42 [I,A]; A61L0015-16 [I,C*]; A61L0015-44 [I,A]; A61P0017-00 [I,C*]; A61P0017-00 [I,A]; A61P0017-02 [I,A]; A61P0017-10 [I,A]; A61P0017-12 [I,A]; A61P0017-16 [I,A]; A61Q0009-04 [I,C*]; A61Q0009-04 [I,A]; A61Q0017-04 [I,C*]; A61Q0017-04 [I,A]; A61Q0019-00 [I,C*]; A61Q0019-00 [I,A]; A61Q0019-02 [I,C*]; A61Q0019-02 [I,A]; A61Q0019-04 [I,C*]; A61Q0019-04 [I,A]; A61Q0019-08 [I,C*]; A61Q0019-08 [I,A]

NCL 424/449.000; 514/061.000

ECLA A61K008/02C; A61K008/35; A61K008/368; A61K008/44; A61K008/67C; A61K008/67H; A61K008/67L; A61K008/97; A61K009/70E; A61L015/44; A61Q009/04; A61Q019/00; A61Q019/04; A61Q019/08; K61K

US 20030175328

IPCI A61K0009-70 [ICM,7]
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[I,A]; A61K0031-616 [I,A]; A61K0031-65 [I,C*];
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 [I,C*]; A61K0047-32 [I,A]; A61K0047-34 [I,C*];
 A61K0047-34 [I,A]; A61K0047-36 [I,C*]; A61K0047-36
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 [I,C*]; A61L0015-44 [I,A]; A61P0017-00 [I,C*];
 A61P0017-00 [I,A]; A61P0017-02 [I,A]; A61P0017-10
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 A61Q0009-04 [I,C*]; A61Q0009-04 [I,A]; A61Q0017-04
 [I,C*]; A61Q0017-04 [I,A]; A61Q0019-00 [I,C*];
 A61Q0019-00 [I,A]; A61Q0019-02 [I,C*]; A61Q0019-02
 [I,A]; A61Q0019-04 [I,C*]; A61Q0019-04 [I,A];
 A61Q0019-08 [I,C*]; A61Q0019-08 [I,A]
 NCL 424/449.000
 ECLA A61K008/02C; A61K008/35; A61K008/368; A61K008/44;
 A61K008/67C; A61K008/67H; A61K008/67L; A61K008/97;
 A61K009/70E; A61L015/44; A61Q009/04; A61Q019/00;
 A61Q019/04; A61Q019/08; K61K
 CA 2515098 IPCI A61K0009-70 [ICM,7]; A61K0007-00 [ICS,7]; A61K0045-00
 [ICS,7]; A61M0037-00 [ICS,7]
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 A61K0009-70 [I,C*]; A61K0009-70 [I,A]; A61K0045-00
 [I,C*]; A61K0045-00 [I,A]; A61M0037-00 [I,C*];
 A61M0037-00 [I,A]
 WO 2004078122 IPCI A61K [ICM,7]
 IPCR A61F0013-00 [I,C*]; A61F0013-00 [I,A]; A61K [I,S];
 A61K0009-70 [I,C*]; A61K0009-70 [I,A]; A61K0045-00
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 A61M0037-00 [I,A]
 EP 1603499 IPCI A61F0013-00 [ICM,7]
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 A61K0009-70 [I,C*]; A61K0009-70 [I,A]; A61K0045-00
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 A61M0037-00 [I,A]
 JP 2006519263 IPCI A61K0008-02 [I,A]; A61K0008-73 [I,A]; A61K0008-81
 [I,A]; A61K0008-84 [I,A]; A61K0008-88 [I,A];
 A61K0008-72 [I,C*]; A61K0008-34 [I,A]; A61K0008-60
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 [I,A]; A61Q0019-00 [I,A]; A61K0008-33 [I,A];
 A61K0008-43 [I,A]; A61K0008-49 [I,A]; A61K0008-36
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 A61K0047-28 [I,A]; A61K0047-36 [I,A]; A61K0047-38
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 A61K0047-34 [I,A]; A61K0047-10 [I,A]; A61K0047-20
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 [I,A]; A61K0045-00 [I,A]; A61K0047-22 [I,A]
 IPCR A61K0008-02 [I,C]; A61K0008-02 [I,A]; A61F0013-00
 [I,C*]; A61F0013-00 [I,A]; A61K [I,S]; A61K0008-30
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 A61K0008-36 [I,A]; A61K0008-37 [I,A]; A61K0008-41
 [I,A]; A61K0008-43 [I,A]; A61K0008-46 [I,A];

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A61K0008-49 [I,A]; A61K0008-55 [I,A]; A61K0008-58 [I,A]; A61K0008-60 [I,A]; A61K0008-72 [I,C]; A61K0008-73 [I,A]; A61K0008-81 [I,A]; A61K0008-84 [I,A]; A61K0008-88 [I,A]; A61K0009-70 [I,C]; A61K0009-70 [I,A]; A61K0045-00 [I,C]; A61K0045-00 [I,A]; A61K0047-10 [I,C]; A61K0047-10 [I,A]; A61K0047-12 [I,C]; A61K0047-12 [I,A]; A61K0047-14 [I,C]; A61K0047-14 [I,A]; A61K0047-16 [I,C]; A61K0047-18 [I,A]; A61K0047-20 [I,C]; A61K0047-20 [I,A]; A61K0047-22 [I,C]; A61K0047-22 [I,A]; A61K0047-24 [I,C]; A61K0047-24 [I,A]; A61K0047-28 [I,C]; A61K0047-28 [I,A]; A61K0047-32 [I,C]; A61K0047-32 [I,A]; A61K0047-34 [I,C]; A61K0047-34 [I,A]; A61K0047-36 [I,C]; A61K0047-36 [I,A]; A61K0047-38 [I,C]; A61K0047-38 [I,A]; A61K0047-42 [I,C]; A61K0047-42 [I,A]; A61M0037-00 [I,C*]; A61M0037-00 [I,A]; A61Q0019-00 [I,C]; A61Q0019-00 [I,A]

FTERM 4C076/AA72; 4C076/AA95; 4C076/BB31; 4C076/CC01; 4C076/CC03; 4C076/CC04; 4C076/CC18; 4C076/DD03; 4C076/DD04; 4C076/DD07; 4C076/DD08; 4C076/DD09; 4C076/DD13; 4C076/DD17; 4C076/DD38A; 4C076/DD66A; 4C076/EE06A; 4C076/EE10A; 4C076/EE12A; 4C076/EE13A; 4C076/EE17A; 4C076/EE23A; 4C076/EE26A; 4C076/EE27; 4C076/EE30A; 4C076/EE31A; 4C076/EE32A; 4C076/EE38A; 4C076/FF31; 4C076/FF35; 4C083/AA112; 4C083/AB032; 4C083/AC122; 4C083/AC131; 4C083/AC181; 4C083/AC371; 4C083/AC391; 4C083/AC421; 4C083/AC441; 4C083/AC532; 4C083/AC682; 4C083/AC772; 4C083/AC781; 4C083/AC791; 4C083/AD041; 4C083/AD042; 4C083/AD051; 4C083/AD071; 4C083/AD072; 4C083/AD091; 4C083/AD111; 4C083/AD131; 4C083/AD151; 4C083/AD201; 4C083/AD202; 4C083/AD211; 4C083/AD241; 4C083/AD261; 4C083/AD271; 4C083/AD281; 4C083/AD282; 4C083/AD351; 4C083/AD391; 4C083/AD642; 4C083/AD662; 4C083/CC02; 4C083/DD12; 4C083/EE12; 4C083/EE13; 4C083/EE14; 4C083/EE16; 4C083/EE22; 4C084/AA17; 4C084/MA32; 4C084/MA63; 4C084/NA10; 4C084/ZA891

AB The present invention relates to a patch for controlled topical or transdermal delivery of effective levels of cosmetic, dermatol., and pharmaceutical active ingredients onto the skin, hair follicles, and sebaceous glands, with minimal discomfort and ease of use. The patch can be transparent or clear and comprises a rate-controlling matrix layer. The matrix layer comprises water-sensitive, bioadhesive, film forming polymers, a water sol. oligomer, and a **surfactant**. The cosmetic, dermatol., and pharmaceutical active ingredients are sol. or dispersed in the matrix. The patch becomes tacky when wetted and adheres onto the skin. The adhesive properties of the patch are sufficient to maintain the patch in place on the skin for the recommended treatment period while allowing the patch to be readily removed without causing skin irritation or leaving adhesive residue on the skin. For example, an antibiotic patch contained polyvinyl alc. 50, PVP 1, polysorbate 20 5, Maltrin 180 10, lactitol 5, glycerin 10, and chloramphenicol 0.55%.

ST patch bioadhesive polymer oligosaccharide **surfactant**; antibiotic patch PVA PVP polysorbate chloramphenicol

IT Glycosides

RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study); USES (Uses)

(alkyl polyglycosides; invisible patches contg. bioadhesive polymers and **surfactants**)

IT **Surfactants**

STN Columbus

- (amphoteric; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT **Surfactants**
(**anionic**; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT **Surfactants**
(cationic; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Essential oils
RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);
USES (Uses)
(clove; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Hair preparations
(conditioners; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Cosmetics
(depilatories; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Acne
Burn
Dandruff
Pruritus
Rhus diversiloba
Rhus toxicodendron
(drugs for; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Alcohols, biological studies
Amides, biological studies
Esters, biological studies
RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);
USES (Uses)
(ethoxylated; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Hair preparations
(growth stimulants; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Vein, disease
(hemorrhoid, drugs for; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Syrups (sweetening agents)
(hydrolyzed starch; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Allergy inhibitors
Aloe barbadensis
Analgesics
Anti-infective agents
Anti-inflammatory agents
Antibacterial agents
Antibiotics
Antiemetics
Antihistamines
Antimicrobial agents
Antioxidants
Antiperspirants
Antitussives
Antiviral agents
Chelating agents
Chemotherapy
Cholinergic antagonists

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Deodorants
Disinfectants
Fungicides
Hemostatics
Immunomodulators
Insecticides
Radical scavengers
Sunscreens
Suntanning agents
Vasoconstrictors
Vasodilators
Wound healing promoters
 (invisible patches contg. bioadhesive polymers and **surfactants**
)

- IT Amine oxides
Amino acids, biological studies
Carbohydrates, biological studies
Caseins, biological studies
Flavonoids
Gelatins, biological studies
Glycerides, biological studies
Lanolin
Lecithins
Oligosaccharides, biological studies
Paraffin oils
Peptides, biological studies
Polyamides, biological studies
Polyesters, biological studies
Polyoxyalkylenes, biological studies
Polyoxyalkylenes, biological studies
Polysaccharides, biological studies
Proteins
Retinoids
Vitamins
RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);
USES (Uses)
 (invisible patches contg. bioadhesive polymers and **surfactants**
)
- IT Anesthetics
 (local; invisible patches contg. bioadhesive polymers and
 surfactants)
- IT Cosmetics
 (moisturizers; invisible patches contg. bioadhesive polymers and
 surfactants)
- IT **Surfactants**
 (**nonionic**; invisible patches contg. bioadhesive polymers and
 surfactants)
- IT Amines, biological studies
RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);
USES (Uses)
 (polyamines, nonpolymeric; invisible patches contg. bioadhesive
 polymers and **surfactants**)
- IT Alcohols, biological studies
RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);
USES (Uses)
 (polyhydric, propoxylated; invisible patches contg. bioadhesive
 polymers and **surfactants**)
- IT Quaternary ammonium compounds, biological studies
RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);
USES (Uses)

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- (polymers; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Skin, disease
(rash, drugs for; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Cosmetics
(skin-lightening; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Drug delivery systems
(tapes; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT Cosmetics
(wrinkle-preventing; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT **Surfactants**
(**zwitterionic**; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT 36574-66-0D, N-coco acyl derivs.
RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study); USES (Uses)
(cocoamidopropylbetaine; invisible patches contg. bioadhesive polymers and **surfactants**)
- IT 68-26-8, Retinol 96-26-4, Dihydroxyacetone 814-71-1, Calcium **thioglycolate** 34452-51-2, Potassium **thioglycolate**
RL: COS (Cosmetic use); BIOL (Biological study); USES (Uses)
(invisible patches contg. bioadhesive polymers and **surfactants**)
- IT 50-70-4, Sorbitol, biological studies 50-70-4D, Sorbitol, oligomers contg. 50-78-2, Aspirin 50-81-7, Vitamin C, biological studies 50-99-7D, Glucose, esters 50-99-7D, D-Glucose, oligomers contg. 55-56-1, Chlorhexidine 56-81-5, Glycerin, biological studies 56-86-0D, Glutamic acid, N-acyl derivs. 57-48-7D, Fructose, oligomers contg. 57-50-1D, Sucrose, esters 57-50-1D, Sucrose, oligomers contg. 57-55-6, Propylene glycol, biological studies 58-86-6D, Xylose, oligomers contg. 59-23-4D, Galactose, oligomers contg. 59-87-0, Nitrofurazone 60-54-8, Tetracycline 69-65-8D, Mannitol, oligomers contg. 69-72-7, Salicylic acid, biological studies 69-79-4D, Maltose, oligomers contg. 87-99-0D, Xylitol, oligomers contg. 106-11-6, Diethylene glycol monostearate 107-36-8D, Isethionic acid, cocoyl derivs. 108-46-3, Resorcinol, biological studies 108-95-2, Phenol, biological studies 114-07-8, Erythromycin 115-83-3, Pentaerythritol tetrastearate 144-55-8, Sodium bicarbonate, biological studies 151-21-3, Sodium lauryl sulfate, biological studies 404-86-4, Capsaicin 497-19-8, Sodium carbonate, biological studies 585-86-4D, Lactitol, oligomers contg. 585-88-6D, Maltitol, oligomers contg. 770-35-4, Phenoxyisopropanol 1338-41-6, Sorbitan monostearate 1406-18-4, Vitamin E 2216-51-5 3380-34-5, Triclosan 3458-28-4D, D-Mannose, oligomers contg. 6284-40-8 7439-97-6, Mercury, biological studies 7440-22-4, **Silver**, biological studies 7553-56-2, Iodine, biological studies 8011-96-9, Calamine 8050-81-5, Simethicone 9000-01-5, Gum arabic 9002-89-5, Polyvinyl alcohol 9002-98-6 9003-05-8, Polyacrylamide 9003-39-8, Polyvinylpyrrolidone 9004-64-2, Hydroxypropyl cellulose 9005-25-8, Starch, biological studies 9005-25-8D, Starch, hydrolyzates 9005-64-5, Polysorbate 20 9011-13-6, Styrene-maleic anhydride copolymer 9011-16-9, Methyl vinyl ether-maleic anhydride copolymer 11099-07-3, Glycerin stearate 11111-12-9, Cephalosporin 11140-06-0, Glycerin palmitate 12694-22-3, Diglyceryl monostearate 13718-94-0D, Palatinose, oligomers contg. 15687-27-1, Ibuprofen 18323-44-9, Clindamycin 25322-68-3, Polyethylene glycol 25322-69-4 25655-41-8, Povidone iodine 26658-19-5, Sorbitan tristearate 27195-16-0, Sucrose distearate

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30233-64-8, Glyceryl monobehenate 39529-26-5, Decaglyceryl decastearate
 42852-72-2 53998-08-6, Sarcosinate 63119-59-5, Diglycerin distearate
 68424-04-4, Polydextrose 71185-87-0, Hexaglyceryl tristearate
 75537-01-8, Gantrez S-97 95461-64-6, Decaglyceryl pentastearate
 99734-29-9, Tetraglyceryl tristearate 99880-64-5, Glyceryl dibehenate
 106392-12-5, Polyoxyethylene polyoxypropylene block copolymer
 RL: COS (Cosmetic use); THU (Therapeutic use); BIOL (Biological study);
 USES (Uses)

(invisible patches contg. bioadhesive polymers and **surfactants**
)

IT 56-75-7, Chloramphenicol 94-09-7, Benzocaine

RL: THU (Therapeutic use); BIOL (Biological study); USES (Uses)

(invisible patches contg. bioadhesive polymers and **surfactants**
)

L18 ANSWER 10 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 1992:536001 CAPLUS

DN 117:136001

OREF 117:23503a,23506a

ED Entered STN: 04 Oct 1992

TI Aqueous emulsion for temporary protection of **silver** and copper surfaces
 against tarnishing

IN Grossmann, Hermann

PA Doduco GmbH und Co. Dr. Eugen Duerrwaechter, Germany

SO Eur. Pat. Appl., 6 pp.

CODEN: EPXXDW

DT Patent

LA German

IC ICM C23F011-16

CC 56-10 (Nonferrous Metals and Alloys)

FAN.CNT 1

| | PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
|------|---------------------------|------|----------|-----------------|----------|
| PI | EP 492487 | A1 | 19920701 | EP 1991-121903 | 19911220 |
| | EP 492487 | B1 | 19960320 | | |
| | R: DE, ES, FR, GB, IT, NL | | | | |
| | DE 4041596 | A1 | 19920702 | DE 1990-4041596 | 19901222 |
| | ES 2086471 | T3 | 19960701 | ES 1991-121903 | 19911220 |
| PRAI | DE 1990-4041596 | A | 19901222 | | |
| | DE 1991-4124955 | A | 19910727 | | |

CLASS

| PATENT NO. | CLASS | PATENT FAMILY CLASSIFICATION CODES |
|------------|-------|--|
| EP 492487 | ICM | C23F011-16 |
| | IPCI | C23F0011-16 [ICM,5]; C23F0011-10 [ICM,5,C*] |
| | IPCR | C23F0011-10 [I,C*]; C23F0011-16 [I,A] |
| | ECLA | C23F011/16B |
| DE 4041596 | IPCI | C23F0011-12 [ICM,5]; C23F0011-16 [ICS,5]; C23F0011-10 [ICS,5,C*]; C09K0015-06 [ICA,5]; C09K0015-12 [ICA,5]; C09K0015-00 [ICA,5,C*]; B01F0017-42 [ICA,5]; B01F0017-38 [ICA,5] |
| | IPCR | C23F0011-10 [I,C*]; C23F0011-16 [I,A] |
| | ECLA | C23F011/16B |
| ES 2086471 | IPCI | C23F0011-16 [ICM,6]; C23F0011-10 [ICM,6,C*] |
| | IPCR | C23F0011-10 [I,C*]; C23F0011-16 [I,A] |
| | ECLA | C23F011/16B |

AB The emulsion of pH 1-10 (preferably 2-4) comprises a hydrophobic inhibitor of a C \geq 12 thioalc. with \geq 1 SH group and its ester 0.05-50

(preferably 2-20), emulsifier 0.05-50 (2-20), and an **anionic** or **nonionic surfactant** ≤ 2 (0.05-1 g/L). The emulsifier comprises an alkoxyated and preferably ethoxyated branched C4-20 alc., an alkyl or alkylphenyl ether of polyethylene glycol. **Ag**, Cu, and their alloys are treated with the emulsion at $>T$ (m.p. of inhibitor), rinsed with H₂O at $<T$, and dried with hot air. An example emulsion of pH 3 and suitable for treatment of **Ag** and **Ag** alloys contains **octadecanethiol** 0.5-30, polyethylene glycol alkyl ether 0.5-30, and SDS ≤ 1 g/L H₂O.

- ST tarnishing inhibitor **silver** copper; thiol SDS tarnishing inhibitor **silver**; SDS thiol tarnishing inhibitor copper; polyethylene glycol ether tarnishing inhibitor
- IT Thiols, uses
RL: USES (Uses)
(corrosion inhibitors, for copper and **silver**, with emulsifiers of alkyl or alkylphenyl ether of polyethylene glycol)
- IT Tarnishing
(of **silver** and copper alloys, aq. emulsion for prevention of)
- IT Corrosion inhibitors
(thiols, with emulsifiers of alkyl or alkyl Ph ether of polyethylene glycol)
- IT Alcohols, compounds
RL: PROC (Process)
(C8-16, ethoxyated, corrosion inhibitor emulsion contg., thiol, for copper and **silver** and their alloys)
- IT copper alloy, base
silver alloy, base
RL: RCT (Reactant); RACT (Reactant or reagent)
(tarnishing of, thiol inhibitor for)
- IT 25322-68-3D, Polyethylene glycol, alkyl and alkylphenyl ethers 151-21-3, uses
RL: PROC (Process)
(corrosion inhibitor emulsion contg., thiol, for copper and **silver** and their alloys)
- IT 2885-00-9, Octadecanethiol
RL: PROC (Process)
(corrosion inhibitors, for copper and **silver**, with emulsifiers of alkyl or alkylphenyl ether of polyethylene glycol)
- IT 7440-22-4, **Silver**, reactions 7440-50-8, Copper, reactions
RL: RCT (Reactant); RACT (Reactant or reagent)
(tarnishing of, thiol inhibitor for)

L18 ANSWER 11 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 1991:89162 CAPLUS

DN 114:89162

OREF 114:15093a,15096a

ED Entered STN: 09 Mar 1991

TI **Silver** metal liquidlike films (MELLFs). The effect of **surfactants**

AU Yogev, D.; Efrima, S.

CS Dep. Chem., Ben-Gurion Univ. Negev, Beer-Sheva, 84105, Israel

SO Langmuir (1991), 7(2), 267-71

CODEN: LANGD5; ISSN: 0743-7463

DT Journal

LA English

CC 66-4 (Surface Chemistry and Colloids)

Section cross-reference(s): 73, 74

AB The effects of **surfactants** on the prodn. and stabilization of **Ag** metal liquidlike films (MELLFs) were studied. The main role of the **surfactant** is in stabilizing the **Ag** MELLFs and improving their properties

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(reflectivity, "fluidity"). A variety of different **surfactants** were found to be active, and of those investigated, **anionic** fluoroalkyl **surfactants** seem to be the most effective. In the case of **anionic surfactants**, the counteraction has a significant effect on the **Ag** MELLF, esp. if it is a surface-active agent in itself. The effects of the **surfactants** on the interfacial tension and their effect on the measured reflectivities of the MELLFs are discussed in the context of the interfacial colloidal model of **Ag** MELLFs.

- ST **silver** metal liquidlike film formation; **surfactant** effect metal liquidlike film; interfacial tension metal liquidlike film
- IT Films
(metal liq.-like, **surfactant** effects on formation of)
- IT Interfacial tension
(of **surfactant** solns., **silver** metal liq.-like film formation in relation to)
- IT Sulfonic acids, compounds
RL: PRP (Properties)
(perfluoroalkane, ammonium and potassium salts, **surfactant** effect of, on **silver** metal liq.-like film formation)
- IT **Surfactants**
(**silver** metal liq.-like film formation in presence of)
- IT Carboxylic acids, compounds
RL: PRP (Properties)
(perfluoro, ammonium salts, **surfactant** effect of, on **silver** metal liq.-like film formation)
- IT 7440-22-4, **Silver**, uses and miscellaneous
RL: USES (Uses)
(liq.-like metal film formation by, **surfactant** effects on)
- IT 577-11-7 **2885-00-9**, 1-Octadecanethiol 9002-93-1, Triton X 100 52584-45-9, Monflor 31 57534-41-5, Zonyl FSN 60529-61-5, Monflor 32 67479-85-0, Zonyl FSC 67479-86-1, Zonyl FSP
RL: PRP (Properties)
(**silver** metal liq.-like film formation in presence of)

L18 ANSWER 12 OF 12 CAPLUS COPYRIGHT 2009 ACS on STN

Full Text

AN 1987:33631 CAPLUS

DN 106:33631

OREF 106:5655a,5658a

ED Entered STN: 07 Feb 1987

TI Maleimide copolymer and thermoplastic resin prepared by using this copolymer

IN Kimura, Atsushi; Toyooka, Yutaka; Kishida, Kazuo

PA Mitsubishi Rayon Co., Ltd., Japan

SO PCT Int. Appl., 41 pp.

CODEN: PIXXD2

DT Patent

LA Japanese

IC ICM C08F002-18

ICS C08F212-04; C08L033-14; C08L035-06; C08L051-04

CC 35-4 (Chemistry of Synthetic High Polymers)

Section cross-reference(s): 38

FAN.CNT 1

| | PATENT NO. | KIND | DATE | APPLICATION NO. | DATE |
|----|------------------------|------|----------|-----------------|----------|
| | ----- | --- | ----- | ----- | ----- |
| PI | WO 8604337 | A1 | 19860731 | WO 1986-JP17 | 19860117 |
| | W: AU, US | | | | |
| | RW: DE, FR, GB, IT, NL | | | | |
| | JP 61163903 | A | 19860724 | JP 1985-4907 | 19850117 |
| | JP 61174248 | A | 19860805 | JP 1985-12705 | 19850128 |

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| | | | | |
|-----------------------|----|----------|----------------|----------|
| AU 8653567 | A | 19860813 | AU 1986-53567 | 19860117 |
| EP 208790 | A1 | 19870121 | EP 1986-900840 | 19860117 |
| R: DE, FR, GB, IT, NL | | | | |
| CA 1262299 | A1 | 19891010 | CA 1986-518902 | 19860923 |
| PRAI JP 1985-4907 | A | 19850117 | | |
| JP 1985-12705 | A | 19850128 | | |
| WO 1986-JP17 | A | 19860117 | | |

CLASS

| PATENT NO. | CLASS | PATENT FAMILY CLASSIFICATION CODES |
|-------------|-------|--|
| WO 8604337 | ICM | C08F002-18 |
| | ICS | C08F212-04; C08L033-14; C08L035-06; C08L051-04 |
| | IPCI | C08F0002-18 [ICM, 4]; C08F0002-12 [ICM, 4, C*]; C08F0212-04 [ICS, 4]; C08F0212-00 [ICS, 4, C*]; C08L0033-14 [ICS, 4]; C08L0033-00 [ICS, 4, C*]; C08L0035-06 [ICS, 4]; C08L0035-00 [ICS, 4, C*]; C08L0051-04 [ICS, 4]; C08L0051-00 [ICS, 4, C*] |
| | IPCR | C08F0002-12 [I, C*]; C08F0002-18 [I, A]; C08F0222-00 [I, C*]; C08F0222-40 [I, A]; C08L0035-00 [I, C*]; C08L0035-06 [I, A]; C08L0051-00 [I, C*]; C08L0051-04 [I, A] |
| | ECLA | C08F222/40; C08L035/06+B5; C08L051/04+B2 |
| JP 61163903 | IPCI | C08F0002-18 [ICM, 4]; C08F0002-12 [ICM, 4, C*]; C08F0212-04 [ICS, 4]; C08F0212-00 [ICS, 4, C*]; C08F0002-00 [ICA, 4] |
| JP 61174248 | IPCI | C08L0033-18 [ICM, 4]; C08L0033-00 [ICM, 4, C*]; C08L0035-06 [ICS, 4]; C08L0035-00 [ICS, 4, C*]; C08L0051-04 [ICS, 4]; C08L0051-00 [ICS, 4, C*] |
| | IPCR | C08L0033-00 [I, C*]; C08L0033-00 [I, A]; C08L0007-00 [I, C*]; C08L0007-00 [I, A]; C08L0021-00 [I, C*]; C08L0021-00 [I, A]; C08L0023-00 [I, C*]; C08L0023-00 [I, A]; C08L0033-02 [I, A]; C08L0033-18 [I, A]; C08L0033-24 [I, A]; C08L0035-00 [I, C*]; C08L0035-06 [I, A]; C08L0051-00 [I, C*]; C08L0051-00 [I, A]; C08L0051-02 [I, A]; C08L0051-04 [I, A]; C08L0101-00 [I, C*]; C08L0101-00 [I, A] |
| AU 8653567 | IPCI | C08F0002-18 [ICM, 4]; C08F0002-12 [ICM, 4, C*]; C08F0212-04 [ICS, 4]; C08F0212-00 [ICS, 4, C*]; C08L0033-14 [ICS, 4]; C08L0033-00 [ICS, 4, C*]; C08L0035-06 [ICS, 4]; C08L0035-00 [ICS, 4, C*]; C08L0051-04 [ICS, 4]; C08L0051-00 [ICS, 4, C*] |
| | IPCR | C08F0002-12 [I, C*]; C08F0002-18 [I, A]; C08F0222-00 [I, C*]; C08F0222-40 [I, A]; C08L0035-00 [I, C*]; C08L0035-06 [I, A]; C08L0051-00 [I, C*]; C08L0051-04 [I, A] |
| | ECLA | C08F222/40; C08L035/06+B5; C08L051/04+B2 |
| EP 208790 | IPCI | C08F0002-18 [ICM, 4]; C08F0002-12 [ICM, 4, C*]; C08F0212-04 [ICS, 4]; C08F0212-00 [ICS, 4, C*]; C08L0033-14 [ICS, 4]; C08L0033-00 [ICS, 4, C*]; C08L0035-06 [ICS, 4]; C08L0035-00 [ICS, 4, C*]; C08L0051-04 [ICS, 4]; C08L0051-00 [ICS, 4, C*] |
| | IPCR | C08F0002-12 [I, C*]; C08F0002-18 [I, A]; C08F0222-00 [I, C*]; C08F0222-40 [I, A]; C08L0035-00 [I, C*]; C08L0035-06 [I, A]; C08L0051-00 [I, C*]; C08L0051-04 [I, A] |
| | ECLA | C08F222/40; C08L035/06+B5; C08L051/04+B2 |
| CA 1262299 | IPCI | C08F0212-04 [ICM, 4]; C08F0212-00 [ICM, 4, C*]; C08L0025-02 [ICS, 4]; C08L0025-00 [ICS, 4, C*]; C08L0051-04 [ICS, 4]; C08L0051-00 [ICS, 4, C*] |
| | IPCR | C08F0212-00 [I, C*]; C08F0212-04 [I, A]; C08L0025-00 |

STN Columbus

[I,C*]; C08L0025-02 [I,A]; C08L0051-00 [I,C*];
C08L0051-04 [I,A]

- AB A maleimide polymer with excellent heat stability during high-temp. molding and giving a product with excellent resistance to discoloration, heat, and impact when blended with a graft rubber, is prepd. by polymn. of a monomer selected from an arom. vinyl monomer, an unsatd. nitrile, and Me methacrylate 50-95, a maleimide 5-50, and other monomers 0-30% in the presence of a Ca phosphate-based dispersing agent and a **nonionic surfactant** [RO(CH₂CH₂O)_n]mPO(OA)₃-m (R = C₈-30 alkyl, aralkyl; A = H, metal; m = 1-3, n = 5-50). The process minimizes the scale formation of formed polymers on a reactor wall during polymn. Thus, a mixt. of acrylonitrile 20, styrene 170, and N-phenylmaleimide 10 parts in 100 parts water contg. AIBN 0.1, tert-Bu benzoate 0.1, tert-dodecyl **mercaptan** 0.3, Gafac GB 520 0.003, and Ca₃PO₄ 0.5 part was suspension-polymd. at 80° for 3 h and at 120° for 2 h to give polymer beads (particle diam. 180 μ, glass-transition temp. 125°). During the polymn., no scale formation was obsd. A blend of 55 parts maleimide copolymer and 45 parts graft polymer from polybutadiene 50, acrylonitrile 15, and styrene 35 parts contg. Mg stearate 0.3, tris(nonylphenyl) phosphite 0.1, and Antage W 400 0.2 phr was injection-molded at 280-290° to give a sample exhibiting yellowing index (at 280°) 31, notched Izod impact strength 16.4 kg-cm/cm², Rockwell hardness (R) 102, and Vicat softening point 108°, with no **silver** streak formation, compared with 44, 16, 101, and 104, with **silver** streak formation, when a maleimide copolymer prepd. in the presence of poly(vinyl alc.) as a dispersing agent was used.
- ST phenylmaleimide copolymer suspension polymn; acrylonitrile copolymer suspension polymn; styrene copolymer suspension polymn; calcium phosphate dispersant suspension polymn; polyethylene glycol lauryl ether phosphate; **nonionic** phosphate **surfactant** suspension polymn; scale prevention suspension polymn dispersant; ABS blend maleimide copolymer molding; heat stability maleimide copolymer molding
- IT Plastics, molded
RL: USES (Uses)
(ABS polymer-maleimide-contg. polymers, heat- and impact-resistant, heat-stable)
- IT Heat-resistant materials
(maleimide-contg. polymers, heat stability improvement of)
- IT Dispersing agents
(polyalkylene glycol phosphate-tricalcium phosphate, in suspension polymn. of maleimide-contg. monomer mixts., for scale formation prevention)
- IT Scale (coating)
(prevention of, on reactor wall during suspension polymn. of maleimide-contg. monomer mixts., dispersing agents for)
- IT Polymerization
(suspension, of maleimide-contg. monomer mixts., dispersing agents for, for scale formation prevention)
- IT 9003-56-9
RL: USES (Uses)
(phenylmaleimide copolymer blends, heat-stable, resistant to discoloration, heat and impact)
- IT 31621-07-5P, Acrylonitrile-N-phenylmaleimide-styrene copolymer
94858-30-7P, Acrylonitrile-α-methylstyrene-N-phenylmaleimide-styrene copolymer
101482-57-9P, Acrylonitrile-methyl methacrylate-N-phenylmaleimide-styrene copolymer
RL: PREP (Preparation)

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(prepn. of, by suspension polymn., dispersing agents for, for improved heat stability and scale prevention during polymn.)

IT 51811-79-1, Gafac RE 610

RL: USES (Uses)

(suspending agents, Gafac RE 610, in suspension polymn. of maleimide-contg. monomer mixts., for scale formation prevention during polymn.)

IT 35604-29-6, Gafac GB 520

RL: USES (Uses)

(suspension agent, Gafac GB 520, in suspension polymn. of maleimide-contg. monomer mixts., for scale formation prevention during polymn.)

IT 7758-87-4, Tricalcium phosphate

RL: USES (Uses)

(suspension agent, in suspension polymn. of maleimide-contg. monomer mixts., for scale formation prevention during polymn.)

RE.CNT 7 THERE ARE 7 CITED REFERENCES AVAILABLE FOR THIS RECORD

RE

- (1) Anon; JP 4983785 A
- (2) Anon; JP 5495689 A
- (3) Anon; JP 57125242 A CAPLUS
- (4) Anon; JP 57167341 A CAPLUS
- (5) Anon; JP 58129043 A CAPLUS
- (6) Anon; JP 58206657 A CAPLUS
- (7) Anon; JP 59184243 A CAPLUS

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COST IN U.S. DOLLARS

| | |
|------------|---------|
| SINCE FILE | TOTAL |
| ENTRY | SESSION |
| 172.85 | 182.49 |

FULL ESTIMATED COST

DISCOUNT AMOUNTS (FOR QUALIFYING ACCOUNTS)

| | |
|------------|---------|
| SINCE FILE | TOTAL |
| ENTRY | SESSION |
| -22.96 | -22.96 |

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